

Eclipse II Family Data Sheet

- • • • • **Ultra-Low Power FPGA Combining Performance, Density, and Embedded RAM**

Device Highlights

Flexible Programmable Logic

- As low as 14 μ A standby current
- 0.18 μ m, six layer metal CMOS process
- 1.8 V VCC, 1.8/2.5/3.3 V drive capable I/O
- Up to 4,002 dedicated flip-flops
- Up to 55.3 K embedded SRAM bits
- Up to 310 I/O
- Up to 335 user available pins
- Up to 320 K system gates
- IEEE 1149.1 boundary scan testing compliant

Embedded Dual Port SRAM

- Up to twenty-four 2,304 bit dual port high performance SRAM blocks
- RAM/ROM/FIFO wizard for automatic configuration
- Configurable and cascadable aspect ratio

Programmable I/O

- High performance I/O cell
- Programmable slew rate control
- Programmable I/O standards:
 - LVTTTL, LVCMOS, LVCMOS18, PCI, GTL+, SSTL2, and SSTL3
 - Independent I/O banks capable of supporting multiple standards in one device
 - I/O register configurations: Input, Output, Output Enable (OE)

Advanced Clock Network

- Multiple dedicated low skew clock networks
- High drive input-only networks
- Quadrant-based segmentable clock networks
- User programmable Phase Locked Loops (PLL)

Embedded Computational Units (ECUs)

Hardwired DSP building blocks with integrated Multiply, Add, and Accumulate functions.

Security Features

The QuickLogic products come with secure ViaLink® technology that protects intellectual property from design theft and reverse engineering. No external configuration memory needed; instant-on at power-up.

Figure 1: Eclipse II Block Diagram

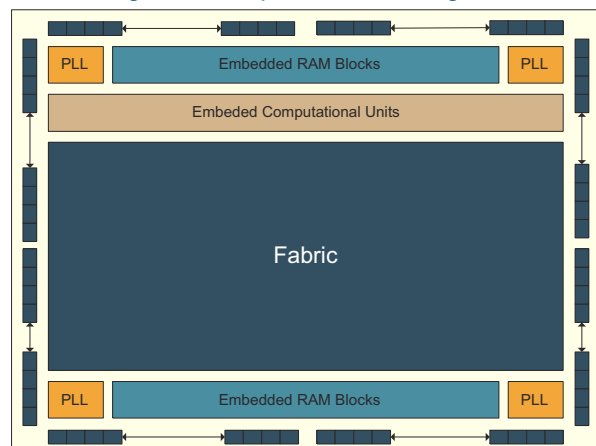


Table 1: Eclipse II Product Family Members

		QL8025	QL8050	QL8150	QL8250	QL8325
Max Gates		47,052	63,840	188,946	248,160	320,640
Logic Array		16 x 8	16 x 16	32 x 20	40 x 24	48 x 32
Logic Cells		128	256	640	960	1,536
Max Flip-Flops		532	884	1,709	2,670	4,002
Max I/O		92	124	165	250	310
RAM Modules		4	4	16	20	24
RAM Bits		9,216	9,216	36,864	46,100	55,300
PLLs		-	-	-	4	4
ECUs		-	-	-	10	12
Packages	VQFP	100	100	-	-	-
	TFBGA (0.5 mm)	-	101	-	-	-
	TQFP	144	144	144	-	-
	TFBGA (0.8 mm)	196	196	196	-	-
	TFBGA (0.5 mm)	-	101	196	-	-
	PQFP	-	-	208	208	208
	LFBGA (0.8 mm)	-	-	280	280	280
	PBGA (1.0 mm)	-	-	-	484	484

Table 2: Max I/O per Device/Package Combination

Device	100 VQFP	101 TFBGA (0.5 mm)	144 TQFP	196 TFBGA (0.8 mm)	196 TFBGA (0.5 mm)	208 PQFP	280 LFBGA	484 PBGA
QL8025	62	-	92	92		-	-	-
QL8050	62	72	100	124		-	-	-
QL8150	-	-	100	124	148	143	165	-
QL8250	-	-	-	-	-	115	163	250
QL8325	-	-	-	-	-	115	163	310

QuickWorks® Design Software

The QuickWorks package provides the most complete ESP and FPGA software solution from design entry to logic synthesis, to place and route, to power calculation, and simulation. The package provides a solution for designers who use third-party tools from Cadence, Mentor, OrCAD, Synopsys, Viewlogic, and other third-party tools for design entry, synthesis, or simulation.

Process Data

Eclipse II is fabricated on a 0.18 μ m, six layer metal CMOS process. The core voltage is 1.8 V and the I/Os are up to 3.3 V drive/tolerant. The Eclipse II product line is available in commercial, industrial, and military temperature grades.

Programmable Logic Architectural Overview

The Eclipse II logic cell structure is presented in **Figure 2**. This architectural feature addresses today's register-intensive designs.

Table 3: Performance Standards

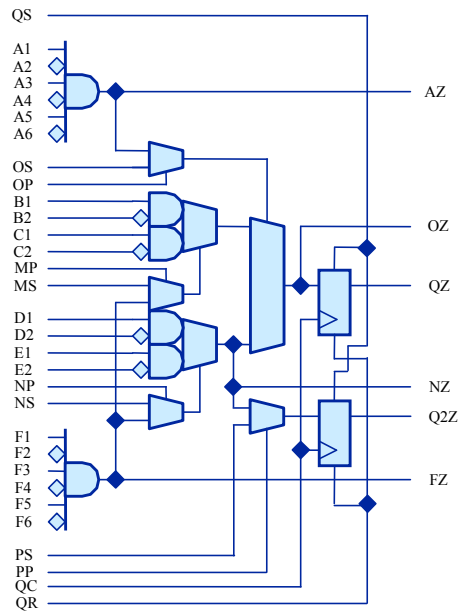
Function	Description	Slowest Speed Grade	Fastest Speed Grade
Multiplexer	16:1	2.8 ns	2.4 ns
Parity Tree	24	3.4 ns	2.9 ns
	36	4.6 ns	3.9 ns
Counter	16 bit	275 MHz	328 MHz
	32 bit	250 MHz	300 MHz
FIFO	128 x 32	197 MHz	235 MHz
	128 x 64	188 MHz	266 MHz
	256 x 16	208 MHz	248 MHz
Clock-to-Out		4 ns	3.3 ns
System clock		200 MHz	300 MHz

The Eclipse II logic cell structure presented in **Figure 2** is a dual register, multiplexer-based logic cell. It is designed for wide fan-in and multiple, simultaneous output functions. Both registers share CLK, SET, and RESET inputs. The second register has a two-to-one multiplexer controlling its input. The register can be loaded from the NZ output or directly from a dedicated input.

NOTE: The input PP is not an “input” in the classical sense. It is a static input to the logic cell and selects which path (NZ or PS) is used as an input to the Q2Z register. All other inputs are dynamic and can be connected to multiple routing channels.

The complete logic cell consists of two six-input AND gates, four two-input AND gates, seven two-to-one multiplexers, and two D flip-flops with asynchronous SET and RESET controls. The cell has a fan-in of 30 (including register control lines), fits a wide range of functions with up to 17 simultaneous inputs, and has six outputs (four combinatorial and two registered). The high logic capacity and fan-in of the logic cell accommodates many user functions with a single level of logic delay while other architectures require two or more levels of delay.

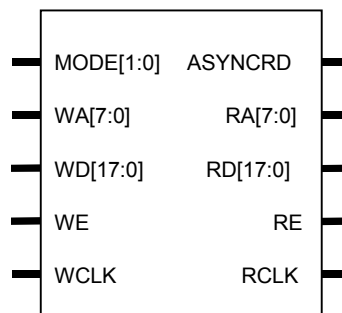
Figure 2: Eclipse II Logic Cell



RAM Modules

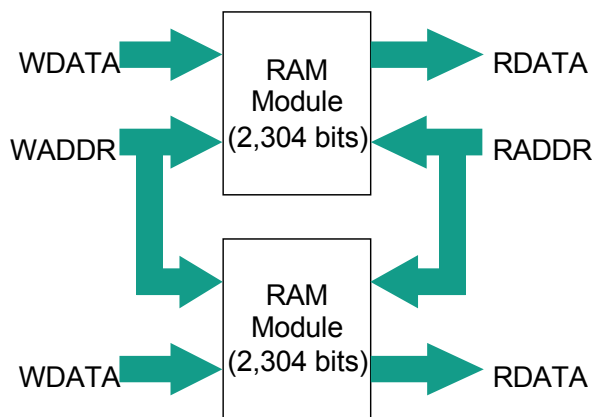
The Eclipse II Product Family includes up to 24 dual-port 2,304-bit RAM modules for implementing RAM, ROM, and FIFO functions. Each module is user-configurable into two different block organizations and can be cascaded horizontally to increase their effective width, or vertically to increase their effective depth as shown in **Figure 4**.

Figure 3: 2,304-bit RAM Module



The number of RAM modules varies from 4 to 24 blocks for a total of 9.2 K to 55.3 K bits of RAM. Using the two “mode” pins, designers can configure each module into 128 x 18 and 256 x 9. The blocks are also easily cascadable to increase their effective width and/or depth (see **Figure 4**).

Figure 4: Cascaded RAM Modules



The RAM modules are dual-port, with completely independent READ and WRITE ports and separate READ and WRITE clocks. The READ ports support asynchronous and synchronous operation, while the WRITE ports support synchronous operation. Each port has 18 data lines and 8 address lines, allowing word lengths of up to 18 bits and address spaces of up to 256 words. Depending on the mode selected, however, some higher order data or address lines may not be used.

The Write Enable (WE) line acts as a clock enable for synchronous write operation. The Read Enable (RE) acts as a clock enable for synchronous READ operation (ASYNCRD input low), or as a flow-through enable for asynchronous READ operation (ASYNCRD input high).

Designers can cascade multiple RAM modules to increase the depth or width allowed in single modules by connecting corresponding address lines together and dividing the words between modules.

A similar technique can be used to create depths greater than 256 words. In this case address signals higher than the MSB are encoded onto the write enable (WE) input for WRITE operations. The READ data outputs are multiplexed together using encoded higher READ address bits for the multiplexer SELECT signals.

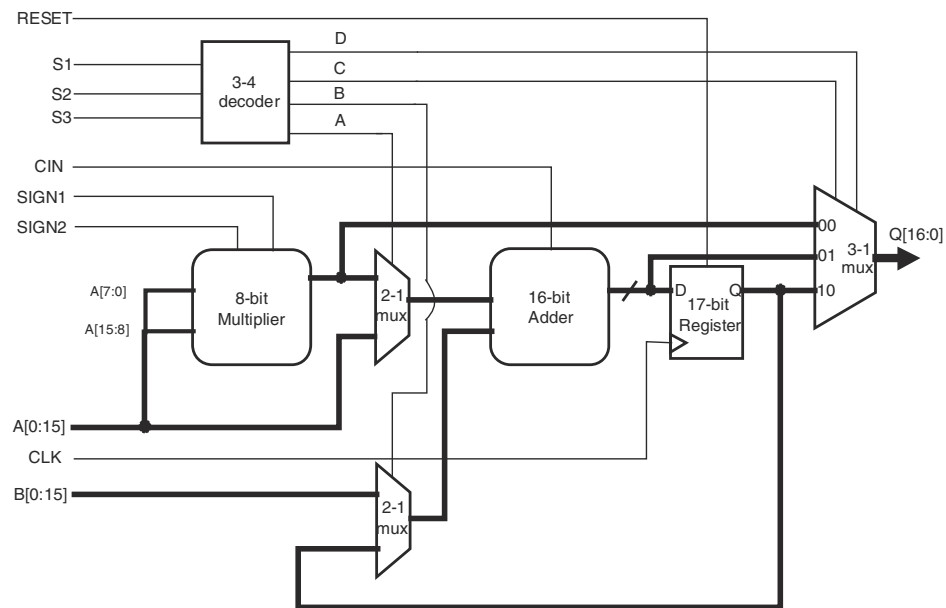
The RAM blocks can be loaded with data generated internally (typically for RAM or FIFO functions) or with data from an external PROM (typically for ROM functions).

Embedded Computational Unit (ECU)

Traditional Programmable Logic architectures do not implement arithmetic functions efficiently or effectively—these functions require high logic cell usage while garnering only moderate performance results.

The Eclipse II architecture allows for functionality above and beyond that achievable using programmable logic devices. By embedding a dynamically reconfigurable computational unit, the Eclipse II device can address various arithmetic functions efficiently. This approach offers greater performance and utilization than traditional programmable logic implementations. The embedded block is implemented at the transistor level as shown in **Figure 5**.

Figure 5: ECU Block Diagram



The Eclipse II ECU blocks (Table 4) are placed next to the SRAM circuitry for efficient memory/instruction fetch and addressing for DSP algorithmic implementations.

Table 4: Eclipse II ECU Blocks

Device	ECUs
QL8325	12
QL8250	10
QL8150	0
QL8050	0
QL8025	0

Up to twelve 8-bit MAC functions can be implemented per cycle for a total of 1 billion MACs/s when clocked at 100 MHz. Additional multiply-accumulate functions can be implemented in the programmable logic.

The modes for the ECU block are dynamically re-programmable through the programmable logic.

Table 5: ECU Mode Select Criteria

Instruction			Operation	ECU Performance ^a , -8 WCC		
S1	S2	S3		t _{PD}	t _{SU}	t _{CO}
0	0	0	Multiply	6.6 ns max		
0	0	1	Multiply-Add	8.8 ns max		
0	1	0	Accumulate ^b		3.9 ns min	1.2 ns max
0	1	1	Add	3.1 ns max		
1	0	0	Multiply (registered) ^c		9.6 ns min	1.2 ns max
1	0	1	Multiply- Add (registered)		9.6 ns min	1.2 ns max
1	1	0	Multiply - Accumulate		9.6 ns min	1.2 ns max
1	1	1	Add (registered)		3.9 ns min	1.2 ns max

a. t_{PD}, t_{SU} and t_{CO} do not include routing paths in/out of the ECU block.

b. Internal feedback path in ECU restricts max clk frequency to 238 MHz.

c. B [15:0] set to zero.

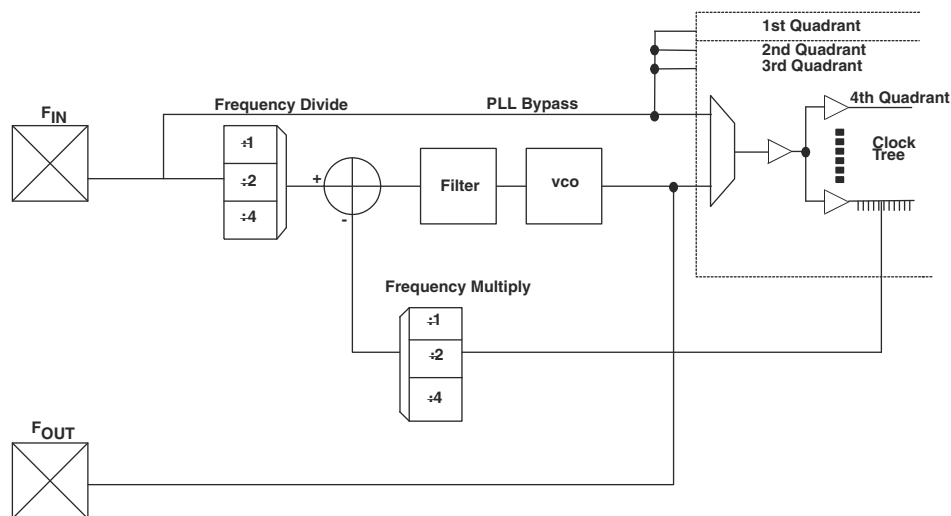
NOTE: Timing numbers in **Table 5** represent -8 Worst Case Commercial conditions.

Phase Locked Loop (PLL) Information

Instead of requiring extra components, designers simply need to instantiate one of the pre-configured models (described in this section). The QuickLogic built-in PLLs support a wider range of frequencies than many other PLLs. These PLLs also have the ability to support different ranges of frequency multiplications or divisions, driving the device at a faster or slower rate than the incoming clock frequency. When PLLs are cascaded, the clock signal must be routed off-chip through the PLLPAD_OUT pin prior to routing into another PLL; internal routing cannot be used for cascading PLLs.

Figure 6 illustrates a QuickLogic PLL.

Figure 6: PLL Block Diagram



F_{in} represents a very stable high-frequency input clock and produces an accurate signal reference. This signal can either bypass the PLL entirely, thus entering the clock tree directly, or it can pass through the PLL itself.

Within the PLL, a voltage-controlled oscillator (VCO) is added to the circuit. The external F_{in} signal and the local VCO form a control loop. The VCO is multiplied or divided down to the reference frequency, so that a phase detector (the crossed circle in **Figure 6**) can compare the two signals. If the phases of the external and local signals are not within the tolerance required, the phase detector sends a signal through the charge pump and loop filter (**Figure 6**). The charge pump generates an error voltage to bring the VCO back into alignment, and the loop filter removes any high frequency noise before the error voltage enters the VCO. This new VCO signal enters the clock tree to drive the chip's circuitry.

F_{out} represents the clock signal emerging from the output pad (the output signal PLLPAD_OUT is explained in **Table 7**). The PLL always drives the PLLPAD_OUT signal, regardless of whether the PLL is configured for on-chip use. The PLLPAD_OUT will not oscillate if PLL_RESET is asserted, or if the PLL is powered down.

The QL8325 and QL8250 devices contain four PLLs, the remaining Eclipse II devices do not contain PLLs. There is one PLL located in each quadrant of the FPGA. QuickLogic PLLs compensate for the additional delay created by the clock tree itself, as previously noted, by subtracting the clock tree delay through the feedback path.

PLL Modes of Operation

QuickLogic PLLs have eight modes of operation, based on the input frequency and desired output frequency—**Table 6** indicates the features of each mode.

NOTE: “HF” stands for “high frequency” and “LF” stands for “low frequency.”

Table 6: PLL Mode Frequencies

PLL Model	Output Frequency	Input Frequency Range	Output Frequency Range
PLL_HF	Same as input	66 MHz–220 MHz	66 MHz–220 MHz
PLL_LF	Same as input	25 MHz–66 MHz	25 MHz–66 MHz
PLL_MULT2HF	2x	33 MHz–110 MHz	66 MHz–220 MHz
PLL_MULT2LF	2x	12.5 MHz–33 MHz	25 MHz–66 MHz
PLL_DIV2HF	1/2x	220 MHz–440 MHz	110 MHz–220 MHz
PLL_DIV2LF	1/2x	50 MHz–220 MHz	25 MHz–110 MHz
PLL_MULT4	4x	12.5 MHz–50 MHz	50 MHz–200 MHz
PLL_DIV4	1/4x	100 MHz–440 MHz	25 MHz–110 MHz

The input frequency can range from 12.5 MHz to 440 MHz, while output frequency ranges from 25 MHz to 220 MHz. When adding PLLs to the top-level design, be sure that the PLL mode matches the desired input and output frequencies.

PLL Signals

Table 7 summarizes the key signals in QuickLogic PLLs.

Table 7: QuickLogic PLL Signals

Signal Name	Description
PLLCLK_IN	Input clock signal.
PLL_RESET	Active High Reset If PLL_RESET is asserted, then CLKNET_OUT and PLLPAD_OUT are reset to 0. This signal must be asserted and then released in order for the LOCK_DETECT to work.
ONn_OFFCHIP	This is a reserved signal. It can be connected to VCC or GND.
CLKNET_OUT	Out to internal gates This signal bypasses the PLL logic before driving the clock tree. Note that this signal cannot be used in the same quadrant where the PLL signal is used (PLLCLK_OUT).
PLLCLK_OUT	Out from PLL to internal gates This signal can drive the clock tree after going through the PLL.
PLLPAD_OUT	Out to off-chip This outgoing signal is used off-chip. The PLLPAD_OUT is always active, driving the PLL-derived clock signal out through the pad. The PLLPAD_OUT will not oscillate if PLL_RESET is asserted, or if the PLL is powered down.
LOCK_DETECT	Active High Lock detection signal NOTE: For simulation purposes, this signal gets asserted after 10 clock cycles. However, it can take a maximum of 200 clock cycles to sync with the input clock upon release of the PLL_RESET signal.

NOTE: Because PLLCLK_IN and PLL_RESET signals have PLL_INPAD, and PLLPAD_OUT has OUTPAD, you do not need to add additional pads to your design.

I/O Cell Structure

Eclipse II features a variety of distinct I/O pins to maximize performance, functionality, and flexibility with bi-directional I/O pins and input-only pins. All input and I/O pins are 1.8 V, 2.5 V, and 3.3 V tolerant and comply with the specific I/O standard selected. For single ended I/O standards, VCCIO specifies the input tolerance and the output drive. For voltage referenced I/O standards (e.g SSTL), the voltage supplied to the INREF pins in each bank specifies the input switch point. For example, the VCCIO pins must be tied to a 3.3 V supply to provide 3.3 V compliance. Eclipse II can also support the LVDS and LVPECL I/O standards with the use of external resistors (see **Table 8**).

Table 8: I/O Standards and Applications

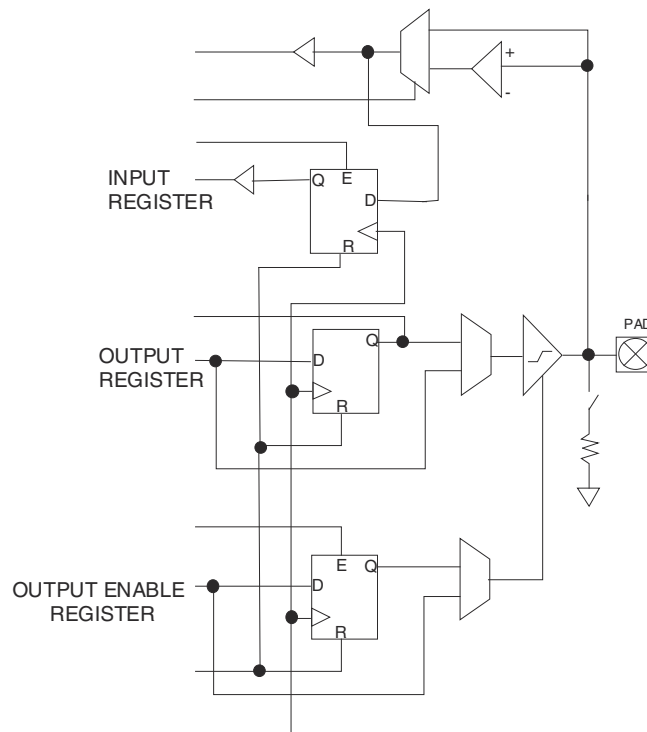
I/O Standard	Reference Voltage	Output Voltage	Application
LVTTTL	n/a	3.3 V	General Purpose
LVC MOS25	n/a	2.5 V	General Purpose
LVC MOS18	n/a	1.8 V	General Purpose
PCI	n/a	3.3 V	PCI Bus Applications
GTL+	1	n/a	Backplane
SSTL3	1.5	3.3 V	SDRAM
SSTL2	1.25	2.5 V	SDRAM

As designs become more complex and requirements more stringent, several application-specific I/O standards have emerged for specific applications. I/O standards for processors, memories, and a variety of bus applications have become commonplace and a requirement for many systems. In addition, I/O timing has

become a greater issue with specific requirements for setup, hold, clock to out, and switching times. Eclipse II has addressed these new system requirements and now includes a completely new I/O cell which consists of programmable I/Os as well as a new cell structure consisting of three registers—Input, Output, and OE.

Eclipse II offers banks of programmable I/Os that address many of the bus standards that are popular today. As shown in **Figure 7** each bi-directional I/O pin is associated with an I/O cell which features an input register, an input buffer, an output register, a three-state output buffer, an output enable register, and 2 two-to-one output multiplexers.

Figure 7: Eclipse II I/O Cell



The bi-directional I/O pin options can be programmed for input, output, or bi-directional operation. As shown in **Figure 7**, each bi-directional I/O pin is associated with an I/O cell which features an input register, an input buffer, an output register, a three-state output buffer, an output enable register, and 2 two-to-one multiplexers. The select lines of the two-to-one multiplexers are static and must be connected to either VCC or GND.

For input functions, I/O pins can provide combinatorial, registered data, or both options simultaneously to the logic array. For combinatorial input operation, data is routed from I/O pins through the input buffer to the array logic. For registered input operation, I/O pins drive the D input of input cell registers, allowing data to be captured with fast, predictable set-up times without consuming internal logic cell resources. The comparator and multiplexer in the input path allows for native support of I/O standards with reference points offset from traditional ground.

For output functions, I/O pins can receive combinatorial or registered data from the logic array. For combinatorial output operation, data is routed from the logic array through a multiplexer to the I/O pin. For registered output operation, the array logic drives the D input of the output cell register which in turn drives the I/O pin through a multiplexer. The multiplexer allows either a combinatorial or a registered signal to be

driven to the I/O pin. The addition of an output register will also decrease the T_{co} . Since the output register does not need to drive the routing the length of the output path is also reduced, and static timing analysis becomes very predictable.

The three-state output buffer controls the flow of data from the array logic to the I/O pin and allows the I/O pin to act as an input and/or output. The buffer's output enable can be individually controlled by the logic cell array or any pin (through the regular routing resources), or it can be bank-controlled through one of the global networks. The signal can also be either combinatorial or registered. This is identical to that of the flow for the output cell. For combinatorial control operation, data is routed from the logic array through a multiplexer to the three-state control. The IOCTRL pins can directly drive the OE and CLK signals for all I/O cells within the same bank.

For registered control operation, the array logic drives the D input of the OE cell register which in turn drives the three-state control through a multiplexer. The multiplexer allows either a combinatorial or a registered signal to be driven to the three-state control.

When I/O pins are unused, the OE controls can be permanently disabled, allowing the output cell register to be used for registered feedback into the logic array.

I/O cell registers are controlled by clock, clock enable, and reset signals, which can come from the regular routing resources, from one of the global networks, or from two IOCTRL input pins per bank of I/O's. The CLK and RESET signals share common lines, while the clock enables for each register can be independently controlled. I/O interface support is programmable on a per bank basis.

The two larger Eclipse II devices contain eight I/O banks. **Figure 8** illustrates the I/O bank configurations for QL8325 and QL8250. The three smaller Eclipse II devices contain two I/O banks per device. **Figure 9** illustrates the I/O bank configurations for QL8150, QL8050, and QL8025.

Each I/O bank is independent of other I/O banks and each I/O bank has its own VCCIO and INREF supply inputs. A mixture of different I/O standards can be used on the device; however, there is a limitation as to which I/O standards can be supported within a given bank. Only standards that share a common VCCIO and INREF can be shared within the same bank (e.g., PCI and LVTTTL). In the case of the QL8150, QL8050 and QL8025, only one voltage-referenced standard can be used. The two I/O banks, A and B, share the INREF pin.

Figure 8: Multiple I/O Banks on QL8325 and QL8250

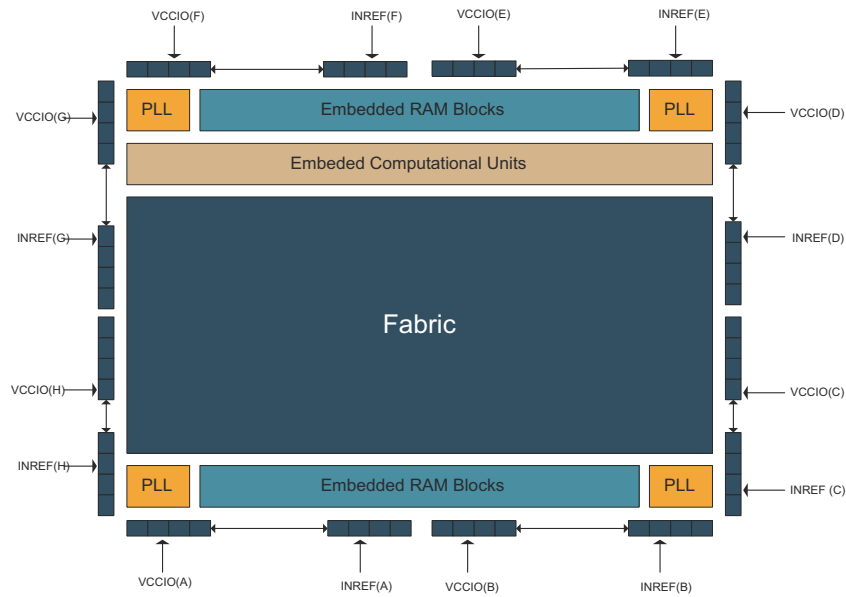
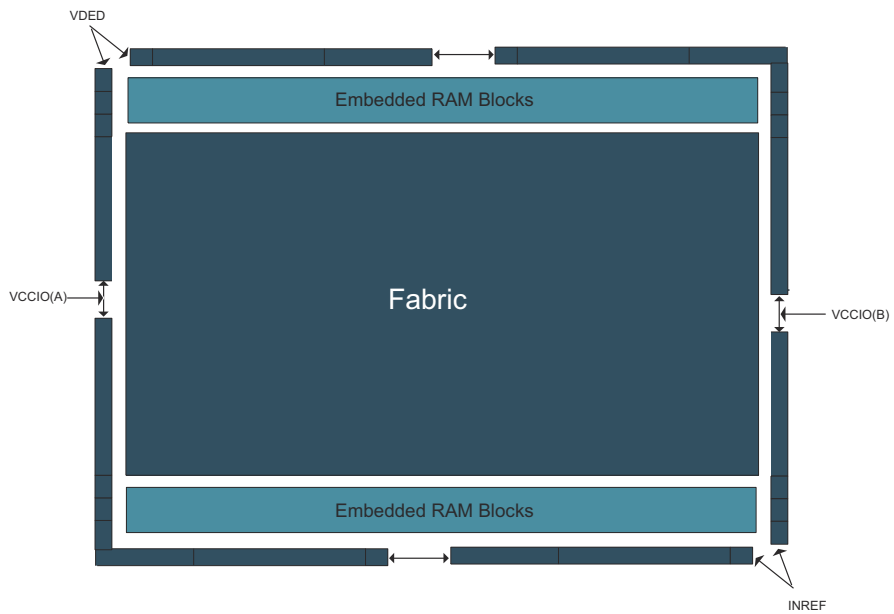


Figure 9: Multiple I/O Banks on QL8150, QL8050, and QL8025



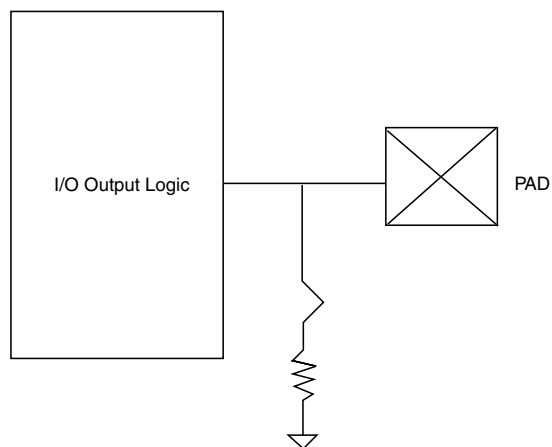
Programmable Slew Rate

Each I/O has programmable slew rate capability—the slew rate can be either fast or slow. The slower rate can be used to reduce the switching times of each I/O.

Programmable Weak Pull-Down

A programmable Weak Pull-Down resistor is available on each I/O. The I/O Weak Pull-Down eliminates the need for external pull down resistors for used I/Os as shown in **Figure 10**. The spec for pull-down current is maximum of 150 μA under worst case condition.

Figure 10: Programmable I/O Weak Pull-Down

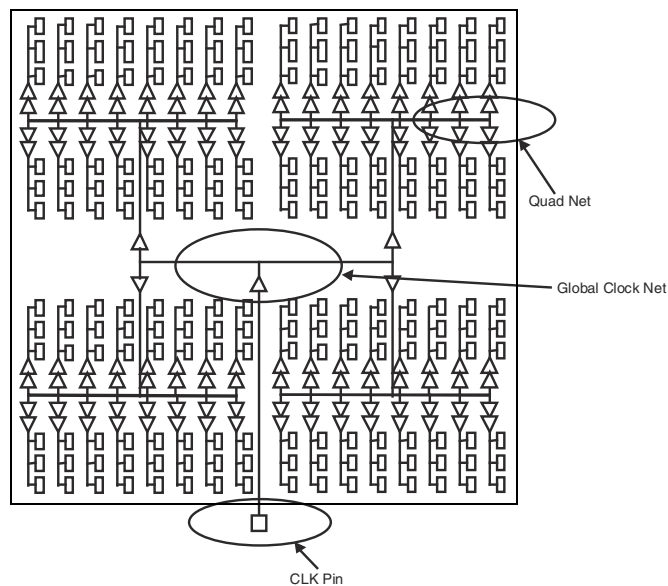


Clock Networks

Global Clocks

There are eight global clock networks in each QL8325 and QL8250 device, and five global clock networks in each QL8150, QL8050 and QL8025 device. Global clocks can drive logic cells and I/O registers, ECUs, and RAM blocks in the device. All global clocks have access to a Quad Net (local clock network) connection with a programmable connection to the logic cell's register clock input.

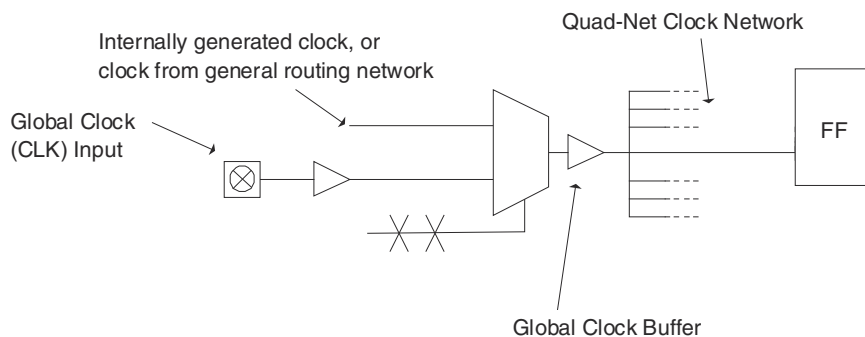
Figure 11: Global Clock Architecture



Quad-Net Network

There are five Quad-Net local clock networks in each quadrant for a total of 20 in a device. Each Quad-Net is local to a quadrant. Before driving the column clock buffers, the quad-net is driven by the output of a mux which selects between the CLK pin input and an internally generated clock source (see Figure 12).

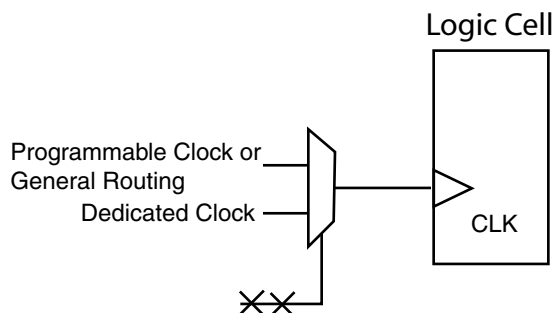
Figure 12: Global Clock Structure



Dedicated Clock

There is one dedicated clock in the two larger devices of the Eclipse II Family (QL8325 and QL8250). This clock connects to the clock input of the Logic Cell and I/O registers, and RAM blocks through a hardwired connection and is multiplexed with the programmable clock input. The dedicated clock provides a fast global network with low skew. Users have the ability to select either the dedicated clock or the programmable clock (Figure 13).

Figure 13: Dedicated Clock Circuitry within Logic Cell



NOTE: For more information on the clocking capabilities of Eclipse II FPGAs, see QuickLogic Application Note 68.

I/O Control and Local Hi-Drives

Each bank of I/Os has two input-only pins that can be programmed to drive the RST, CLK, and EN inputs of I/Os in that bank. These input-only pins also serve as high drive inputs to a quadrant. These buffers can be driven by the internal logic both as an I/O control or high drive. For I/O constrained designs, these pins can be used for general purpose inputs. To provide more general purpose I/Os in the 208 PQFP package, the I/O controls pins are not bonded out. The performance of these resources is presented in Table 9.

Table 9: I/O Control Network/Local High-Drive

Destination TT, 25 C, 2.5 V	From Pad	From Array
I/O (far)	1.00 ns	1.14 ns
I/O (near)	0.63 ns	0.78 ns
Skew	0.37 ns	0.36 ns

Table 10 shows the total number of I/O control pins per device/package combination. These pins are not bonded out in the smaller devices and packages. This increases the number of bi-directional user I/Os available.

Table 10: I/O Control Pins per Device/Package Combination

Device	100 VQFP	101 TFBGA	144 TQFP	196 TFBGA (0.8 mm)	196 TFBGA (0.5 mm)	208 PQFP	280 LFBGA	484 BGA
QL8025	-	NA	-	-	NA ^a	NA	NA	NA
QL8050	-	-	-	-	NA	NA	NA	NA
QL8150	NA	NA	-	-	-	-	NA	NA
QL8250	NA	NA	NA	NA	NA	-	16	16
QL8325	NA	NA	NA	NA	NA	-	16	16

a. Not available.

Programmable Logic Routing

Eclipse II devices are engineered with six types of routing resources as follows: short (sometimes called segmented) wires, dual wires, quad wires, express wires, distributed networks, and default wires. Short wires span the length of one logic cell, always in the vertical direction. Dual wires run horizontally and span the length of two logic cells. Short and dual wires are predominantly used for local connections. Default wires supply VCC and GND (Logic '1' and Logic '0') to each column of logic cells.

Quad wires have passive link interconnect elements every fourth logic cell. As a result, these wires are typically used to implement intermediate length or medium fan-out nets.

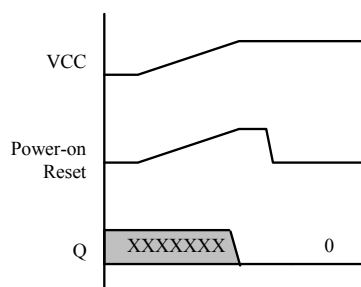
Express lines run the length of the device, uninterrupted. Each of these lines has a higher capacitance than a quad, dual, or short wire, but less capacitance than shorter wires connected to run the length of the device. The resistance will also be lower because the express wires don't require the use of pass links. Express wires provide higher performance for long routes or high fan-out nets.

Distributed networks are described in **Clock Networks** on page 14. These wires span the programmable logic and are driven by quad-net buffers.

Global Power-On Reset (POR)

The Eclipse II family of devices features a global power-on reset. This reset is hardwired to all registers and resets them to Logic '0' upon power-up of the device. In QuickLogic devices, the asynchronous Reset input to flip-flops has priority over the Set input; therefore, the Global POR will reset all flip-flops during power-up. If you want to set the flip-flops to Logic '1', you must assert the "Set" signal after the Global POR signal has been deasserted.

Figure 14: Power-On Reset

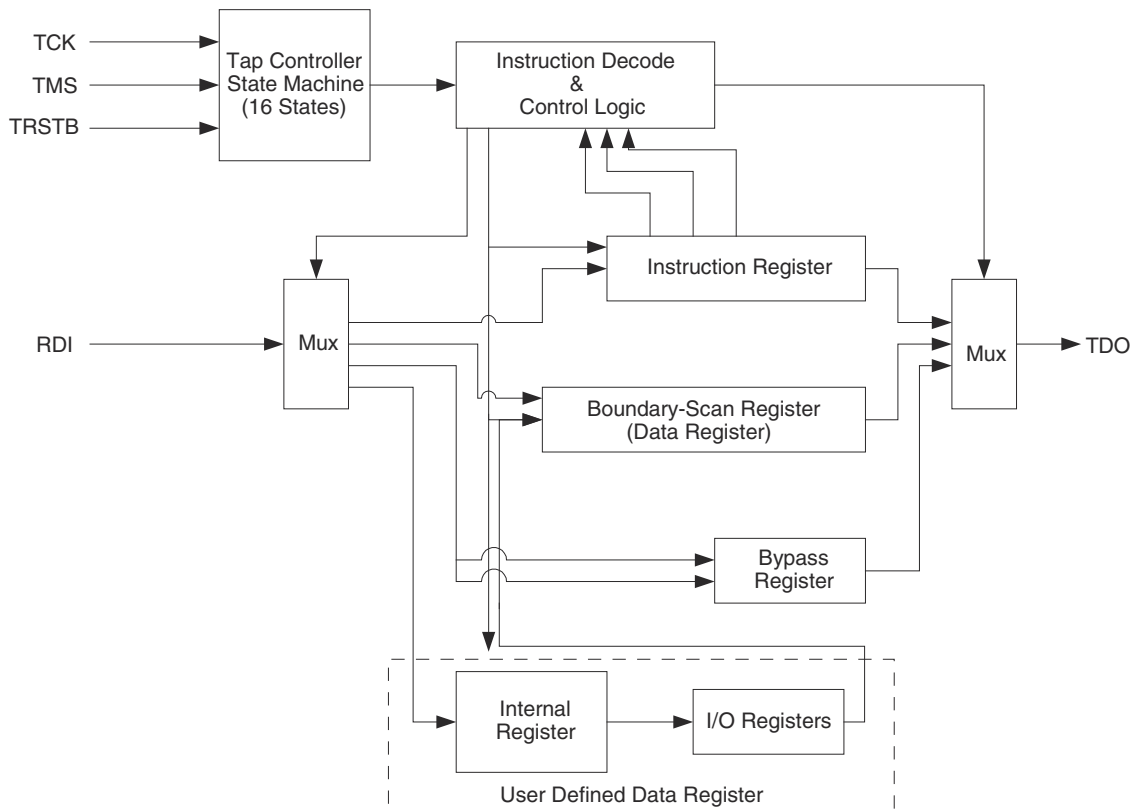


Low Power Mode

Quiescent power consumption of all Eclipse II devices can be reduced significantly by de-activating the charge pumps inside the architecture. By applying 3.3 V to the VPUMP pin, the internal charge pump is de-activated—this effectively reduces the static and dynamic power consumption of the device. The Eclipse II device is fully functional and operational in the Low Power mode. Users who have a 3.3 V supply available in their system should take advantage of this low power feature by tying the VPUMP pin to 3.3 V. Otherwise, if a 3.3 V supply is not available, this pin should be tied to ground.

Joint Test Access Group (JTAG) Information

Figure 15: JTAG Block Diagram



Microprocessors and Application Specific Integrated Circuits (ASICs) pose many design challenges, one problem being the accessibility of test points. JTAG formed in response to this challenge, resulting in IEEE standard 1149.1, the Standard Test Access Port and Boundary Scan Architecture.

The JTAG boundary scan test methodology allows complete observation and control of the boundary pins of a JTAG-compatible device through JTAG software. A Test Access Port (TAP) controller works in concert with the Instruction Register (IR), which allow users to run three required tests along with several user-defined tests.

JTAG tests allow users to reduce system debug time, reuse test platforms and tools, and reuse subsystem tests for fuller verification of higher level system elements.

The 1149.1 standard requires the following three tests:

- Extest Instruction.** The Extest Instruction performs a printed circuit board (PCB) interconnect test. This test places a device into an external boundary test mode, selecting the boundary scan register to be connected between the TAP Test Data In (TDI) and Test Data Out (TDO) pins. Boundary scan cells are preloaded with test patterns (through the Sample/Preload Instruction), and input boundary cells capture the input data for analysis.

- **Sample/Preload Instruction.** The Sample/Preload Instruction allows a device to remain in its functional mode, while selecting the boundary scan register to be connected between the TDI and TDO pins. For this test, the boundary scan register can be accessed through a data scan operation, allowing users to sample the functional data entering and leaving the device.
- **Bypass Instruction.** The Bypass Instruction allows data to skip a device boundary scan entirely, so the data passes through the bypass register. The Bypass instruction allows users to test a device without passing through other devices. The bypass register is connected between the TDI and TDO pins, allowing serial data to be transferred through a device without affecting the operation of the device.

JTAG BSDL Support

- BSDL-Boundary Scan Description Language
- Machine-readable data for test equipment to generate testing vectors and software
- BSDL files available for all device/package combinations from QuickLogic
- Extensive industry support available and ATVG (Automatic Test Vector Generation)

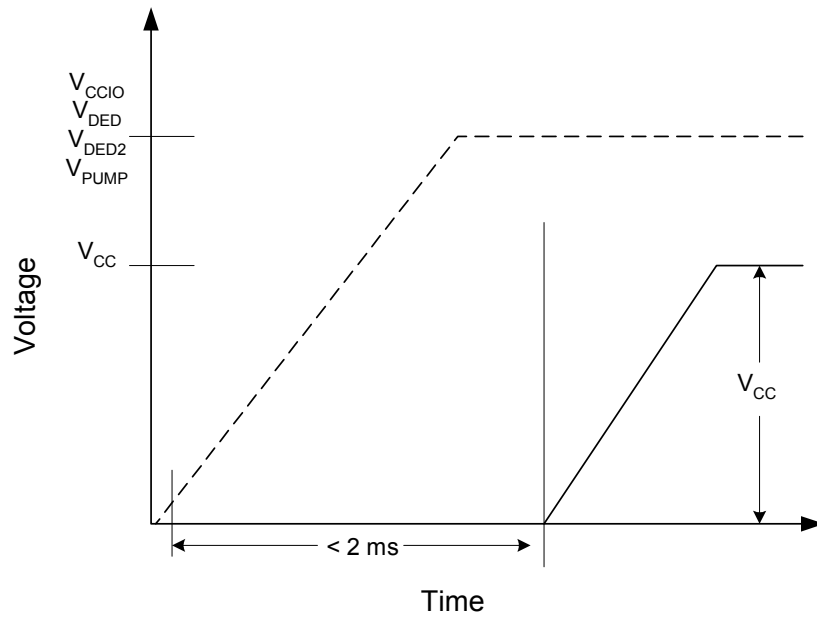
Security Links

There are several security links to disable reading logic from the array, and to disable JTAG access to the device. Programming these optional links completely disables access to the device from the outside world and provides an extra level of design security not possible in SRAM-based FPGAs. The option to program these links is selectable through QuickWorks in the Tools/Options/Device Programming window in SpDE.

Power-Up Loading Link

The flexibility link enables Power-Up Loading of the Embedded RAM blocks. If the link is programmed, the Power-Up Loading state machine is activated during power-up of the device. The state machine communicates with an external EPROM via the JTAG pins to download memory contents into the on-chip RAM. If the link is not programmed, Power-Up Loading is not enabled and the JTAG pins function as they normally would. The option to program this link is selectable through QuickWorks in the Tools/Options/Device Programming window in SpDE. For more information on Power-Up Loading, see QuickLogic Application Note 55. See the Power-Up Loading power-up sequencing requirement for proper functionality in **Figure 16**.

Figure 16: Required Power-Up Sequence When Using Power-Up Loading



To use the power-up loading function in Eclipse II, designers must ensure that V_{CC} begins to ramp within a maximum of 2 ms of V_{CCIO} , V_{DED} , V_{DED2} , and V_{PUMP} .

Electrical Specifications

DC Characteristics

The DC Specifications are provided in **Table 11** through **Table 14**.

Table 11: Absolute Maximum Ratings

Parameter	Value	Parameter	Value
VCC Voltage	-0.5 V to 2.0 V	Latch-up Immunity	±100 mA
VCCIO Voltage	-0.5 V to 4.0 V	DC Input Current	±20 mA
INREF Voltage	0.5 V to VCCIO	Leaded Package Storage Temperature	-65° C to + 150° C
Input Voltage	-0.5 V to VCCIO + 0.5 V	Laminate Package (BGA) Storage Temperature	-55° C to + 125° C

Table 12: Recommended Operating Range

Symbol	Parameter	Military		Industrial		Commercial		Unit	
		Min	Max	Min	Max	Min	Max		
VCC	Supply Voltage	1.71	1.89	1.71	1.89	1.71	1.89	V	
VCCIO	I/O Input Tolerance Voltage	1.71	3.60	1.71	3.60	1.71	3.60	V	
TJ	Junction Temperature	-55	125	-40	100	0	85	°C	
K	Delay Factor	-6 Speed Grade	0.49	1.57	0.50	1.51	0.54	1.47	n/a
		-7 Speed Grade	0.48	1.40	0.50	1.34	0.53	1.31	n/a
		-8 Speed Grade	0.45	1.32	0.47	1.26	0.50	1.23	n/a

Table 13: DC Characteristics

Symbol	Parameter	Conditions	Min	Max	Units
I_I	I or I/O Input Leakage Current	$V_I = V_{CCIO}$ or GND	-1	1	μA
I_{OZ}	3-State Output Leakage Current	$V_I = V_{CCIO}$ or GND	-	1	μA
C_I	I/O Input Capacitance	-	-	8	pF
C_{CLOCK}	Clock Input Capacitance	-	-	8	pF
I_{OS}	Output Short Circuit Current ^a	$V_O = \text{GND}$ $V_O = V_{CC}$	-15 40	-180 210	mA mA
I_{REF}	Quiescent Current on INREF	-	-10	10	μA
I_{PD}	Current on programmable pull-down	$V_{CC} = 1.8 \text{ V}$	-	50	μA
I_{PUMP}	Quiescent Current on VPUMP	$V_{PUMP} = 3.3 \text{ V}$	-	10	μA
I_{PLL}	Quiescent Current on each VCCPLL	2.5 V 3.3 V	-	3	mA
I_{VCCIO}	Quiescent Current on VCCIO	$V_{CCIO} = 3.3 \text{ V}$ $V_{CCIO} = 2.5 \text{ V}$ $V_{CCIO} = 1.8 \text{ V}$	-	20 10 10	μA

a. The data provided in **Table 13** represents the JEDEC and PCI specifications. Duration should not exceed 30 seconds.

Table 14: DC Input and Output Levels^a

Symbol	INREF		V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V_{MIN}	V_{MAX}	V_{MIN}	V_{MAX}	V_{MIN}	V_{MAX}	V_{MAX}	V_{MIN}	mA	mA
LVTTL	n/a	n/a	-0.3	0.8	2.2	$V_{CCIO} + 0.3$	0.4	2.4	2.0	-2.0
LVC MOS2	n/a	n/a	-0.3	0.7	1.7	$V_{CCIO} + 0.3$	0.7	1.7	2.0	-2.0
LVC MOS18	n/a	n/a	-0.3	0.63	1.2	$V_{CCIO} + 0.3$	0.7	1.7	2.0	-2.0
GTL+	0.88	1.12	-0.3	$\text{INREF} - 0.2$	$\text{INREF} + 0.2$	$V_{CCIO} + 0.3$	0.6	n/a	40	n/a
PCI	n/a	n/a	-0.3	$0.3 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	$V_{CCIO} + 0.5$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
SSTL2	1.15	1.35	-0.3	$\text{INREF} - 0.18$	$\text{INREF} + 0.18$	$V_{CCIO} + 0.3$	0.74	1.76	7.6	-7.6
SSTL3	1.3	1.7	-0.3	$\text{INREF} - 0.2$	$\text{INREF} + 0.2$	$V_{CCIO} + 0.3$	1.10	1.90	8	-8

a. The data provided in **Table 14** represents the JEDEC and PCI specification. QuickLogic devices either meet or exceed these requirements. For data specific to QuickLogic I/Os, see preceding **Table 19** through **Table 27**, **Figure 7** through **Figure 10**, and **Figure 39** through **Figure 42**.

NOTE: All CLK, IOCTRL, and PLLIN pins are clamped to the VDED rail. Therefore, these pins can be driven up to VDED. All JTAG inputs are clamped to the VDED2 rail. These JTAG input pins can only be driven up to VDED2.

Figure 17 through Figure 20 show the VIL and VIH characteristics for I/O and clock pins.

Figure 17: VIL Maximum for I/O

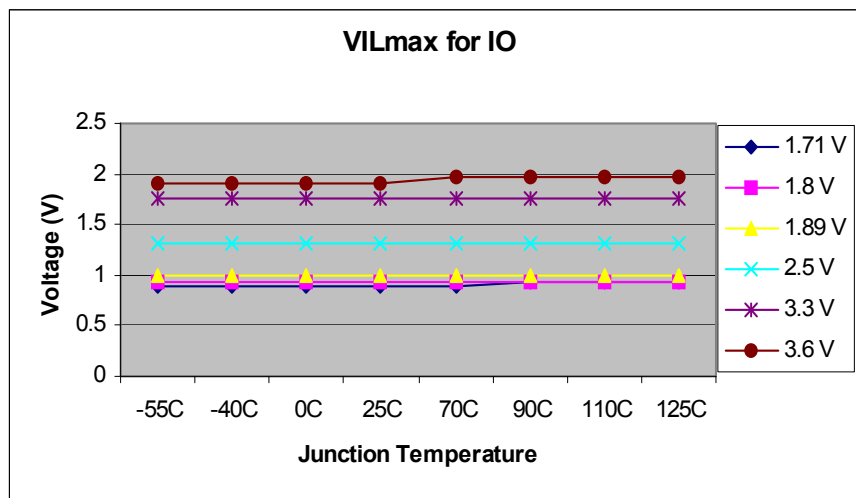


Figure 18: VIH Minimum for I/O

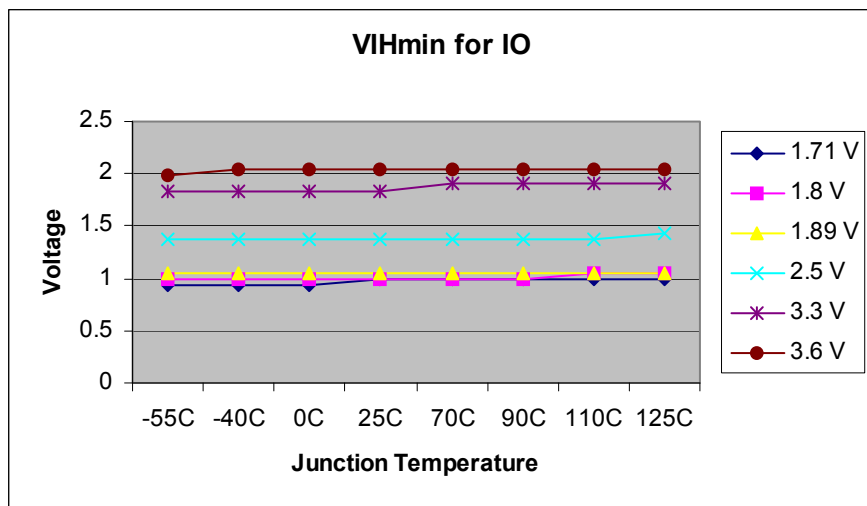


Figure 19: VIL Maximum for CLOCK Pins

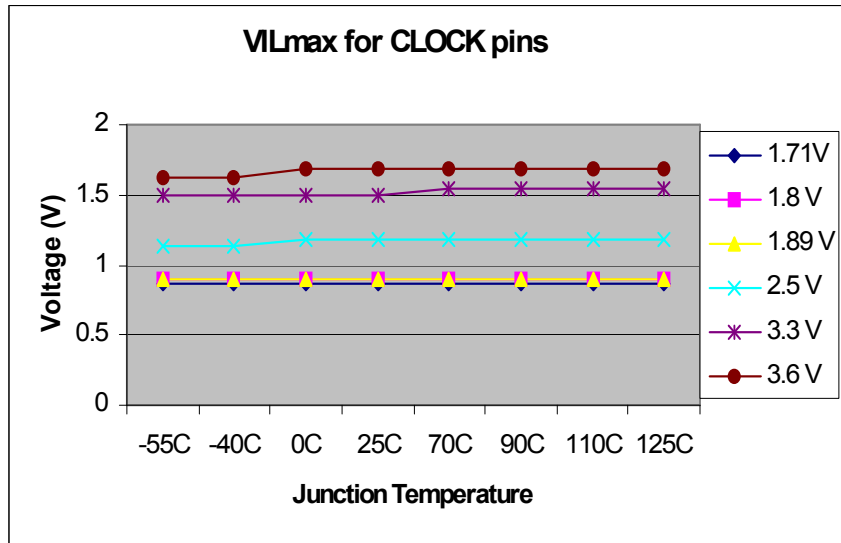


Figure 20: VIH Minimum for CLOCK Pins

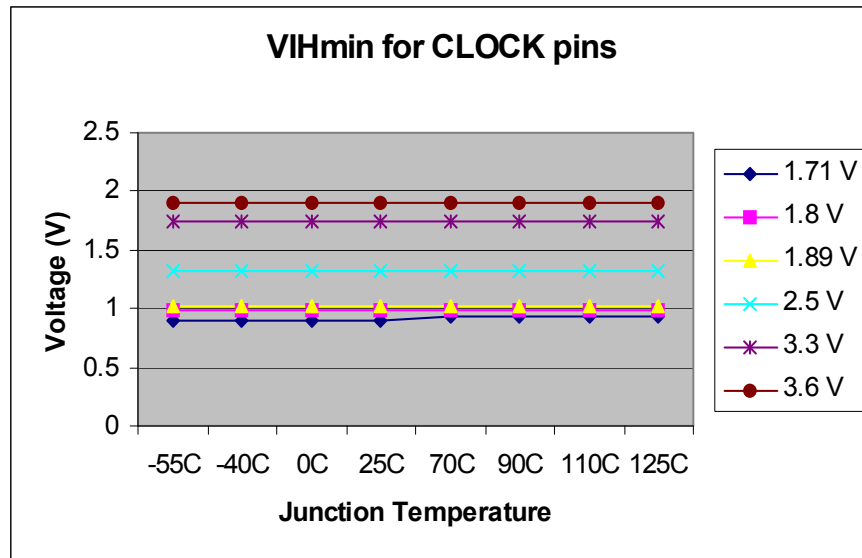


Figure 21 through Figure 25 show the output drive characteristics for the I/Os across various voltages and temperatures.

Figure 21: Drive Current at VCCIO = 1.71 V

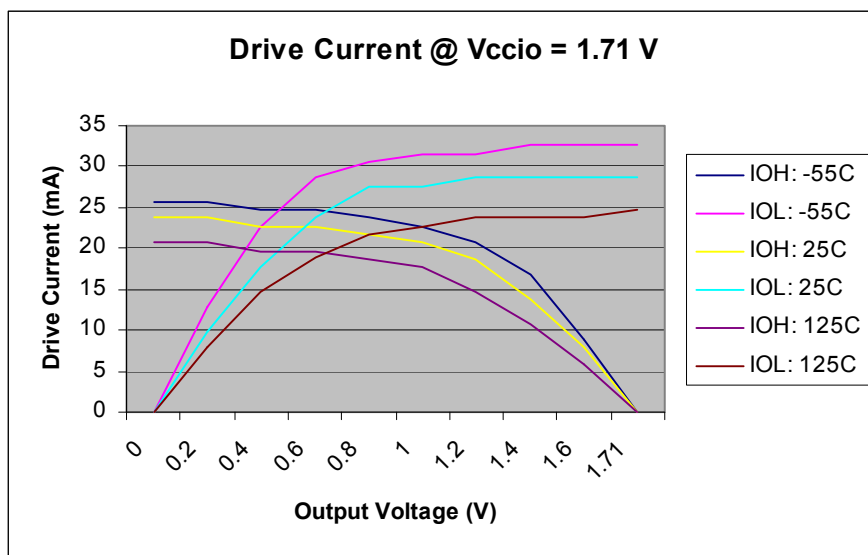


Figure 22: Drive Current at VCCIO = 1.8 V

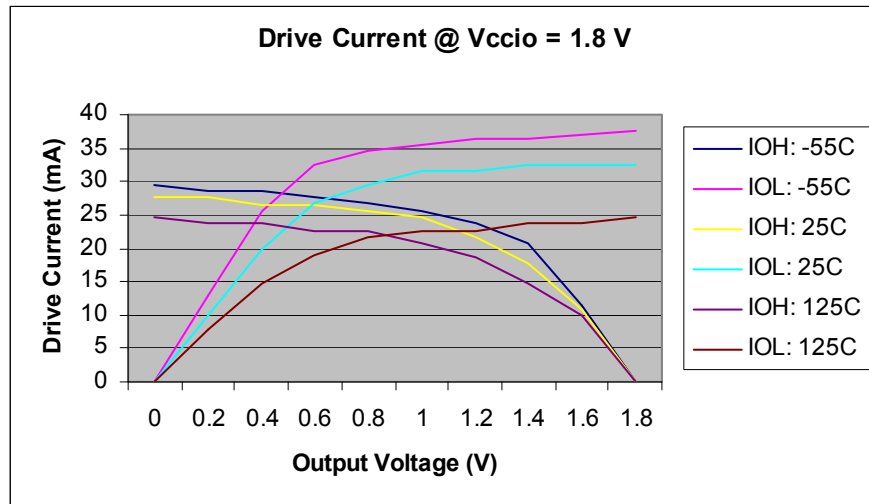


Figure 23: Drive Current at VCCIO = 2.5 V

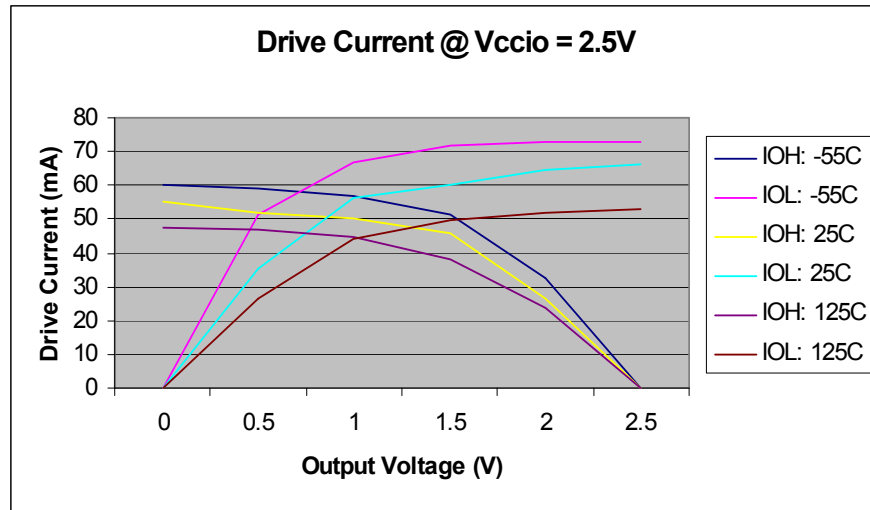


Figure 24: Drive Current at VCCIO = 3.3 V

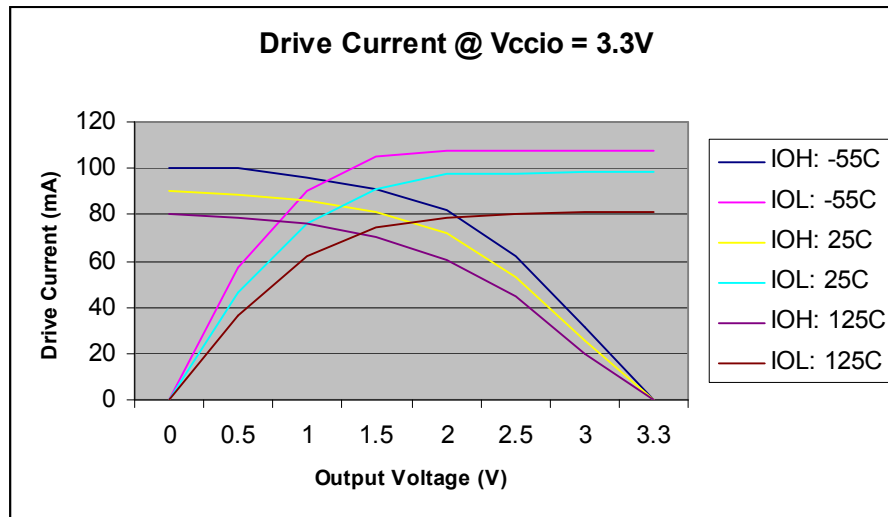


Figure 25: Drive Current at VCCIO = 3.6 V

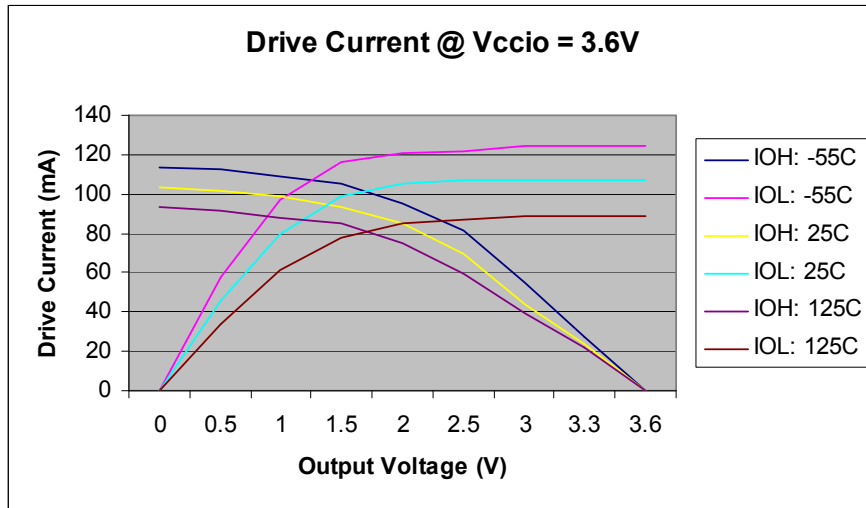


Figure 26 through Figure 30 show the quiescent current for the Eclipse II family of devices for each of the voltage supplies, across voltage and temperature. Quiescent current on V_{CC} is a function of device utilization. The numbers in the following graphs were taken from 100% utilized devices, filled with 32-bit counters. For conditions other than those described, measured quiescent current levels may be higher than the values in Figure 26 through Figure 30. Use the Power Calculator Tool for more accurate estimates.

Figure 26: Quiescent Current on V_{CC} for QL8025

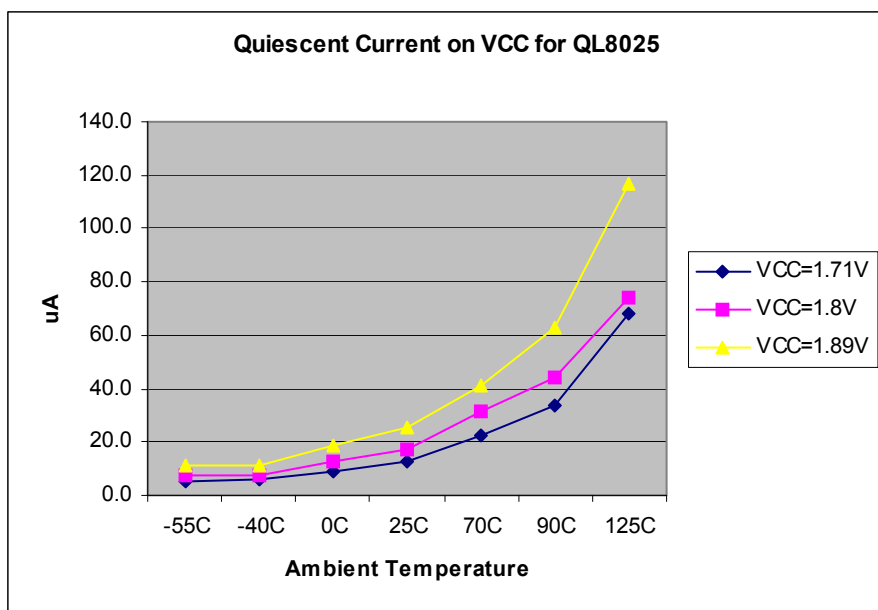


Table 15: Quiescent Current on V_{CC} for QL8025 (Over All Temperatures – Over 1.71 V to 3.6 V)

Parameter	Current
IVDED	2.5 μ A
ICCIO	1.0 μ A

Figure 27: Quiescent Current on V_{CC} for QL8050

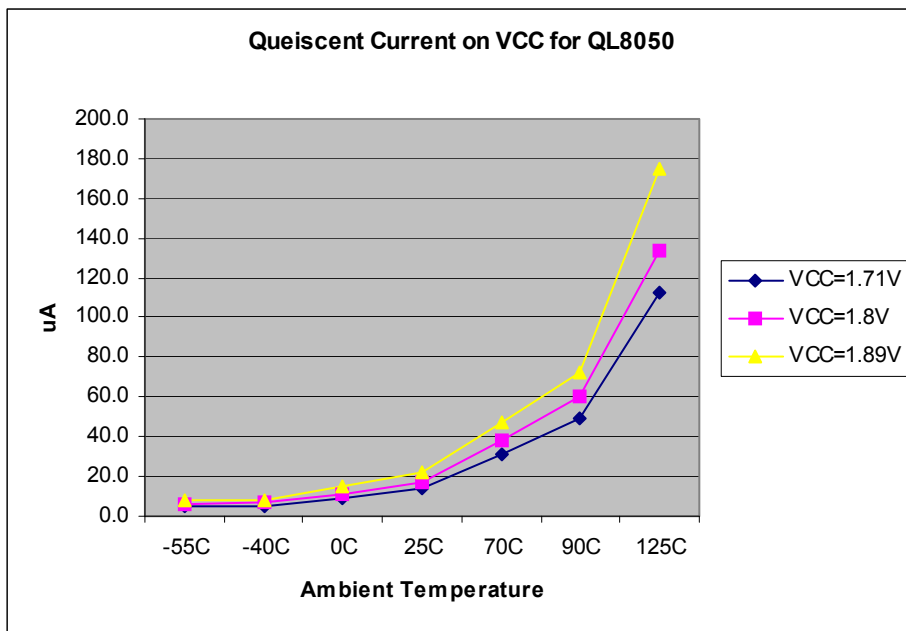


Table 16: Quiescent Current on V_{CC} for QL8050 (Over All Temperatures – Over 1.71 V to 3.6 V)

Parameter	Current
IVDED	2.6 μA
ICCIO	2.0 μA

Figure 28: Quiescent Current on V_{CC} for QL8150

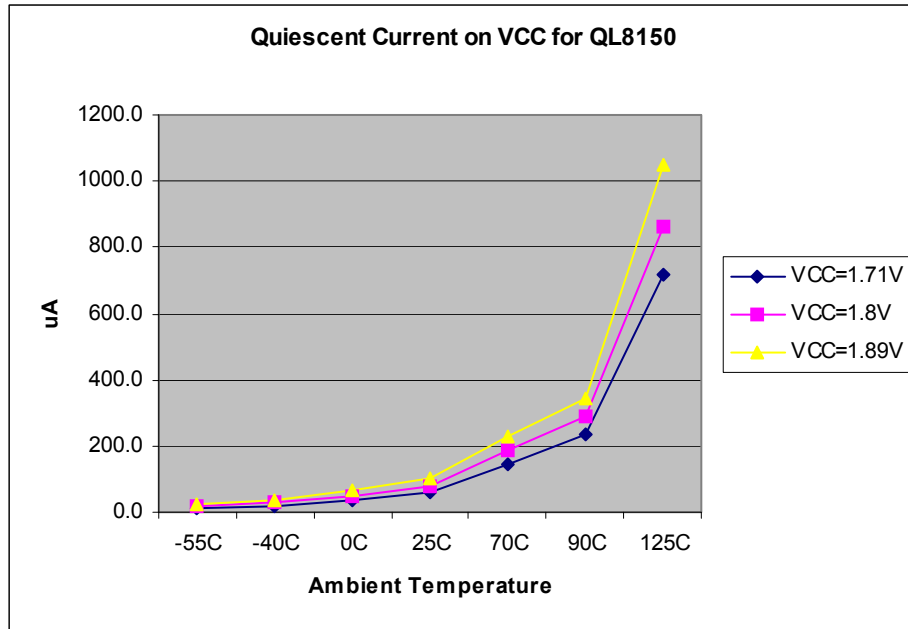


Table 17: Quiescent Current on V_{CC} for QL8150 (Over All Temperatures – Over 1.71 V to 3.6 V)

Parameter	Current
IVDED	18.4 μA
ICCIO	7.7 μA

Figure 29: Quiescent Current on V_{CC} for QL8250

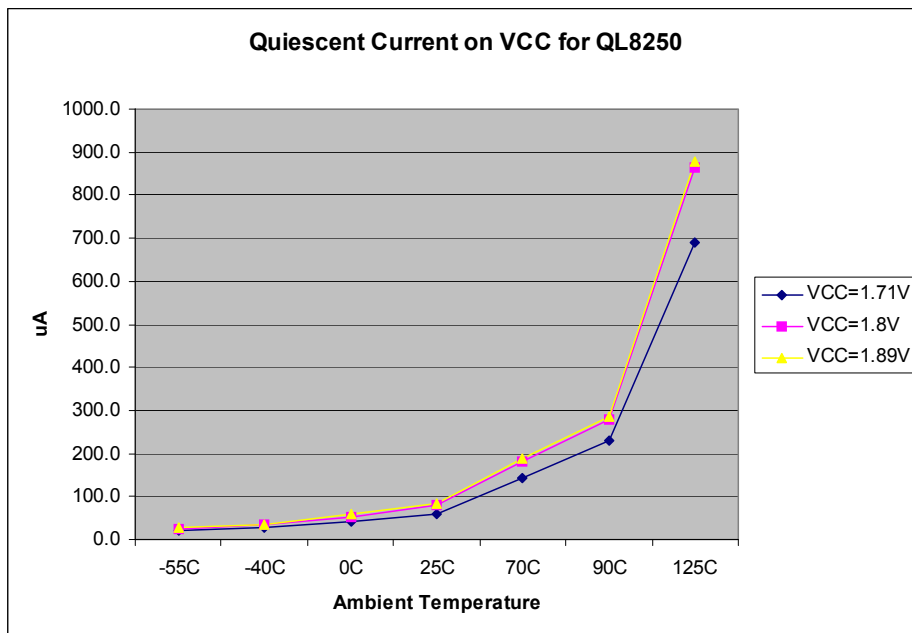


Table 18: Quiescent Current on V_{CC} for QL8250 (Over All Temperatures – Over 1.71 V to 3.6 V)

Parameter	Current
IVDED	16.9 μA
ICCIO	5.5 μA

Figure 30: Quiescent Current on V_{CC} for QL8325

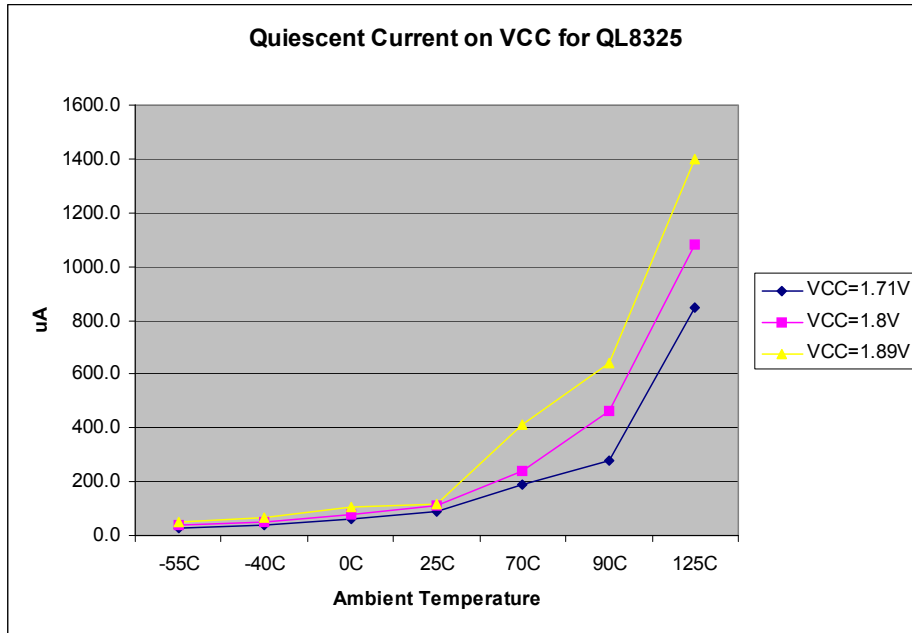


Table 19: Quiescent Current on V_{CC} for QL8325 (Over All Temperatures – Over 1.71 V to 3.6 V)

Parameter	Current
I _{VDED}	16.9 μA
I _{CCIO}	5.1 μA

AC Characteristics

The AC Specifications (at $V_{CC} = 1.8\text{ V}$, $T_J = 25^\circ\text{ C}$, Worst Case Corner, Speed Grade = -8 ($K = 1.03$)) are provided from **Table 20** through **Table 29**. Logic Cell diagrams and waveforms are provided from **Figure 31** through **Figure 42**.

Figure 31: Eclipse II Logic Cell

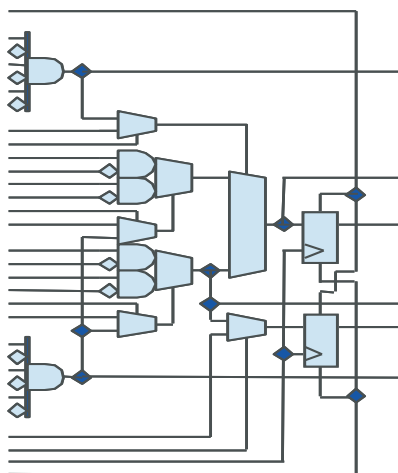


Table 20: Logic Cell Delays

Symbol	Parameter	Value	
		Min	Max
t_{PD}	Combinatorial Delay of the longest path: time taken by the combinatorial circuit to output	0.28 ns	0.98 ns
t_{SU}	Setup time: time the synchronous input of the flip-flop must be stable before the active clock edge	0.10 ns	0.25 ns
t_{HL}	Hold time: time the synchronous input of the flip-flop must be stable after the active clock edge	0 ns	0 ns
t_{CO}	Clock-to-out delay: the amount of time taken by the flip-flop to output after the active clock edge.	0.22 ns	0.52 ns
t_{CWHI}	Clock High Time: required minimum time the clock stays high	0.46 ns	0.46 ns
t_{CWLO}	Clock Low Time: required minimum time that the clock stays low	0.46 ns	0.46 ns
t_{SET}	Set Delay: time between when the flip-flop is "set" (high) and when the output is consequently "set" (high)	0.69 ns	0.69 ns
t_{RESET}	Reset Delay: time between when the flip-flop is "reset" (low) and when the output is consequently "reset" (low)	1.09 ns	1.09 ns
t_{SW}	Set Width: time that the SET signal must remain high/low	0.3 ns	0.3 ns
t_{RW}	Reset Width: time that the RESET signal must remain high/low	0.3 ns	0.3 ns

Figure 32: Logic Cell Flip-Flop

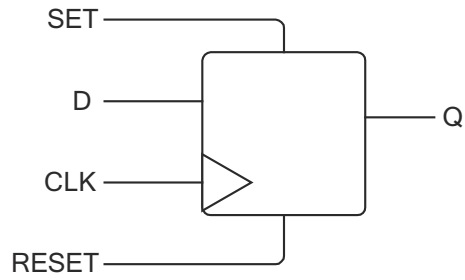


Figure 33: Logic Cell Flip-Flop Timings—First Waveform

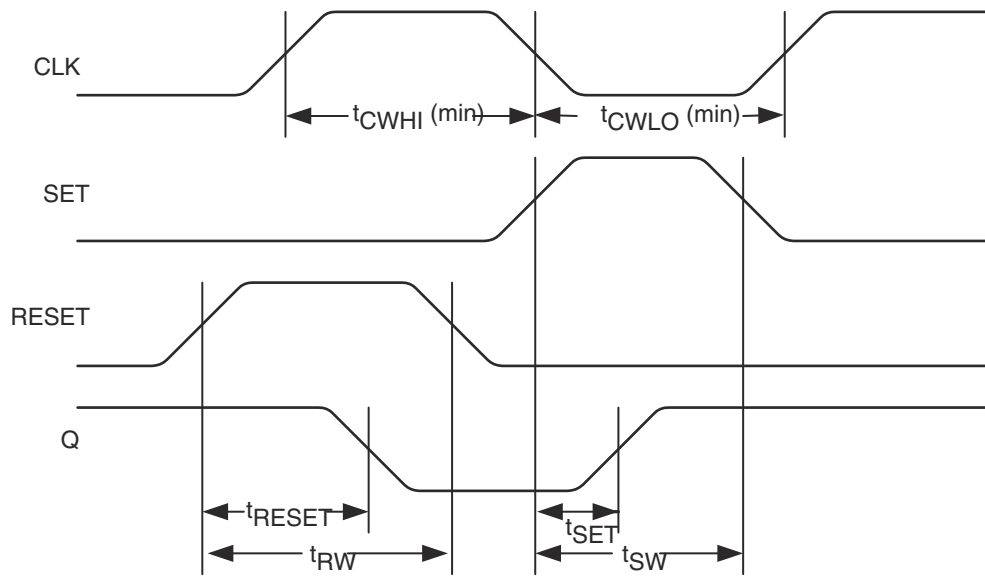


Figure 34: Logic Cell Flip-Flop Timings—Second Waveform

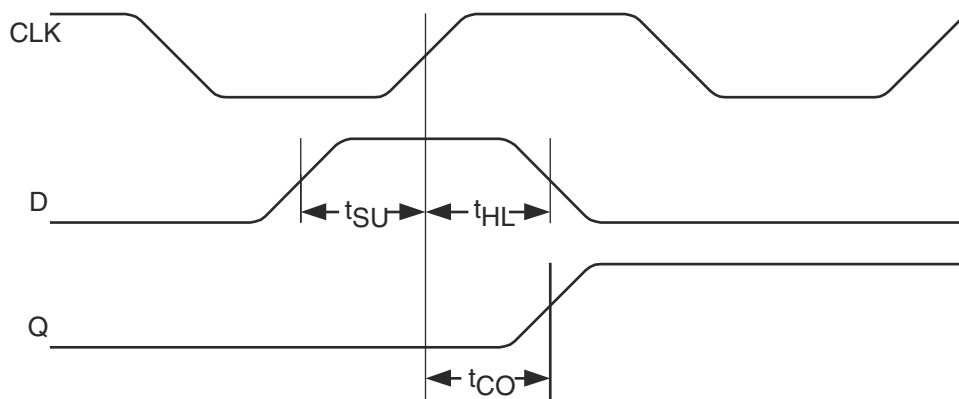


Table 21: Eclipse II Tree Clock Delay

Clock Segment	Parameter	Value	
		Min	Max
t_{PGCK}	Global clock pin delay to quad net	-	1.92 ns
t_{BGCK}	Global clock tree delay (quad net to flip-flop)	-	0.28 ns
t_{DPD}	Dedicated clock pad	-	1.7 ns
t_{GSKEW}	Global delay clock skew	-	0.1 ns
t_{DSKEW}	Dedicated clock skew	-	0.05 ns

NOTE: When using a PLL, t_{PGCK} and t_{BGCK} are effectively zero due to delay adjustment by Phase Locked Loop feedback path.

Figure 35: Global Clock Structure Timing Elements

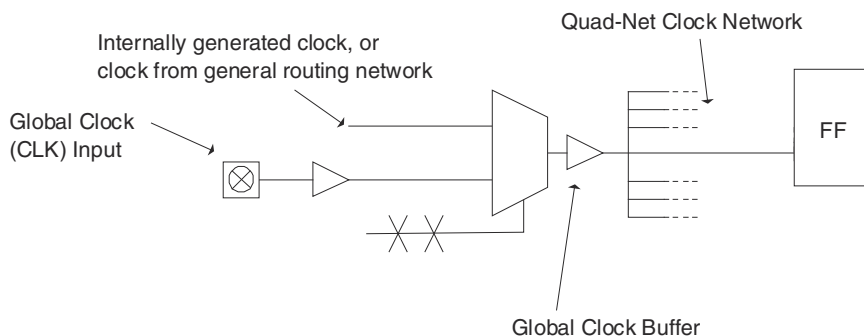


Figure 36: Dual-Port SRAM Cell

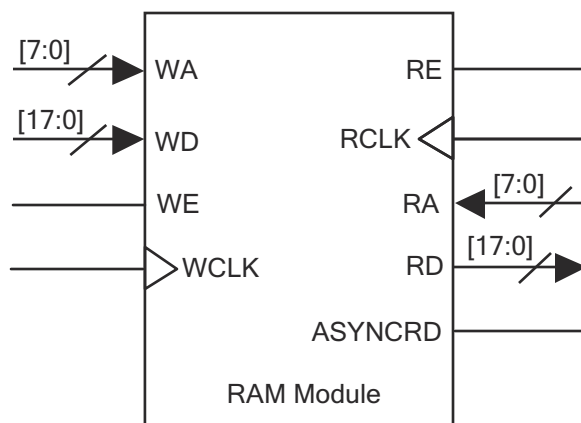


Table 22: RAM Cell Synchronous Write Timing

Symbol	Parameter	Value	
		Min	Max
RAM Cell Synchronous Write Timing			
t_{SWA}	WA setup time to WCLK: time the WRITE ADDRESS must be stable before the active edge of the WRITE CLOCK	0.47 ns	-
t_{HWA}	WA hold time to WCLK: time the WRITE ADDRESS must be stable after the active edge of the WRITE CLOCK	0 ns	-
t_{SWD}	WD setup time to WCLK: time the WRITE DATA must be stable before the active edge of the WRITE CLOCK	0.48 ns	-
t_{HWD}	WD hold time to WCLK: time the WRITE DATA must be stable after the active edge of the WRITE CLOCK	0 ns	-
t_{SWE}	WE setup time to WCLK: time the WRITE ENABLE must be stable before the active edge of the WRITE CLOCK	0 ns	-
t_{HWE}	WE hold time to WCLK: time the WRITE ENABLE must be stable after the active edge of the WRITE CLOCK	0 ns	-
t_{WCRD}	WCLK to RD (WA = RA): time between the active WRITE CLOCK edge and the time when the data is available at RD	-	3.79 ns

Figure 37: RAM Cell Synchronous Write Timing

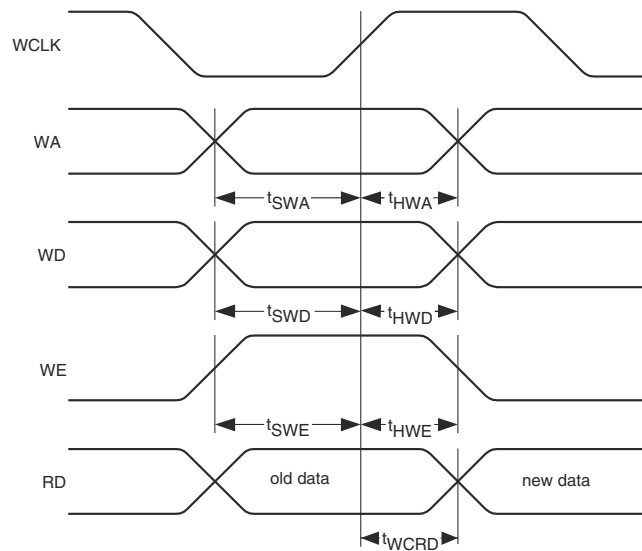


Table 23: RAM Cell Synchronous and Asynchronous Read Timing

Symbol	Parameter	Value	
		Min	Max
RAM Cell Synchronous Read Timing			
t_{SRA}	RA setup time to RCLK: time the READ ADDRESS must be stable before the active edge of the READ CLOCK	0.43 ns	-
t_{HRA}	RA hold time to RCLK: time the READ ADDRESS must be stable after the active edge of the READ CLOCK	0 ns	-
t_{SRE}	RE setup time to WCLK: time the READ ENABLE must be stable before the active edge of the READ CLOCK	0.21 ns	-
t_{HRE}	RE hold time to WCLK: time the READ ENABLE must be stable after the active edge of the READ CLOCK	0 ns	-
t_{RCRD}	RCLK to RD: time between the active READ CLOCK edge and the time when the data is available at RD	-	2.25 ns
RAM Cell Asynchronous Read Timing			
t_{PDRD}	RA to RD: time between when the READ ADDRESS is input and when the DATA is output	-	1.99 ns

Figure 38: RAM Cell Synchronous and Asynchronous Read Timing

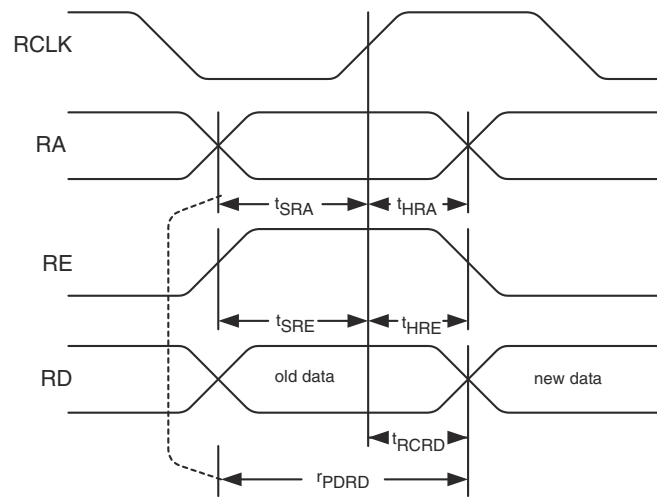


Figure 39: Eclipse II I/O Cell Output Path

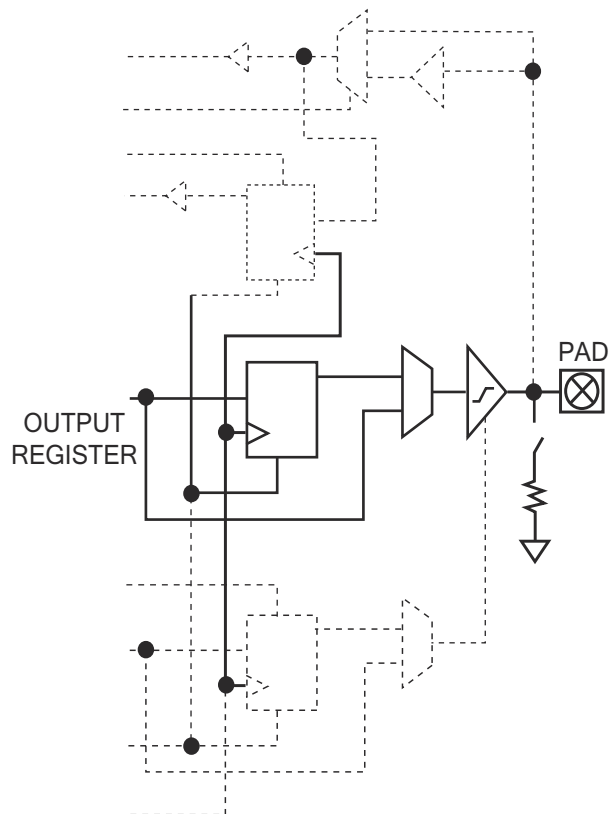


Figure 40: Eclipse II I/O Cell Output Enable Timing

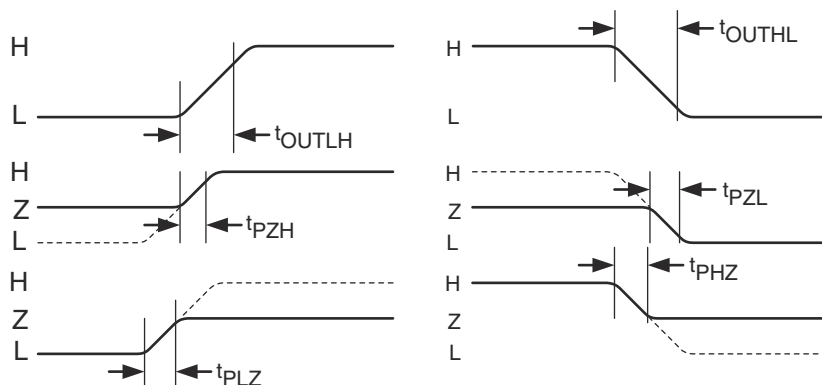


Table 24: Eclipse II I/O Cell Output Timing

Symbol	Parameter	Value (ns)	
		Slow Slew Max	Fast Slew Max
Output Register Cell Only			
t_{OUTLH}	Output Delay low to high (90% of H)	4.0	2.95
t_{OUTHL}	Output Delay high to low (10% of L)	3.5	2.49
t_{PZH}	Output Delay tri-state to high (90% of H)	4.96	2.93
t_{PZL}	Output Delay tri-state to low (10% of L)	4.87	2.84
t_{PHZ}	Output Delay high to tri-state	5.8	3.62
t_{PLZ}	Output Delay low to tri-state	5.58	3.4
t_{COP}	Clock-to-out delay (does not include clock tree delays)	5.49	3.3

Table 25: Output Slew Rates @ VCCIO = 3.3 V, T = 25° C

	Fast Slew	Slow Slew
Rising Edge	2.8 V/ns	1.0 V/ns
Falling Edge	2.9 V/ns	1.0 V/ns

Table 26: Output Slew Rates @ VCCIO = 2.5 V, T = 25° C

	Fast Slew	Slow Slew
Rising Edge	1.7 V/ns	0.6 V/ns
Falling Edge	1.9 V/ns	0.6 V/ns

Table 27: Output Slew Rates @ VCCIO = 1.8 V, T = 25° C

	Fast Slew	Slow Slew
Rising Edge	1.0 V/ns	0.5 V/ns
Falling Edge	1.1 V/ns	0.5 V/ns

Figure 41: Eclipse II I/O Cell Input Path

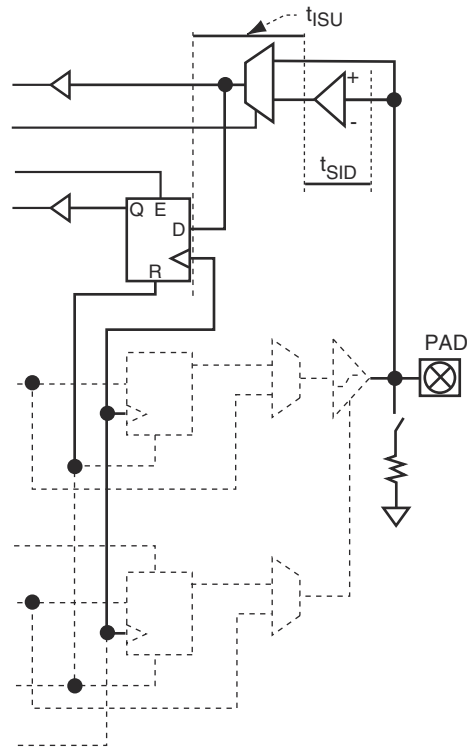


Figure 42: Eclipse II Input Register Cell Timing

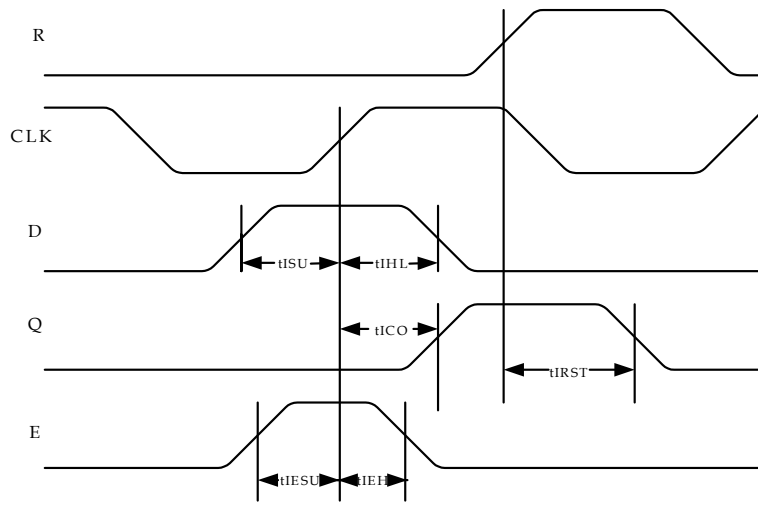


Table 28: I/O Input Register Cell Timing

Symbol	Parameter	Value	
		Min	Max
t_{ISU}	Input register setup time: time the synchronous input of the flip-flop must be stable before the active clock edge	2.15 ns	-
t_{IHL}	Input register hold time: time the synchronous input of the flip-flop must be stable after the active clock edge	0 ns	-
t_{ICO}	Input register clock-to-out: time taken by the flip-flop to output after the active clock edge	-	0.3 ns
t_{IRST}	Input register reset delay: time between when the flip-flop is “reset”(low) and when the output is consequently “reset” (low)	-	0.82 ns
t_{IESU}	Input register clock enable setup time: time “enable” must be stable before the active clock edge	0.4 ns	-
t_{IEH}	Input register clock enable hold time: time “enable” must be stable after the active clock edge	0 ns	-

Table 29: I/O Input Buffer Delays

Symbol	Parameter	Value	
		Min	Max
	To get the total input delay add this delay to t_{ISU}		
t_{SID} (LVTTTL)	LVTTTL input delay: Low Voltage TTL for 3.3 V applications	-	0.82 ns
t_{SID} (LVCMOS2)	LVCMOS2 input delay: Low Voltage CMOS for 2.5 V and lower applications	-	0.82 ns
t_{SID} (LVCMOS18)	LVCMOS18 input delay: Low Voltage CMOS for 1.8 V applications	-	-
t_{SID} (GTL+)	GTL+ input delay: Gunning Transceiver Logic	-	0.94 ns
t_{SID} (SSTL3)	SSTL3 input delay: Stub Series Terminated Logic for 3.3 V	-	0.94 ns
t_{SID} (SSTL2)	SSTL2 input delay: Stub Series Terminated Logic for 2.5 V	-	0.94 ns
t_{SID} (PCI)	PCI input delay: Peripheral Component Interconnect for 3.3 V	-	0.82 ns

Package Thermal Characteristics

Thermal Resistance Equations:

$$\theta_{JC} = (T_J - T_C) / P$$

$$\theta_{JA} = (T_J - T_A) / P$$

$$P_{MAX} = (T_{JMAX} - T_{AMAX}) / \theta_{JA}$$

Parameter Description:

θ_{JC} : Junction-to-case thermal resistance

θ_{JA} : Junction-to-ambient thermal resistance

T_J : Junction temperature

T_A : Ambient temperature

P: Power dissipated by the device while operating

P_{MAX} : The maximum power dissipation for the device

T_{JMAX} : Maximum junction temperature

T_{AMAX} : Maximum ambient temperature

NOTE: Maximum junction temperature (T_{JMAX}) is 125°C. To calculate the maximum power dissipation for a device package look up θ_{JA} from **Table 30**, pick an appropriate T_{AMAX} and use:

$$P_{MAX} = (125^\circ\text{C} - T_{AMAX}) / \theta_{JA}$$

Table 30: Package Thermal Characteristics

Device	Package Description			θ_{JA} (°C/W)		
	Package Code	Package Type	Pin Count	0 LFM	200 LFM	400 LFM
QL8325 QL6325E	PS	PBGA	484	26.6	24.1	21.8
	PT	LFBGA	280	34	31.6	29.9
	PQ	PQFP	208	32	28	26.5
QL8250 QL6250E	PS	PBGA	484	26.6	24.1	21.8
	PT	LFBGA	280	34	31.6	29.9
	PQ	PQFP	208	32	28	26.5
QL8150	PT	LFBGA	280	34	31.6	29.9
	PQ	PQFP	208	43.6	41	39
	PT	TFBGA	196	40	38	35.2
	PU	TFBGA	196	40	34	33
	PF	TQFP	144	37	36	34
QL8050	PT	TFBGA	196	54	51.8	48
	PF	TQFP	144	41	39	37
	PU	TFBGA	101	59	52	50
	PV	VQFP	100	43	41.3	38.8
QL8025	PT	TFBGA	196	54	51.8	48
	PF	TQFP	144	41	39	37
	PV	VQFP	100	43	41.3	38.8

Power vs. Operating Frequency

The basic power equation which best models power consumption is given below:

$$P_{TOTAL} = 0.350 + f[0.0031 \eta_{LC} + 0.0948 \eta_{CKBF} + 0.01 \eta_{CLBF} + 0.0263 \eta_{CKLD} + 0.543 \eta_{RAM} + 0.20 \eta_{PLL} + 0.0035 \eta_{INP} + 0.0257 \eta_{OUTP}] \text{ (mW)}$$

Where:

η_{LC} is the total number of logic cells in the design

η_{CKBF} = # of clock buffers

η_{CLBF} = # of column clock buffers

η_{CKLD} = # of loads connected to the column clock buffers

η_{RAM} = # of RAM blocks

η_{PLL} = # of PLLs

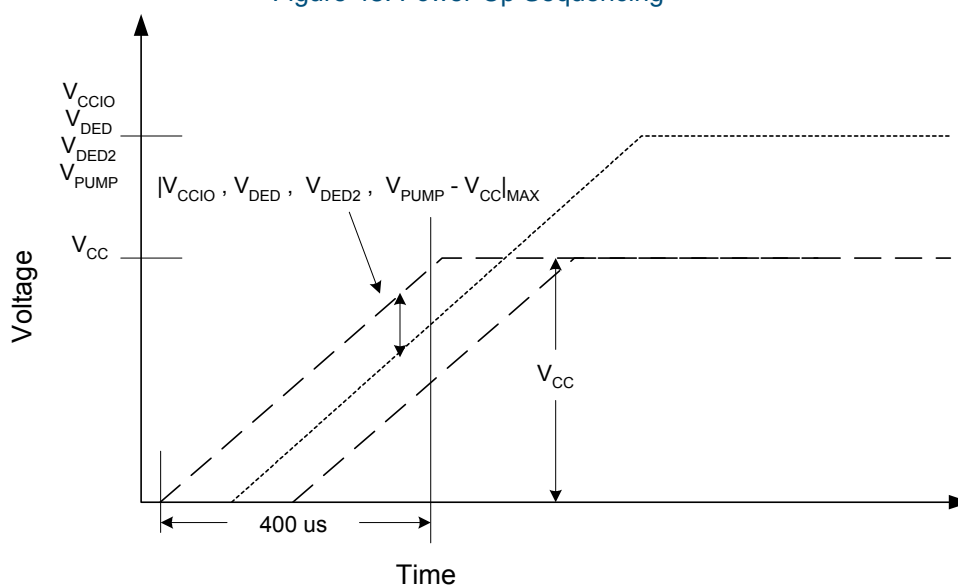
η_{INP} is the number of input pins

η_{OUTP} is the number of output pins

NOTE: To learn more about power consumption, see QuickLogic Application Note 60.

Power-up Sequencing

Figure 43: Power-Up Sequencing



When powering up a device, the $V_{CC}/V_{CCIO}/V_{DEd}/V_{DEd2}$ rails must take 400 μ s or longer to reach the maximum value (refer to **Figure 43**).

NOTE: Ramping V_{CC} , V_{CCIO} , V_{PUMP} , V_{DEd} , or V_{DEd2} faster than 400 μ s can cause the device to behave improperly.

For users with a limited power budget, ensure V_{CCIO} , V_{DEd} , V_{DEd2} , and V_{PUMP} are within 500 mV of V_{CC} when ramping up the power supplies.

Pin Descriptions

Table 31: Pin Descriptions

Pin	Direction	Function	Description
JTAG Pin Descriptions			
TDI/RSI	I	Test Data In for JTAG/RAM init. Serial Data In	Hold HIGH during normal operation. Connects to serial PROM data in for RAM initialization. Connect to VDED2 if unused
TRSTB/RRO	I/O	Active low Reset for JTAG/RAM init. reset out	Hold LOW during normal operation. Connects to serial PROM reset for RAM initialization. Connect to GND if unused
TMS	I	Test Mode Select for JTAG	Hold HIGH during normal operation. Connect to VDED2 if not used for JTAG
TCK	I	Test Clock for JTAG	Hold HIGH or LOW during normal operation. Connect to VDED2 or GND if not used for JTAG
TDO/RCO	O	Test data out for JTAG/RAM init. clock out	Connect to serial PROM clock for RAM initialization. Must be left unconnected if not used for JTAG or RAM initialization. The output voltage drive is specified by VDED.
Dedicated Pin Descriptions			
CLK	I	Global clock network pin	Low skew global clock. This pin provides access to a dedicated, distributed network capable of driving the CLOCK, SET, RESET, F1, and A2 inputs to the Logic Cell, READ, and WRITE CLOCKS, Read and Write Enables of the Embedded RAM Blocks, CLOCK of the ECUs, and Output Enables of the I/Os. The voltage tolerance of this pin is specified by VDED. The voltage tolerance of the CLK pins in the PU101 package are specified by VCCIO(B).
I/O(A)	I/O	Input/Output pin	The I/O pin is a bi-directional pin, configurable to either an input-only, output-only, or bi-directional pin. The A inside the parenthesis means that the I/O is located in Bank A. If an I/O is not used, SpDE (QuickWorks Tool) provides the option of tying that pin to GND, VCC, or TriState.
VCC	I	Power supply pin	Connect to 1.8 V supply.
VCCIO(A)	I	Input voltage tolerance pin	This pin provides the flexibility to interface the device with either a 3.3 V, 2.5 V, or 1.8 V device. The A inside the parenthesis means that VCCIO is located in BANK A. Every I/O pin in Bank A will be tolerant of VCCIO input signals and will drive VCCIO level output signals. This pin must be connected to either 3.3 V, 2.5 V, or 1.8 V. VCCIO powers the the PLLOUT pins.
GND	I	Ground pin	Connect to ground.
PLLIN	I	PLL clock input	Clock input for PLL. The voltage tolerance of this pin is specified by VDED.
DEDCLK	I	Dedicated clock pin	Very low skew global clock. This pin provides access to a dedicated, distributed clock network capable of driving the CLOCK inputs of all sequential elements of the device (e.g., RAM, Flip Flops). The voltage tolerance of this pin is specified by VDED.
GNDPLL	I	Ground pin for PLL	Connect to GND.

Table 31: Pin Descriptions (Continued)

Pin	Direction	Function	Description
INREF(A)	I	Differential reference voltage	The INREF is the reference voltage pin for GTL+, SSTL2, and STTL3 standards. Follow the recommendations provided in Table 14 for the appropriate standard. The A inside the parenthesis means that INREF is located in BANK A. This pin should be tied to GND if voltage referenced standards are not used.
PLLOUT	O	PLL output pin	Dedicated PLL output pin. Must be left unconnected if PLL is powered up and not held in reset, since PLLOUT will be driving the PLL-derived clock. May be left unconnected if PLL is held in reset or not powered up. PLLOUT pin is driven by VCCIO. For a list of each PLLOUT pin and the VCCIO pin that powers it see Table 32 .
IOCTRL(A)	I	Highdrive input	This pin provides fast RESET, SET, CLOCK, and ENABLE access to the I/O cell flip-flops, providing fast clock-to-out and fast I/O response times. This pin can also double as a high-drive pin to the internal logic cells. The A inside the parenthesis means that IOCTRL is located in Bank A. There is an internal pulldown resistor to GND on this pin. This pin should be tied to GND if it is not used. For backwards compatibility with Eclipse and EclipsePlus, it can be tied to VDED or GND. If tied to VDED, it will draw no more than 20 μ A per IOCTRL pin due to current through the pulldown resistor. The voltage tolerance of this pin is specified by VDED. Note that the 208 PQFP package has no I/O control pins.
VPUMP	I	Charge Pump Disable	This pin disables the internal charge pump for lower static power consumption. To disable the charge pump, connect VPUMP to 3.3 V. If the Disable Charge Pump feature is not used, connect VPUMP to GND. For backwards compatibility with Eclipse and EclipsePlus devices, connect VPUMP to GND.
VDED	I	Voltage tolerance for clocks, TDO JTAG output, and IOCTRL	This pin specifies the input voltage tolerance for CLK, DEDCLK, PLLIN, and IOCTRL dedicated input pins, as well as the output voltage drive TDO JTAG pins. If the PLLs are used, VDED must be the same as VCCPLL. The legal range for VDED is between 1.71 V and 3.6 V. For backwards compatibility with Eclipse and EclipsePlus devices, connect VDED to 2.5 V.

Table 31: Pin Descriptions (Continued)

Pin	Direction	Function	Description
VDED2	I	Voltage tolerance for JTAG pins (TDI, TMS, TCK, and TRSTB)	These pins specify the input voltage tolerance for the JTAG input pins. The legal range for VDED2 is between 1.71 V and 3.6 V. These do not specify output voltage of the JTAG output, TDO. Refer to the VDED pin section for specifying the JTAG output voltage.
VCCPLL	I	Power Supply pin for PLL	Connect to 2.5 V or 3.3 V supply. For backwards compatibility with Eclipse and EclipsePlus devices, connect to 2.5 V. To minimize static power consumption when designs do not utilize the PLLs, you may connect VCCPLL to GND. If VCCPLL is grounded, the PLL is disabled.
PLL_RESET	I	PLL reset pin	If PLL_RESET is asserted, then CLKNET_OUT and PLLPAD_OUT are reset to 0. This signal must be asserted and then released in order for the LOCK_DETECT to work. If a PLL module is not used, then the associated PLLRST<x> must be connected to VDED.

Table 32: PLLOUT Pin Supply Voltage

PLLOUT	VCCIO
PLLOUT(0)	VCCIO(E)
PLLOUT(1)	VCCIO(B)
PLLOUT(2)	VCCIO(A)
PLLOUT(3)	VCCIO(F)

Figure 44: QL8325 and QL8250 I/O Banks with Relevant Pins

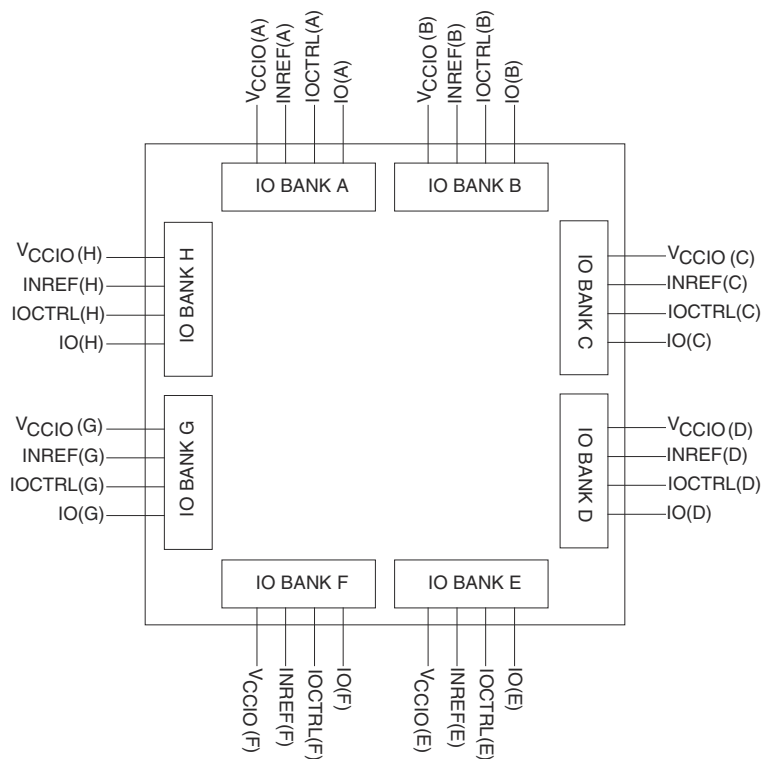
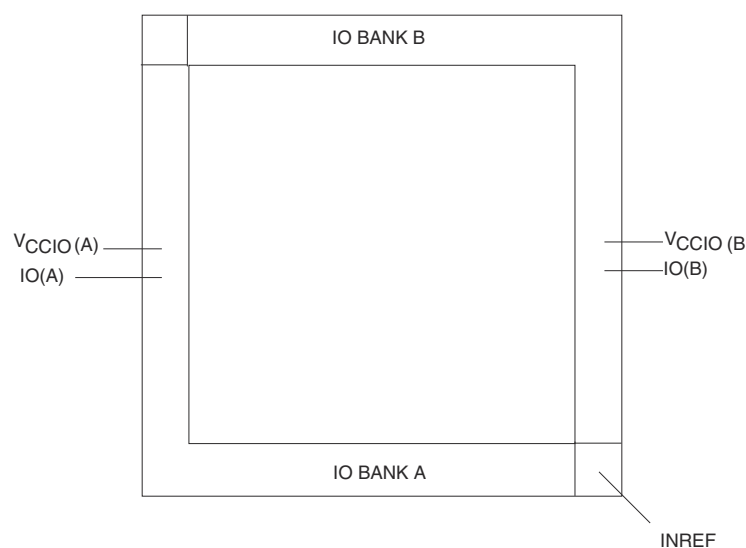


Figure 45: QL8150, QL8050, and QL8025 I/O Banks with Relevant Pins



Recommended Unused Pin Terminations for Eclipse II Devices

All unused, general purpose I/O pins can be tied to VCC, GND, or HIZ (high impedance) internally using the Configuration Editor. This option is given in the bottom-right corner of the placement window. To use the Placement Editor, choose **Constraint > Fix Placement** in the **Option** pull-down menu of SpDE.

The rest of the pins should be terminated at the board level in the manner presented in **Table 33**.

Table 33: Recommended Unused Pin Terminations

Signal Name	Recommended Termination
PLLOUT<x> ^a	In earlier versions, the recommendation for unused PLLOUT pins was that they be connected to VCC or GND. This was acceptable for Rev. D (and earlier) silicon, including all 0.25 μ m devices. For Rev. G (and later) silicon this is not correct. Unused PLLOUT pins should be left unconnected. Used PLLOUT pins will normally be connected to inputs, but can also be left unconnected. For the truth table of PLLOUT connections, refer to Table 34 .
IOCTRL<y> ^b	There is an internal pulldown resistor to GND on this pin. This pin should be tied to GND if it is not used. For backwards compatibility with Eclipse, it can be tied to VDED or GND. If tied to VDED, it will draw no more than 20 μ A per IOCTRL pin due to current through the pulldown resistor.
CLK/PLLIN<x>	Any unused clock pins should be connected to VDED or GND.
PLL_RST<x>	If a PLL module is not used, then the associated PLL_RST<x> must be connected to VDED or GND. If VCCPLL is grounded, then PLL_RST must be grounded also. If VCCPLL is driven by 2.5 V or 3.3 V, PLL_RST must be driven by the same voltage.
INREF<y>	If an I/O bank does not require the use of the INREF signal the pin should be connected to GND.

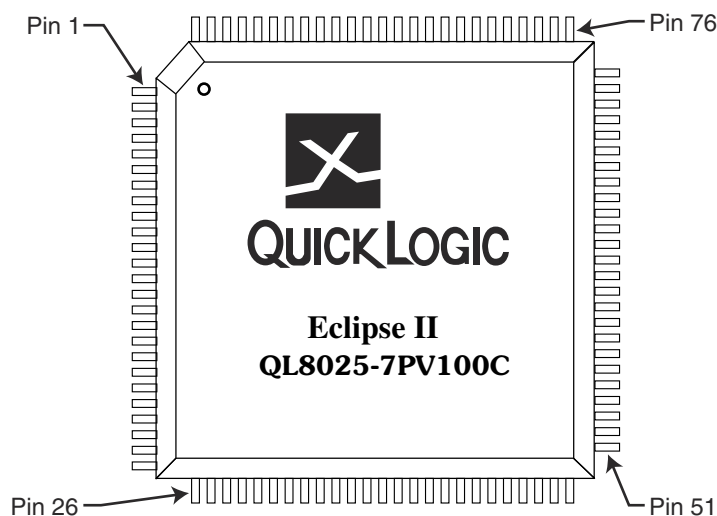
a. x represents a number.

b. y represents an alphabetical character.

Table 34: Recommended PLLOUT Terminations Truth Table

PLL_RESET	Recommended PLLOUT Termination
0	Must be left unconnected.
1	May be left unconnected, or connected to GND. Must not be connected to VCC.

QL8025 - 100 VQFP Pinout Diagram



QL8025 - 100 VQFP Pinout Table

Table 35: QL8025 - 100 VQFP Pinout Table

Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	GND	21	I/O(A)	41	VCC	61	I/O(B)	81	I/O(B)
2	GND	22	I/O(A)	42	I/O(A)	62	I/O(B)	82	I/O(B)
3	I/O(A)	23	I/O(A)	43	I/O(A)	63	CLK(2)	83	I/O(B)
4	I/O(A)	24	I/O(A)	44	I/O(A)	64	CLK(3)	84	VCC
5	I/O(A)	25	TDO	45	I/O(A)	65	VCC	85	I/O(B)
6	VCC	26	I/O(A)	46	I/O(A)	66	CLK(4)	86	I/O(B)
7	I/O(A)	27	GND	47	VCCIO(A)	67	TMS	87	VCC
8	I/O(A)	28	I/O(A)	48	I/O(A)	68	I/O(B)	88	TCK
9	VCCIO(A)	29	VCCIO(A)	49	VPUMP	69	GND	89	VDED2
10	I/O(A)	30	I/O(A)	50	I/O(A)	70	I/O(B)	90	I/O(B)
11	TDI	31	I/O(A)	51	GND	71	I/O(B)	91	GND
12	CLK(0)	32	I/O(A)	52	I/O(B)	72	I/O(B)	92	I/O(B)
13	CLK(1)	33	I/O(A)	53	I/O(B)	73	I/O(B)	93	I/O(B)
14	VCC	34	I/O(A)	54	I/O(B)	74	I/O(B)	94	I/O(B)
15	I/O(A)	35	VCC	55	VCC	75	I/O(B)	95	I/O(B)
16	VDED	36	TRSTB	56	I/O(B)	76	GND	96	I/O(B)
17	I/O(A)	37	VDED2	57	INREF	77	I/O(B)	97	I/O(B)
18	GND	38	I/O(A)	58	I/O(B)	78	VCCIO(B)	98	VCCIO(B)
19	I/O(A)	39	I/O(A)	59	I/O(B)	79	I/O(B)	99	I/O(B)
20	I/O(A)	40	GND	60	VCCIO(B)	80	I/O(B)	100	I/O(B)

QL8025 - 144 TQFP Pinout Diagram

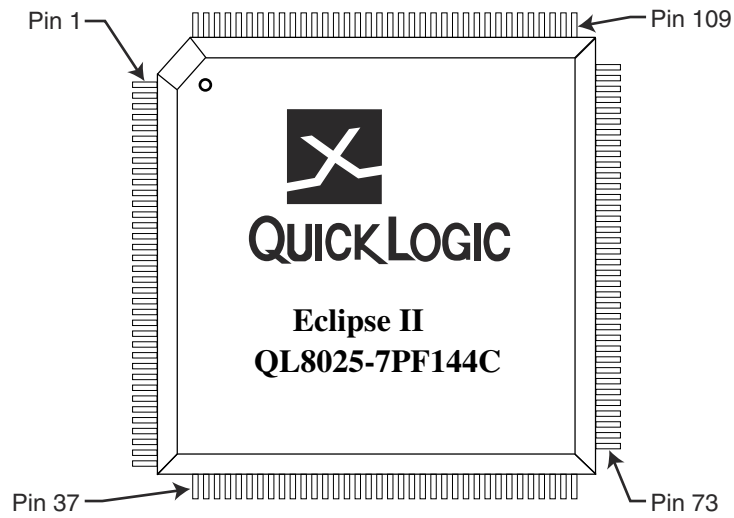


Figure 46: Top View of 144 Pin TQFP

QL8025 - 144 TQFP Pinout Table

Table 36: QL8025 - 144 TQFP Pinout Table

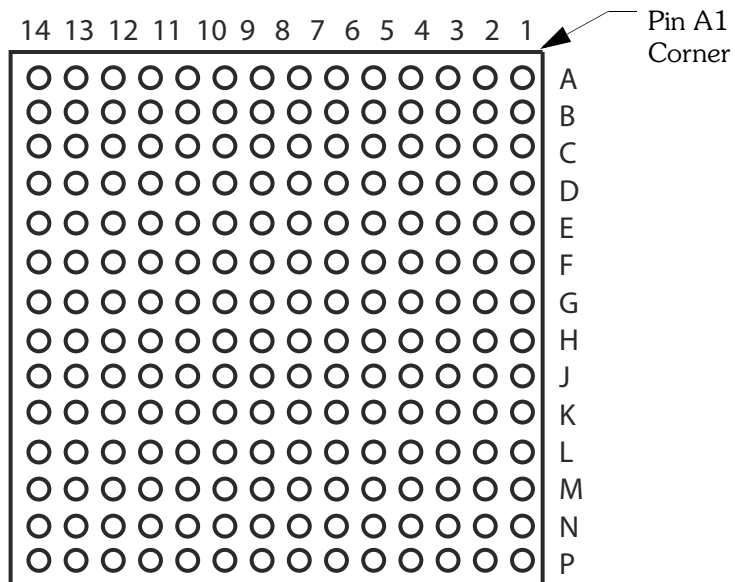
Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	GND	37	IO(A)	73	IO(A)	109	GND
2	GND	38	GND	74	IO(B)	110	IO(B)
3	IO(A)	39	IO(A)	75	GND	111	VCCIO(B)
4	IO(A)	40	VCCIO(A)	76	IO(B)	112	IO(B)
5	IO(A)	41	IO(A)	77	IO(B)	113	IO(B)
6	IO(A)	42	IO(A)	78	IO(B)	114	IO(B)
7	VCC	43	IO(A)	79	VCC	115	IO(B)
8	IO(A)	44	IO(A)	80	IO(B)	116	IO(B)
9	IO(A)	45	IO(A)	81	IO(B)	117	NC
10	IO(A)	46	IO(A)	82	INREF	118	IO(B)
11	NC	47	IO(A)	83	IO(B)	119	IO(B)
12	IO(A)	48	IO(A)	84	IO(B)	120	VCC
13	VCCIO(A)	49	VCCIO(A)	85	IO(B)	121	IO(B)
14	IO(A)	50	IO(A)	86	VCCIO(B)	122	VCCIO(B)
15	TDI	51	NC	87	IO(B)	123	IO(B)
16	CLK(0)	52	VCC	88	NC	124	IO(B)
17	CLK(1)	53	TRSTB	89	IO(B)	125	VCC
18	VCC	54	VDED2	90	CLK(2)	126	TCK
19	IO(A)	55	IO(A)	91	CLK(3)	127	VDED2
20	VDED	56	IO(A)	92	VCC	128	IO(B)
21	IO(A)	57	IO(A)	93	CLK(4)	129	IO(B)
22	IO(A)	58	GND	94	TMS	130	GND
23	GND	59	IO(A)	95	IO(B)	131	IO(B)
24	VCCIO(A)	60	VCC	96	GND	132	IO(B)
25	IO(A)	61	IO(A)	97	VCCIO(B)	133	IO(B)
26	IO(A)	62	IO(A)	98	IO(B)	134	IO(B)
27	NC	63	IO(A)	99	IO(B)	135	IO(B)
28	IO(A)	64	IO(A)	100	IO(B)	136	IO(B)
29	IO(A)	65	NC	101	IO(B)	137	NC
30	IO(A)	66	IO(A)	102	NC	138	IO(B)
31	IO(A)	67	IO(A)	103	IO(B)	139	IO(B)
32	IO(A)	68	IO(A)	104	IO(B)	140	IO(B)
33	IO(A)	69	VCCIO(A)	105	IO(B)	141	VCCIO(B)
34	TDO	70	IO(A)	106	IO(B)	142	IO(B)
35	GND	71	VPUMP	107	GND	143	IO(B)
36	IO(A)	72	IO(A)	108	IO(B)	144	IO(B)

QL8025 - 196 TFBGA Pinout Diagram

Top



Bottom

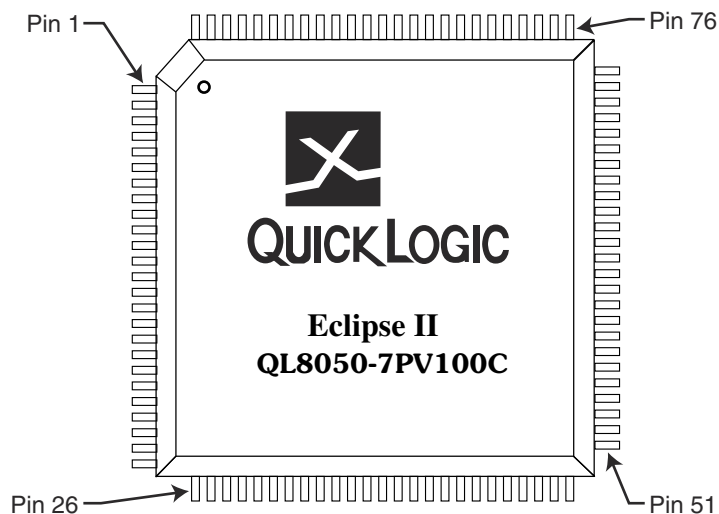


QL8025 - 196 TFBGA Pinout Table

Table 37: QL8025 - 196 TFBGA Pinout Table

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	IO(B)	C13	NC	F11	IO(A)	J9	GND	M7	VCC
A2	IO(B)	C14	NC	F12	NC	J10	GND	M8	IO(A)
A3	NC	D1	IO(B)	F13	IO(A)	J11	IO(A)	M9	IO(A)
A4	IO(B)	D2	NC	F14	IO(A)	J12	IO(A)	M10	IO(A)
A5	IO(B)	D3	NC	G1	IO(B)	J13	NC	M11	IO(A)
A6	NC	D4	IO(B)	G2	TCK	J14	NC	M12	IO(A)
A7	CLK(4)	D5	IO(B)	G3	NC	K1	NC	M13	NC
A8	CLK(2)	D6	VCCIO(B)	G4	VCC	K2	NC	M14	IO(A)
A9	NC	D7	VCCIO(B)	G5	GND	K3	IO(B)	N1	NC
A10	IO(B)	D8	VDED	G6	GND	K4	IO(B)	N2	IO(B)
A11	INREF	D9	VCCIO(B)	G7	GND	K5	VCCIO(B)	N3	IO(A)
A12	IO(B)	D10	IO(B)	G8	GND	K6	VCCIO(A)	N4	IO(A)
A13	IO(B)	D11	NC	G9	GND	K7	GND	N5	IO(A)
A14	IO(B)	D12	VPUMP	G10	GND	K8	GND	N6	NC
B1	NC	D13	IO(A)	G11	IO(A)	K9	VCCIO(A)	N7	IO(A)
B2	IO(B)	D14	IO(A)	G12	VCC	K10	VCCIO(A)	N8	IO(A)
B3	IO(B)	E1	IO(B)	G13	IO(A)	K11	NC	N9	IO(A)
B4	NC	E2	IO(B)	G14	IO(A)	K12	IO(A)	N10	NC
B5	IO(B)	E3	IO(B)	H1	NC	K13	IO(A)	N11	NC
B6	TMS	E4	IO(B)	H2	IO(B)	K14	IO(A)	N12	TDO
B7	VCC	E5	VCCIO(B)	H3	VDED2	L1	IO(B)	N13	IO(A)
B8	IO(B)	E6	GND	H4	VCCIO(B)	L2	IO(B)	N14	NC
B9	NC	E7	GND	H5	GND	L3	IO(B)	P1	IO(A)
B10	IO(B)	E8	GND	H6	GND	L4	IO(B)	P2	IO(A)
B11	IO(B)	E9	GND	H7	GND	L5	NC	P3	IO(A)
B12	IO(B)	E10	IO(A)	H8	GND	L6	NC	P4	NC
B13	IO(A)	E11	VCCIO(A)	H9	GND	L7	VCCIO(A)	P5	IO(A)
B14	IO(A)	E12	IO(A)	H10	GND	L8	VDED	P6	CLK(0)
C1	IO(B)	E13	NC	H11	VCCIO(A)	L9	VDED	P7	CLK(1)
C2	IO(B)	E14	VCC	H12	TRSTB	L10	VCCIO(A)	P8	IO(A)
C3	IO(B)	F1	IO(B)	H13	VDED2	L11	VCC	P9	IO(A)
C4	VCC	F2	VCC	H14	VCC	L12	IO(A)	P10	IO(A)
C5	IO(B)	F3	NC	J1	IO(B)	L13	IO(A)	P11	NC
C6	VCC	F4	IO(B)	J2	IO(B)	L14	IO(A)	P12	IO(A)
C7	IO(B)	F5	VCCIO(B)	J3	IO(B)	M1	NC	P13	IO(A)
C8	CLK(3)	F6	GND	J4	VCC	M2	IO(B)	P14	IO(A)
C9	IO(B)	F7	GND	J5	IO(B)	M3	IO(A)		
C10	VCC	F8	GND	J6	GND	M4	GND		
C11	IO(B)	F9	GND	J7	GND	M5	VCC		
C12	IO(A)	F10	IO(A)	J8	GND	M6	TDI		

QL8050 - 100 VQFP Pinout Diagram



QL8050 - 100 VQFP Pinout Table

Table 38: QL8050 - 100 VQFP Pinout Table

Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	GND	21	I/O(A)	41	VCC	61	I/O(B)	81	I/O(B)
2	GND	22	I/O(A)	42	I/O(A)	62	I/O(B)	82	I/O(B)
3	I/O(A)	23	I/O(A)	43	I/O(A)	63	CLK(2)	83	I/O(B)
4	I/O(A)	24	I/O(A)	44	I/O(A)	64	CLK(3)	84	VCC
5	I/O(A)	25	TDO	45	I/O(A)	65	VCC	85	I/O(B)
6	VCC	26	I/O(A)	46	I/O(A)	66	CLK(4)	86	I/O(B)
7	I/O(A)	27	GND	47	VCCIO(A)	67	TMS	87	VCC
8	I/O(A)	28	I/O(A)	48	I/O(A)	68	I/O(B)	88	TCK
9	VCCIO(A)	29	VCCIO(A)	49	VPUMP	69	GND	89	VDED2
10	I/O(A)	30	I/O(A)	50	I/O(A)	70	I/O(B)	90	I/O(B)
11	TDI	31	I/O(A)	51	GND	71	I/O(B)	91	GND
12	CLK(0)	32	I/O(A)	52	I/O(B)	72	I/O(B)	92	I/O(B)
13	CLK(1)	33	I/O(A)	53	I/O(B)	73	I/O(B)	93	I/O(B)
14	VCC	34	I/O(A)	54	I/O(B)	74	I/O(B)	94	I/O(B)
15	I/O(A)	35	VCC	55	VCC	75	I/O(B)	95	I/O(B)
16	VDED	36	TRSTB	56	I/O(B)	76	GND	96	I/O(B)
17	I/O(A)	37	VDED2	57	INREF	77	I/O(B)	97	I/O(B)
18	GND	38	I/O(A)	58	I/O(B)	78	VCCIO(B)	98	VCCIO(B)
19	I/O(A)	39	I/O(A)	59	I/O(B)	79	I/O(B)	99	I/O(B)
20	I/O(A)	40	GND	60	VCCIO(B)	80	I/O(B)	100	I/O(B)

QL8050 - 101 TFBGA Pinout Diagram

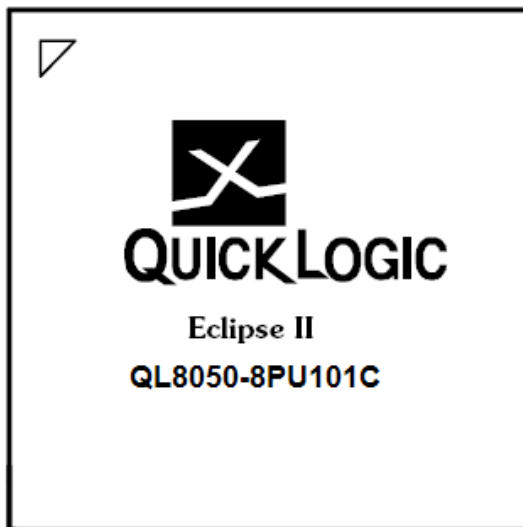


Figure 47: Top View of 101 Pin TFBGA

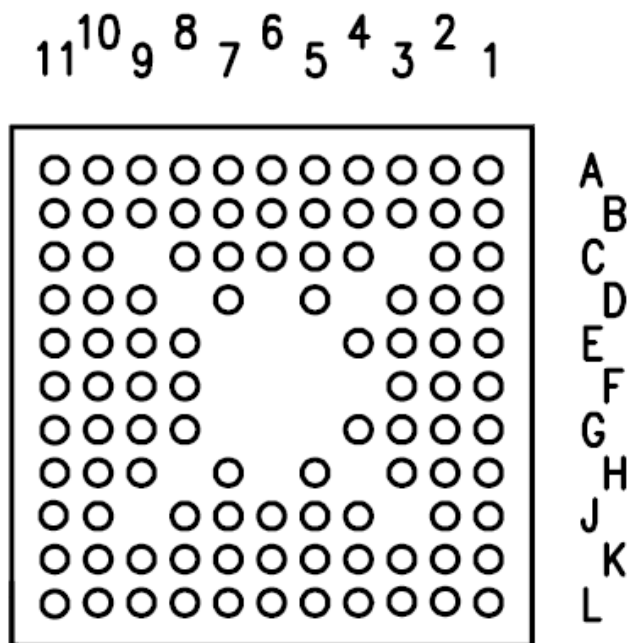


Figure 48: Bottom View of 101 Pin TFBGA

QL8050 - 101 TFBGA Pinout Table

Table 39: QL8050 - 101 TFBGA Pinout Table

Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
A1	I/O(B)	B11	I/O(B)	E4	I/O(B)	H2	I/O(B)	K6	I/O(A)
A2	I/O(B)	C1	I/O(B)	E8	VCC	H3	VCC	K7	I/O(A)
A3	I/O(B)	C2	I/O(B)	E9	I/O(A)	H5	GND	K8	I/O(A)
A4	I/O(B)	C4	I/O(B)	E10	VCCIO(B)	H7	VCC	K9	GND
A5	CLK(4)	C5	I/O(B)	E11	I/O(A)	H9	I/O(A)	K10	I/O(A)
A6	CLK(3)	C6	I/O(B)	F1	I/O(B)	H10	I/O(A)	K11	I/O(A)
A7	CLK(2)	C7	VCC	F2	I/O(B)	H11	I/O(A)	L1	I/O(B)
A8	VCCIO(B)	C8	I/O(B)	F3	VCC	J1	I/O(B)	L2	I/O(B)
A9	I/O(B)	C10	I/O(A)	F8	I/O(A)	J2	I/O(B)	L3	I/O(A)
A10	I/O(B)	C11	VCC	F9	VCCIO(A)	J4	I/O(A)	L4	CLK(0)
A11	I/O(B)	D1	I/O(B)	F10	I/O(A)	J5	VCCIO(A)	L5	CLK(1)
B1	I/O(B)	D2	I/O(B)	F11	GND	J6	I/O(A)	L6	I/O(A)
B2	I/O(B)	D3	I/O(B)	G1	I/O(B)	J7	I/O(A)	L7	I/O(A)
B3	GND	D5	I/O(B)	G2	GND	J8	I/O(A)	L8	I/O(A)
B4	I/O(B)	D7	I/O(B)	G3	GND	J10	I/O(A)	L9	I/O(A)
B5	I/O(B)	D9	VCCIO(B)	G4	VCCIO(B)	J11	I/O(A)	L10	I/O(A)
B6	VCCIO(B)	D10	I/O(B)	G8	VCCIO(A)	K1	I/O(B)	L11	I/O(A)
B7	I/O(B)	D11	I/O(A)	G9	I/O(A)	K2	I/O(B)		
B8	I/O(B)	E1	I/O(B)	G10	I/O(A)	K3	GND		
B9	GND	E2	I/O(B)	G11	I/O(A)	K4	I/O(A)		
B10	VPUMP	E3	I/O(B)	H1	I/O(B)	K5	VCCIO(B)		

NOTE: The voltage tolerance of the CLK pins in the PU101 package are specified by VCCIO(B).

QL8050 - 144 TQFP Pinout Diagram

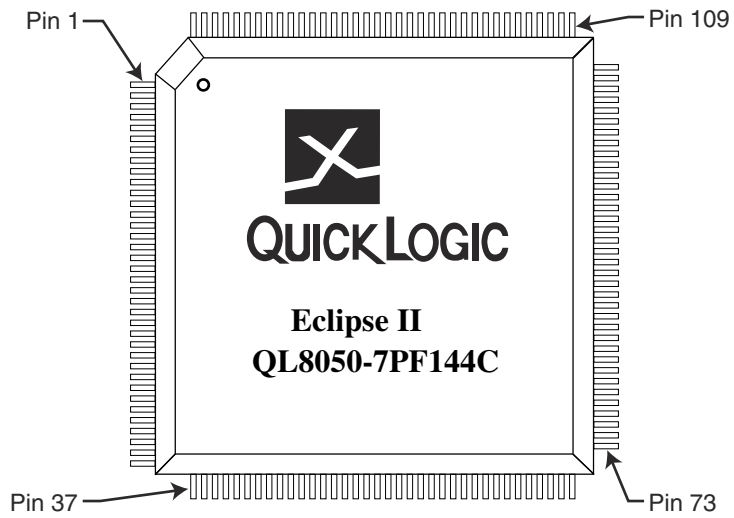


Figure 49: Top View of 144 Pin TQFP

QL8050 - 144 TQFP Pinout Table

Table 40: QL8050 - 144 TQFP Pinout Table

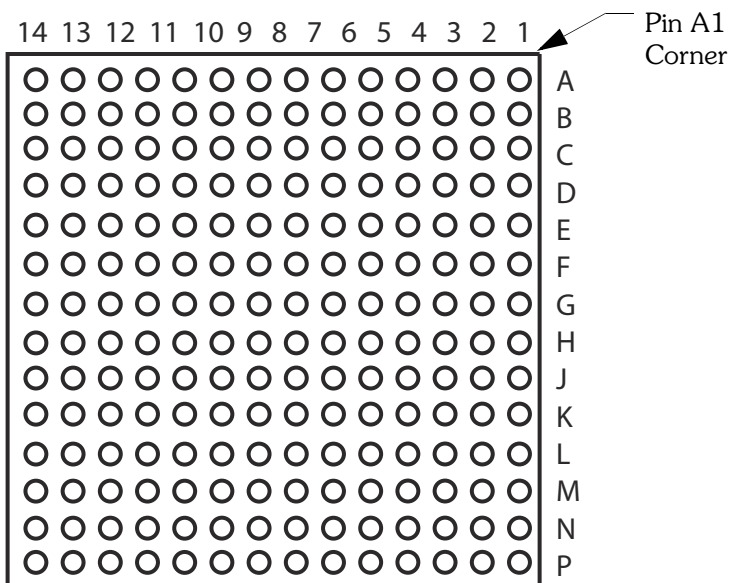
Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	GND	37	IO(A)	73	IO(A)	109	GND
2	GND	38	GND	74	IO(B)	110	IO(B)
3	IO(A)	39	IO(A)	75	GND	111	VCCIO(B)
4	IO(A)	40	VCCIO(A)	76	IO(B)	112	IO(B)
5	IO(A)	41	IO(A)	77	IO(B)	113	IO(B)
6	IO(A)	42	IO(A)	78	IO(B)	114	IO(B)
7	VCC	43	IO(A)	79	VCC	115	IO(B)
8	IO(A)	44	IO(A)	80	IO(B)	116	IO(B)
9	IO(A)	45	IO(A)	81	IO(B)	117	IO(B)
10	IO(A)	46	IO(A)	82	INREF	118	IO(B)
11	IO(A)	47	IO(A)	83	IO(B)	119	IO(B)
12	IO(A)	48	IO(A)	84	IO(B)	120	VCC
13	VCCIO(A)	49	VCCIO(A)	85	IO(B)	121	IO(B)
14	IO(A)	50	IO(A)	86	VCCIO(B)	122	VCCIO(B)
15	TDI	51	IO(A)	87	IO(B)	123	IO(B)
16	CLK(0)	52	VCC	88	IO(B)	124	IO(B)
17	CLK(1)	53	TRSTB	89	IO(B)	125	VCC
18	VCC	54	VDED2	90	CLK(2)	126	TCK
19	IO(A)	55	IO(A)	91	CLK(3)	127	VDED2
20	VDED	56	IO(A)	92	VCC	128	IO(B)
21	IO(A)	57	IO(A)	93	CLK(4)	129	IO(B)
22	IO(A)	58	GND	94	TMS	130	GND
23	GND	59	IO(A)	95	IO(B)	131	IO(B)
24	VCCIO(A)	60	VCC	96	GND	132	IO(B)
25	IO(A)	61	IO(A)	97	VCCIO(B)	133	IO(B)
26	IO(A)	62	IO(A)	98	IO(B)	134	IO(B)
27	IO(A)	63	IO(A)	99	IO(B)	135	IO(B)
28	IO(A)	64	IO(A)	100	IO(B)	136	IO(B)
29	IO(A)	65	IO(A)	101	IO(B)	137	IO(B)
30	IO(A)	66	IO(A)	102	IO(B)	138	IO(B)
31	IO(A)	67	IO(A)	103	IO(B)	139	IO(B)
32	IO(A)	68	IO(A)	104	IO(B)	140	IO(B)
33	IO(A)	69	VCCIO(A)	105	IO(B)	141	VCCIO(B)
34	TDO	70	IO(A)	106	IO(B)	142	IO(B)
35	GND	71	VPUMP	107	GND	143	IO(B)
36	IO(A)	72	IO(A)	108	IO(B)	144	IO(B)

QL8050 - 196 TFBGA Pinout Diagram

Top



Bottom



QL8050 - 196 TFBGA Pinout Table

Table 41: QL8050 - 196 TFBGA Pinout Table

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	IO(B)	C13	IO(A)	F11	IO(A)	J9	GND	M7	VCC
A2	IO(B)	C14	IO(A)	F12	IO(A)	J10	GND	M8	IO(A)
A3	IO(B)	D1	IO(B)	F13	IO(A)	J11	IO(A)	M9	IO(A)
A4	IO(B)	D2	IO(B)	F14	IO(A)	J12	IO(A)	M10	IO(A)
A5	IO(B)	D3	IO(B)	G1	IO(B)	J13	IO(A)	M11	IO(A)
A6	IO(B)	D4	IO(B)	G2	TCK	J14	IO(A)	M12	IO(A)
A7	CLK(4)	D5	IO(B)	G3	IO(B)	K1	IO(B)	M13	IO(A)
A8	CLK(2)	D6	VCCIO(B)	G4	VCC	K2	IO(B)	M14	IO(A)
A9	IO(B)	D7	VCCIO(B)	G5	GND	K3	IO(B)	N1	IO(B)
A10	IO(B)	D8	VDED	G6	GND	K4	IO(B)	N2	IO(B)
A11	INREF	D9	VCCIO(B)	G7	GND	K5	VCCIO(B)	N3	IO(A)
A12	IO(B)	D10	IO(B)	G8	GND	K6	VCCIO(A)	N4	IO(A)
A13	IO(B)	D11	IO(B)	G9	GND	K7	GND	N5	IO(A)
A14	IO(B)	D12	VPUMP	G10	GND	K8	GND	N6	IO(A)
B1	IO(B)	D13	IO(A)	G11	IO(A)	K9	VCCIO(A)	N7	IO(A)
B2	IO(B)	D14	IO(A)	G12	VCC	K10	VCCIO(A)	N8	IO(A)
B3	IO(B)	E1	IO(B)	G13	IO(A)	K11	IO(A)	N9	IO(A)
B4	IO(B)	E2	IO(B)	G14	IO(A)	K12	IO(A)	N10	IO(A)
B5	IO(B)	E3	IO(B)	H1	IO(B)	K13	IO(A)	N11	IO(A)
B6	TMS	E4	IO(B)	H2	IO(B)	K14	IO(A)	N12	TDO
B7	VCC	E5	VCCIO(B)	H3	VDED2	L1	IO(B)	N13	IO(A)
B8	IO(B)	E6	GND	H4	VCCIO(B)	L2	IO(B)	N14	IO(A)
B9	IO(B)	E7	GND	H5	GND	L3	IO(B)	P1	IO(A)
B10	IO(B)	E8	GND	H6	GND	L4	IO(B)	P2	IO(A)
B11	IO(B)	E9	GND	H7	GND	L5	IO(A)	P3	IO(A)
B12	IO(B)	E10	IO(A)	H8	GND	L6	IO(A)	P4	IO(A)
B13	IO(A)	E11	VCCIO(A)	H9	GND	L7	VCCIO(A)	P5	IO(A)
B14	IO(A)	E12	IO(A)	H10	GND	L8	VDED	P6	CLK(0)
C1	IO(B)	E13	IO(A)	H11	VCCIO(A)	L9	VDED	P7	CLK(1)
C2	IO(B)	E14	VCC	H12	TRSTB	L10	VCCIO(A)	P8	IO(A)
C3	IO(B)	F1	IO(B)	H13	VDED2	L11	VCC	P9	IO(A)
C4	VCC	F2	VCC	H14	VCC	L12	IO(A)	P10	IO(A)
C5	IO(B)	F3	IO(B)	J1	IO(B)	L13	IO(A)	P11	IO(A)
C6	VCC	F4	IO(B)	J2	IO(B)	L14	IO(A)	P12	IO(A)
C7	IO(B)	F5	VCCIO(B)	J3	IO(B)	M1	IO(B)	P13	IO(A)
C8	CLK(3)	F6	GND	J4	VCC	M2	IO(B)	P14	IO(A)
C9	IO(B)	F7	GND	J5	IO(B)	M3	IO(A)		
C10	VCC	F8	GND	J6	GND	M4	GND		
C11	IO(B)	F9	GND	J7	GND	M5	VCC		
C12	IO(A)	F10	IO(A)	J8	GND	M6	TDI		

QL8150 - 144 TQFP Pinout Diagram

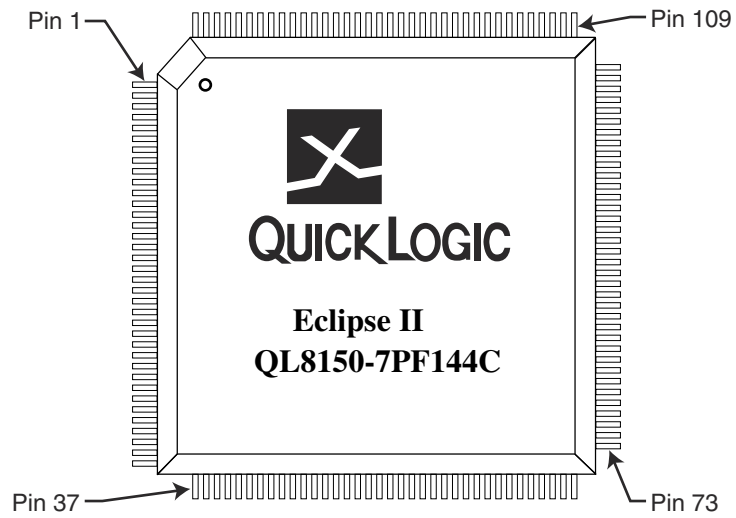


Figure 50: Top View of 144 Pin TQFP

QL8150 - 144 TQFP Pinout Table

Table 42: QL8150 - 144 TQFP Pinout Table

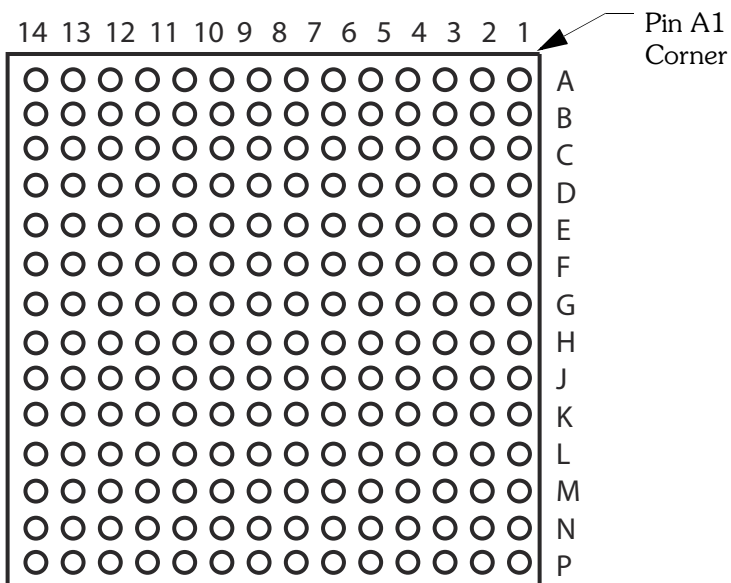
Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	GND	37	IO(A)	73	IO(A)	109	GND
2	GND	38	GND	74	IO(B)	110	IO(B)
3	IO(A)	39	IO(A)	75	GND	111	VCCIO(B)
4	IO(A)	40	VCCIO(A)	76	IO(B)	112	IO(B)
5	IO(A)	41	IO(A)	77	IO(B)	113	IO(B)
6	IO(A)	42	IO(A)	78	IO(B)	114	IO(B)
7	VCC	43	IO(A)	79	VCC	115	IO(B)
8	IO(A)	44	IO(A)	80	IO(B)	116	IO(B)
9	IO(A)	45	IO(A)	81	IO(B)	117	IO(B)
10	IO(A)	46	IO(A)	82	INREF	118	IO(B)
11	IO(A)	47	IO(A)	83	IO(B)	119	IO(B)
12	IO(A)	48	IO(A)	84	IO(B)	120	VCC
13	VCCIO(A)	49	VCCIO(A)	85	IO(B)	121	IO(B)
14	IO(A)	50	IO(A)	86	VCCIO(B)	122	VCCIO(B)
15	TDI	51	IO(A)	87	IO(B)	123	IO(B)
16	CLK(0)	52	VCC	88	IO(B)	124	IO(B)
17	CLK(1)	53	TRSTB	89	IO(B)	125	VCC
18	VCC	54	VDED2	90	CLK(2)	126	TCK
19	IO(A)	55	IO(A)	91	CLK(3)	127	VDED2
20	VDED	56	IO(A)	92	VCC	128	IO(B)
21	IO(A)	57	IO(A)	93	CLK(4)	129	IO(B)
22	IO(A)	58	GND	94	TMS	130	GND
23	GND	59	IO(A)	95	IO(B)	131	IO(B)
24	VCCIO(A)	60	VCC	96	GND	132	IO(B)
25	IO(A)	61	IO(A)	97	VCCIO(B)	133	IO(B)
26	IO(A)	62	IO(A)	98	IO(B)	134	IO(B)
27	IO(A)	63	IO(A)	99	IO(B)	135	IO(B)
28	IO(A)	64	IO(A)	100	IO(B)	136	IO(B)
29	IO(A)	65	IO(A)	101	IO(B)	137	IO(B)
30	IO(A)	66	IO(A)	102	IO(B)	138	IO(B)
31	IO(A)	67	IO(A)	103	IO(B)	139	IO(B)
32	IO(A)	68	IO(A)	104	IO(B)	140	IO(B)
33	IO(A)	69	VCCIO(A)	105	IO(B)	141	VCCIO(B)
34	TDO	70	IO(A)	106	IO(B)	142	IO(B)
35	GND	71	VPUMP	107	GND	143	IO(B)
36	IO(A)	72	IO(A)	108	IO(B)	144	IO(B)

QL8150 - 196 TFBGA (8 mm x 8 mm Package) Pinout Diagram

Top



Bottom



QL8150 - 196 TFBGA (8 mm x 8 mm Package) Pinout Table

Table 43: QL8150 - 196 TFBGA Pinout Table

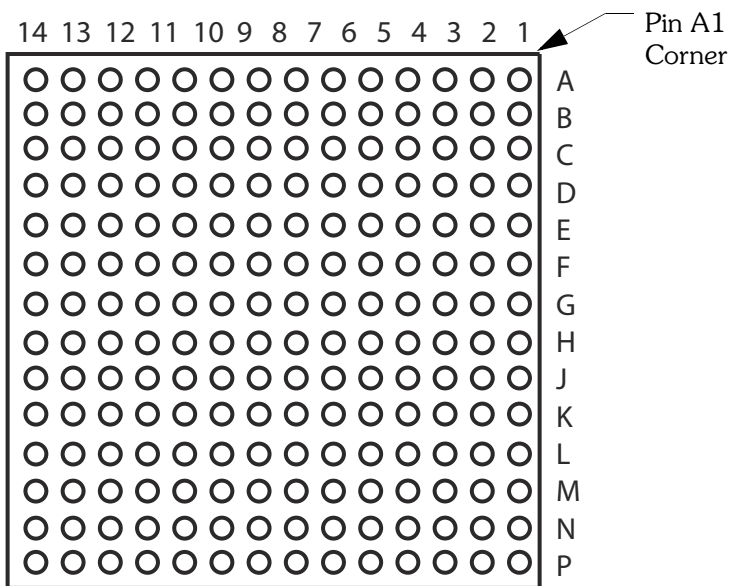
Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	GND	C13	IO(A)	F11	IO(A)	J9	VCCIO(A)	M7	TDI
A2	IO(B)	C14	IO(A)	F12	IO(A)	J10	IO(A)	M8	VDED
A3	IO(B)	D1	IO(B)	F13	IO(A)	J11	IO(A)	M9	IO(A)
A4	IO(B)	D2	VCCIO(B)	F14	VCCIO(A)	J12	IO(A)	M10	IO(A)
A5	VCCIO(B)	D3	IO(B)	G1	GND	J13	IO(A)	M11	TDO
A6	VCC	D4	IO(B)	G2	IO(B)	J14	VCCIO(A)	M12	IO(A)
A7	GND	D5	IO(B)	G3	VDED2	K1	IO(B)	M13	VDED
A8	VCC	D6	IO(B)	G4	TCK	K2	IO(B)	M14	IO(A)
A9	VCCIO(B)	D7	TMS	G5	IO(A)	K3	IO(B)	N1	IO(A)
A10	IO(B)	D8	CLK(4)	G6	IO(A)	K4	IO(B)	N2	IO(B)
A11	IO(B)	D9	INREF	G7	IO(A)	K5	IO(A)	N3	IO(A)
A12	IO(B)	D10	IO(B)	G8	IO(A)	K6	IO(A)	N4	IO(A)
A13	IO(B)	D11	IO(B)	G9	IO(A)	K7	IO(A)	N5	IO(A)
A14	GND	D12	IO(A)	G10	IO(A)	K8	IO(A)	N6	IO(A)
B1	IO(B)	D13	VPUMP	G11	VDED2	K9	GND	N7	IO(A)
B2	IO(B)	D14	IO(A)	G12	IO(A)	K10	IO(A)	N8	IO(A)
B3	IO(B)	E1	VCCIO(B)	G13	IO(A)	K11	VCCIO(A)	N9	IO(A)
B4	IO(B)	E2	IO(B)	G14	GND	K12	IO(A)	N10	IO(A)
B5	IO(B)	E3	IO(B)	H1	VCC	K13	IO(A)	N11	IO(A)
B6	IO(B)	E4	IO(B)	H2	IO(B)	K14	IO(A)	N12	IO(A)
B7	IO(B)	E5	IO(B)	H3	IO(B)	L1	IO(B)	N13	IO(A)
B8	IO(B)	E6	IO(B)	H4	IO(B)	L2	IO(B)	N14	IO(A)
B9	VDED	E7	IO(A)	H5	IO(B)	L3	IO(B)	P1	GND
B10	IO(B)	E8	IO(B)	H6	IO(A)	L4	IO(A)	P2	IO(A)
B11	IO(B)	E9	IO(B)	H7	GND	L5	IO(A)	P3	IO(A)
B12	IO(B)	E10	IO(B)	H8	GND	L6	IO(A)	P4	IO(A)
B13	IO(B)	E11	IO(B)	H9	IO(A)	L7	CLK(0)	P5	IO(A)
B14	IO(A)	E12	IO(A)	H10	IO(A)	L8	CLK(1)	P6	VCCIO(A)
C1	IO(B)	E13	IO(A)	H11	IO(A)	L9	IO(A)	P7	GND
C2	IO(B)	E14	VCC	H12	TRSTB	L10	IO(A)	P8	VCC
C3	IO(B)	F1	VCC	H13	IO(A)	L11	IO(A)	P9	VCCIO(A)
C4	IO(B)	F2	IO(B)	H14	VCC	L12	IO(A)	P10	VCC
C5	IO(B)	F3	IO(B)	J1	VCCIO(B)	L13	IO(A)	P11	IO(A)
C6	IO(B)	F4	IO(B)	J2	IO(B)	L14	IO(A)	P12	IO(A)
C7	CLK(3)	F5	IO(B)	J3	IO(B)	M1	IO(B)	P13	IO(A)
C8	CLK(2)	F6	IO(B)	J4	IO(B)	M2	IO(B)	P14	GND
C9	IO(B)	F7	IO(A)	J5	IO(A)	M3	IO(B)		
C10	IO(B)	F8	IO(A)	J6	IO(A)	M4	GND		
C11	IO(B)	F9	IO(A)	J7	VCCIO(B)	M5	IO(A)		
C12	IO(B)	F10	IO(A)	J8	GND	M6	IO(A)		

QL8150 - 196 TFBGA (12 mm x 12 mm Package) Pinout Diagram

Top



Bottom



QL8150 - 196 TFBGA (12 mm x 12 mm Package) Pinout Table

Table 44: QL8150 - 196 TFBGA Pinout Table

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	IO(B)	C13	IO(A)	F11	IO(A)	J9	GND	M7	VCC
A2	IO(B)	C14	IO(A)	F12	IO(A)	J10	GND	M8	IO(A)
A3	IO(B)	D1	IO(B)	F13	IO(A)	J11	IO(A)	M9	IO(A)
A4	IO(B)	D2	IO(B)	F14	IO(A)	J12	IO(A)	M10	IO(A)
A5	IO(B)	D3	IO(B)	G1	IO(B)	J13	IO(A)	M11	IO(A)
A6	IO(B)	D4	IO(B)	G2	TCK	J14	IO(A)	M12	IO(A)
A7	CLK(4)	D5	IO(B)	G3	IO(B)	K1	IO(B)	M13	IO(A)
A8	CLK(2)	D6	VCCIO(B)	G4	VCC	K2	IO(B)	M14	IO(A)
A9	IO(B)	D7	VCCIO(B)	G5	GND	K3	IO(B)	N1	IO(A)
A10	IO(B)	D8	VDED	G6	GND	K4	IO(A)	N2	IO(A)
A11	INREF	D9	VCCIO(B)	G7	GND	K5	VCCIO(B)	N3	IO(A)
A12	IO(B)	D10	IO(B)	G8	GND	K6	VCCIO(A)	N4	IO(A)
A13	IO(B)	D11	IO(A)	G9	GND	K7	GND	N5	IO(A)
A14	IO(B)	D12	VPUMP	G10	GND	K8	GND	N6	IO(A)
B1	IO(B)	D13	IO(A)	G11	IO(A)	K9	VCCIO(A)	N7	IO(A)
B2	IO(B)	D14	IO(A)	G12	VCC	K10	VCCIO(A)	N8	IO(A)
B3	IO(B)	E1	IO(B)	G13	IO(A)	K11	IO(A)	N9	IO(A)
B4	IO(B)	E2	IO(B)	G14	IO(A)	K12	IO(A)	N10	IO(A)
B5	IO(B)	E3	IO(B)	H1	IO(B)	K13	IO(A)	N11	IO(A)
B6	TMS	E4	IO(B)	H2	IO(B)	K14	IO(A)	N12	TDO
B7	VCC	E5	VCCIO(B)	H3	VDED2	L1	IO(B)	N13	IO(A)
B8	IO(B)	E6	GND	H4	VCCIO(B)	L2	IO(B)	N14	IO(A)
B9	IO(B)	E7	GND	H5	GND	L3	IO(B)	P1	IO(A)
B10	IO(B)	E8	GND	H6	GND	L4	IO(B)	P2	IO(A)
B11	IO(B)	E9	GND	H7	GND	L5	IO(A)	P3	IO(A)
B12	IO(B)	E10	IO(B)	H8	GND	L6	IO(A)	P4	IO(A)
B13	IO(B)	E11	VCCIO(A)	H9	GND	L7	VCCIO(A)	P5	IO(A)
B14	IO(B)	E12	IO(A)	H10	GND	L8	VDED	P6	CLK(0)
C1	IO(B)	E13	IO(A)	H11	VCCIO(A)	L9	VDED	P7	CLK(1)
C2	IO(B)	E14	VCC	H12	TRSTB	L10	VCCIO(A)	P8	IO(A)
C3	IO(B)	F1	IO(B)	H13	VDED2	L11	VCC	P9	IO(A)
C4	VCC	F2	VCC	H14	VCC	L12	IO(A)	P10	IO(A)
C5	IO(B)	F3	IO(B)	J1	IO(B)	L13	IO(A)	P11	IO(A)
C6	VCC	F4	IO(B)	J2	IO(B)	L14	IO(A)	P12	IO(A)
C7	IO(B)	F5	VCCIO(B)	J3	IO(B)	M1	IO(B)	P13	IO(A)
C8	CLK(3)	F6	GND	J4	VCC	M2	IO(B)	P14	IO(A)
C9	IO(B)	F7	GND	J5	IO(B)	M3	IO(B)		
C10	VCC	F8	GND	J6	GND	M4	GND		
C11	IO(B)	F9	GND	J7	GND	M5	VCC		
C12	IO(A)	F10	IO(A)	J8	GND	M6	TDI		

QL8150 - 208 PQFP Pinout Diagram



QL8150 - 208 PQFP Pinout Table

Table 45: QL8150 - 208 PQFP Pinout Table

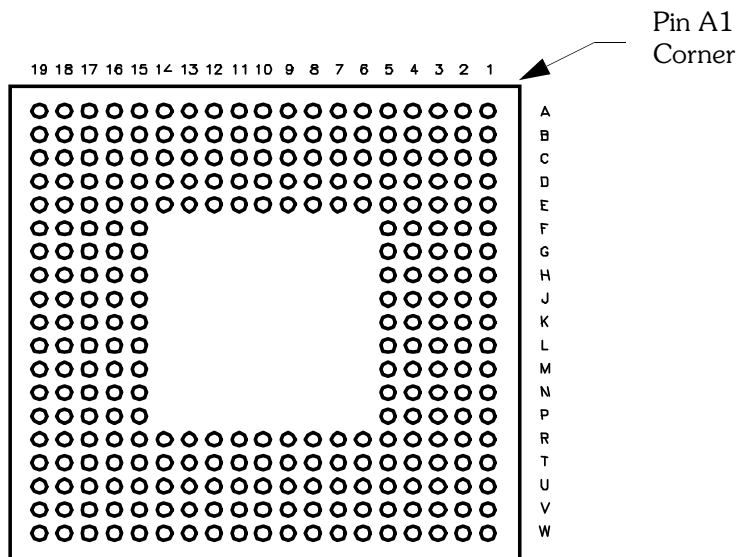
Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	I/O(A)	43	I/O(A)	85	I/O(A)	127	I/O(B)	169	I/O(B)
2	I/O(A)	44	VCCIO(A)	86	VCC	128	CLK(2)	170	I/O(B)
3	GND	45	I/O(A)	87	I/O(A)	129	VDED	171	I/O(B)
4	GND	46	VCC	88	I/O(A)	130	CLK(3)	172	I/O(B)
5	I/O(A)	47	I/O(A)	89	VCC	131	VCC	173	I/O(B)
6	I/O(A)	48	I/O(A)	90	I/O(A)	132	CLK(4)	174	I/O(B)
7	I/O(A)	49	GND	91	I/O(A)	133	TMS	175	VCC
8	VCCIO(A)	50	TDO	92	I/O(A)	134	I/O(B)	176	I/O(B)
9	I/O(A)	51	I/O(A)	93	I/O(A)	135	I/O(B)	177	VCCIO(B)
10	I/O(A)	52	GND	94	I/O(A)	136	I/O(B)	178	GND
11	I/O(A)	53	I/O(A)	95	I/O(A)	137	GND	179	I/O(B)
12	VCC	54	I/O(A)	96	I/O(A)	138	VCCIO(B)	180	I/O(B)
13	I/O(A)	55	I/O(A)	97	I/O(A)	139	I/O(B)	181	I/O(B)
14	I/O(A)	56	VDED	98	VCCIO(A)	140	I/O(B)	182	VCC
15	I/O(A)	57	I/O(A)	99	I/O(A)	141	I/O(B)	183	TCK
16	I/O(A)	58	GND	100	I/O(A)	142	I/O(B)	184	VDED2
17	I/O(A)	59	I/O(A)	101	VPUMP	143	I/O(B)	185	I/O(B)
18	I/O(A)	60	VCCIO(A)	102	I/O(A)	144	I/O(B)	186	I/O(B)
19	VCCIO(A)	61	I/O(A)	103	I/O(A)	145	I/O(B)	187	I/O(B)
20	I/O(A)	62	I/O(A)	104	GND	146	VCC	188	GND
21	GND	63	I/O(A)	105	I/O(B)	147	I/O(B)	189	VCCIO(B)
22	I/O(A)	64	I/O(A)	106	I/O(B)	148	I/O(B)	190	I/O(B)
23	TDI	65	I/O(A)	107	I/O(B)	149	I/O(B)	191	I/O(B)
24	CLK(0)	66	I/O(A)	108	GND	150	VCCIO(B)	192	I/O(B)
25	CLK(1)	67	I/O(A)	109	I/O(B)	151	I/O(B)	193	I/O(B)
26	VCC	68	I/O(A)	110	I/O(B)	152	I/O(B)	194	I/O(B)
27	I/O(A)	69	I/O(A)	111	VCCIO(B)	153	GND	195	VCC
28	I/O(A)	70	I/O(A)	112	I/O(B)	154	I/O(B)	196	I/O(B)
29	VDED	71	I/O(A)	113	VCC	155	I/O(B)	197	I/O(B)
30	I/O(A)	72	VCCIO(A)	114	I/O(B)	156	GND	198	I/O(B)
31	I/O(A)	73	I/O(A)	115	I/O(B)	157	I/O(B)	199	I/O(B)
32	I/O(A)	74	I/O(A)	116	I/O(B)	158	I/O(B)	200	I/O(B)
33	GND	75	GND	117	I/O(B)	159	I/O(B)	201	I/O(B)
34	VCCIO(A)	76	VCC	118	INREF	160	GND	202	I/O(B)
35	I/O(A)	77	I/O(A)	119	I/O(B)	161	I/O(B)	203	VCCIO(B)
36	I/O(A)	78	TRSTB	120	I/O(B)	162	VCCIO(B)	204	GND
37	I/O(A)	79	VDED2	121	I/O(B)	163	I/O(B)	205	I/O(B)
38	I/O(A)	80	I/O(A)	122	VCCIO(B)	164	I/O(B)	206	I/O(B)
39	I/O(A)	81	I/O(A)	123	GND	165	VCC	207	I/O(B)
40	I/O(A)	82	I/O(A)	124	I/O(B)	166	I/O(B)	208	I/O(B)
41	I/O(A)	83	GND	125	I/O(B)	167	I/O(B)		
42	I/O(A)	84	VCCIO(A)	126	I/O(B)	168	I/O(B)		

QL8150 - 280 LFBGA Pinout Diagram

Top



Bottom



QL8150 - 280 LFBGA Pinout Table

Table 46: QL8150 - 280 LFBGA Pinout Table

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	NC	C10	I/O(B)	E19	NC	K16	I/O(A)	R4	I/O(B)	U13	I/O(A)
A2	GND	C11	VCCIO(B)	F1	NC	K17	I/O(A)	R5	GND	U14	NC
A3	I/O(B)	C12	I/O(B)	F2	NC	K18	I/O(A)	R6	GND	U15	VCCIO(A)
A4	I/O(B)	C13	I/O(B)	F3	I/O(B)	K19	TRSTB	R7	VCC	U16	I/O(A)
A5	I/O(B)	C14	I/O(B)	F4	I/O(B)	L1	I/O(B)	R8	VCC	U17	TDO
A6	NC	C15	VCCIO(B)	F5	GND	L2	I/O(B)	R9	GND	U18	NC
A7	I/O(B)	C16	I/O(B)	F15	VCC	L3	VCCIO(B)	R10	GND	U19	I/O(A)
A8	I/O(B)	C17	I/O(B)	F16	NC	L4	I/O(B)	R11	VCC	V1	NC
A9	I/O(B)	C18	I/O(B)	F17	I/O(A)	L5	VCC	R12	VCC	V2	GND
A10	CLK(3)	C19	I/O(B)	F18	I/O(A)	L15	GND	R13	VCC	V3	GND
A11	I/O(B)	D1	I/O(B)	F19	I/O(A)	L16	I/O(A)	R14	VDED	V4	I/O(A)
A12	I/O(B)	D2	I/O(B)	G1	I/O(B)	L17	VCCIO(A)	R15	GND	V5	I/O(A)
A13	I/O(B)	D3	I/O(B)	G2	I/O(B)	L18	I/O(A)	R16	I/O(A)	V6	NC
A14	NC	D4	I/O(B)	G3	NC	L19	I/O(A)	R17	VCCIO(A)	V7	I/O(A)
A15	I/O(B)	D5	I/O(B)	G4	I/O(B)	M1	I/O(B)	R18	I/O(A)	V8	I/O(A)
A16	I/O(B)	D6	I/O(B)	G5	VCC	M2	I/O(B)	R19	I/O(A)	V9	I/O(A)
A17	I/O(B)	D7	I/O(B)	G15	VCC	M3	I/O(B)	T1	I/O(B)	V10	CLK(1)
A18	NC	D8	I/O(B)	G16	I/O(A)	M4	I/O(B)	T2	I/O(B)	V11	NC
A19	NC	D9	CLK(4)	G17	I/O(A)	M5	VCC	T3	I/O(A)	V12	I/O(A)
B1	NC	D10	I/O(B)	G18	I/O(A)	M15	VDED	T4	I/O(A)	V13	I/O(A)
B2	NC	D11	I/O(B)	G19	I/O(A)	M16	NC	T5	I/O(A)	V14	NC
B3	I/O(B)	D12	I/O(B)	H1	I/O(B)	M17	I/O(A)	T6	NC	V15	I/O(A)
B4	I/O(B)	D13	INREF	H2	I/O(B)	M18	I/O(A)	T7	I/O(A)	V16	I/O(A)
B5	I/O(B)	D14	I/O(B)	H3	I/O(B)	M19	I/O(A)	T8	I/O(A)	V17	I/O(A)
B6	NC	D15	I/O(B)	H4	I/O(B)	N1	NC	T9	I/O(A)	V18	GND
B7	I/O(B)	D16	I/O(A)	H5	VCC	N2	I/O(B)	T10	I/O(A)	V19	NC
B8	I/O(B)	D17	I/O(A)	H15	VCC	N3	I/O(B)	T11	NC	W1	NC
B9	TMS	D18	I/O(A)	H16	VDED2	N4	I/O(B)	T12	I/O(A)	W2	NC
B10	CLK(2)	D19	I/O(A)	H17	I/O(A)	N5	VCC	T13	I/O(A)	W3	I/O(A)
B11	I/O(B)	E1	I/O(B)	H18	I/O(A)	N15	VCC	T14	I/O(A)	W4	I/O(A)
B12	I/O(B)	E2	I/O(B)	H19	I/O(A)	N16	I/O(A)	T15	I/O(A)	W5	I/O(A)
B13	NC	E3	VCCIO(B)	J1	I/O(B)	N17	I/O(A)	T16	I/O(A)	W6	I/O(A)
B14	I/O(B)	E4	I/O(B)	J2	I/O(B)	N18	NC	T17	NC	W7	I/O(A)
B15	I/O(B)	E5	GND	J3	VCCIO(B)	N19	NC	T18	I/O(A)	W8	I/O(A)
B16	I/O(B)	E6	VCC	J4	I/O(B)	P1	I/O(B)	T19	I/O(A)	W9	TDI
B17	NC	E7	VCC	J5	GND	P2	I/O(B)	U1	I/O(A)	W10	I/O(A)
B18	GND	E8	VDED	J15	VCC	P3	NC	U2	I/O(A)	W11	I/O(A)
B19	NC	E9	VCC	J16	I/O(A)	P4	NC	U3	NC	W12	I/O(A)
C1	I/O(B)	E10	GND	J17	VCCIO(A)	P5	VCC	U4	I/O(A)	W13	I/O(A)
C2	NC	E11	GND	J18	I/O(A)	P15	GND	U5	VCCIO(A)	W14	NC
C3	I/O(B)	E12	VCC	J19	I/O(A)	P16	I/O(A)	U6	NC	W15	I/O(A)
C4	I/O(B)	E13	VCC	K1	VDED2	P17	I/O(A)	U7	I/O(A)	W16	I/O(A)
C5	VCCIO(B)	E14	GND	K2	TCK	P18	I/O(A)	U8	I/O(A)	W17	I/O(A)
C6	NC	E15	VPUMP	K3	I/O(B)	P19	I/O(A)	U9	VCCIO(A)	W18	I/O(A)
C7	I/O(B)	E16	I/O(A)	K4	I/O(B)	R1	I/O(B)	U10	CLK(0)	W19	NC
C8	I/O(B)	E17	VCCIO(A)	K5	GND	R2	I/O(B)	U11	VCCIO(A)		
C9	VCCIO(B)	E18	NC	K15	GND	R3	VCCIO(B)	U12	I/O(A)		

QL8250 - 208 PQFP Pinout Diagram



QL8250 - 208 PQFP Pinout Table

Table 47: QL8250 - 208 PQFP Pinout Table

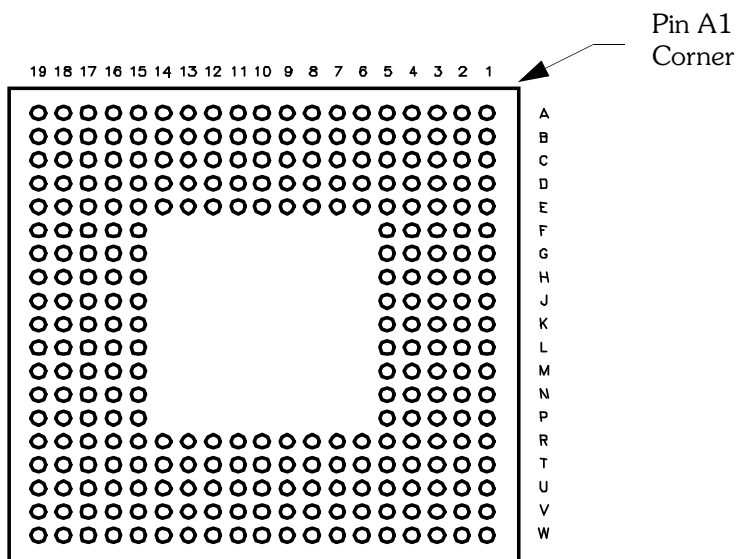
Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	PLLST(3)	43	I/O(B)	85	I/O(D)	127	CLK(5),PLLIN(3)	169	I/O(G)
2	VCCPLL(3)	44	VCCIO(B)	86	VCC	128	CLK(6)	170	INREF(G)
3	GND	45	I/O(B)	87	I/O(D)	129	VDED	171	I/O(G)
4	GND	46	VCC	88	I/O(D)	130	CLK(7)	172	I/O(G)
5	I/O(A)	47	I/O(B)	89	VCC	131	VCC	173	I/O(G)
6	I/O(A)	48	I/O(B)	90	I/O(D)	132	CLK(8)	174	I/O(G)
7	I/O(A)	49	GND	91	I/O(D)	133	TMS	175	VCC
8	VCCIO(A)	50	TDO	92	I/O(D)	134	I/O(F)	176	I/O(G)
9	I/O(A)	51	PLLOUT(1)	93	INREF(D)	135	I/O(F)	177	VCCIO(G)
10	I/O(A)	52	GNDPLL(2)	94	I/O(D)	136	I/O(F)	178	GND
11	I/O(A)	53	GND	95	I/O(D)	137	GND	179	I/O(G)
12	VCC	54	VCCPLL(2)	96	I/O(D)	138	VCCIO(F)	180	I/O(G)
13	INREF(A)	55	PLLST(2)	97	I/O(D)	139	I/O(F)	181	I/O(G)
14	I/O(A)	56	VDED	98	VCCIO(D)	140	I/O(F)	182	VCC
15	I/O(A)	57	I/O(C)	99	I/O(D)	141	I/O(F)	183	TCK
16	I/O(A)	58	GND	100	I/O(D)	142	I/O(F)	184	VDED2
17	I/O(A)	59	I/O(C)	101	VPUMP	143	I/O(F)	185	I/O(H)
18	I/O(A)	60	VCCIO(C)	102	PLLOUT(0)	144	I/O(F)	186	I/O(H)
19	VCCIO(A)	61	I/O(C)	103	GND	145	INREF(F)	187	I/O(H)
20	I/O(A)	62	I/O(C)	104	GNDPLL(1)	146	VCC	188	GND
21	GND	63	I/O(C)	105	PLLST(1)	147	I/O(F)	189	VCCIO(H)
22	I/O(A)	64	I/O(C)	106	VCCPLL(1)	148	I/O(F)	190	I/O(H)
23	TDI	65	I/O(C)	107	I/O(E)	149	I/O(F)	191	I/O(H)
24	CLK(0)	66	I/O(C)	108	GND	150	VCCIO(F)	192	I/O(H)
25	CLK(1)	67	I/O(C)	109	I/O(E)	151	I/O(F)	193	I/O(H)
26	VCC	68	INREF(C)	110	I/O(E)	152	I/O(F)	194	INREF(H)
27	CLK(2),PLLIN(2)	69	I/O(C)	111	VCCIO(E)	153	GND	195	VCC
28	CLK(3),PLLIN(1)	70	I/O(C)	112	I/O(E)	154	I/O(F)	196	I/O(H)
29	VDED	71	I/O(C)	113	VCC	155	PLLOUT(3)	197	I/O(H)
30	CLK(4),DEDCLK, PLLIN(0)	72	VCCIO(C)	114	I/O(E)	156	GNDPLL(0)	198	I/O(H)
31	I/O(B)	73	I/O(C)	115	I/O(E)	157	GND	199	I/O(H)
32	I/O(B)	74	I/O(C)	116	I/O(E)	158	VCCPLL(0)	200	I/O(H)
33	GND	75	GND	117	I/O(E)	159	PLLST(0)	201	I/O(H)
34	VCCIO(B)	76	VCC	118	INREF(E)	160	GND	202	I/O(H)
35	I/O(B)	77	I/O(C)	119	I/O(E)	161	I/O(G)	203	VCCIO(H)
36	I/O(B)	78	TRSTB	120	I/O(E)	162	VCCIO(G)	204	GND
37	I/O(B)	79	VDED2	121	I/O(E)	163	I/O(G)	205	I/O(H)
38	I/O(B)	80	I/O(D)	122	VCCIO(E)	164	I/O(G)	206	PLLOUT(2)
39	I/O(B)	81	I/O(D)	123	GND	165	VCC	207	GND
40	INREF(B)	82	I/O(D)	124	I/O(E)	166	I/O(G)	208	GNDPLL(3)
41	I/O(B)	83	GND	125	I/O(E)	167	I/O(G)		
42	I/O(B)	84	VCCIO(D)	126	I/O(E)	168	I/O(G)		

QL8250 - 280 LFBGA Pinout Diagram

Top



Bottom



QL8250 - 280 LFBGA Pinout Table

Table 48: QL8250 - 280 LFBGA Pinout Table

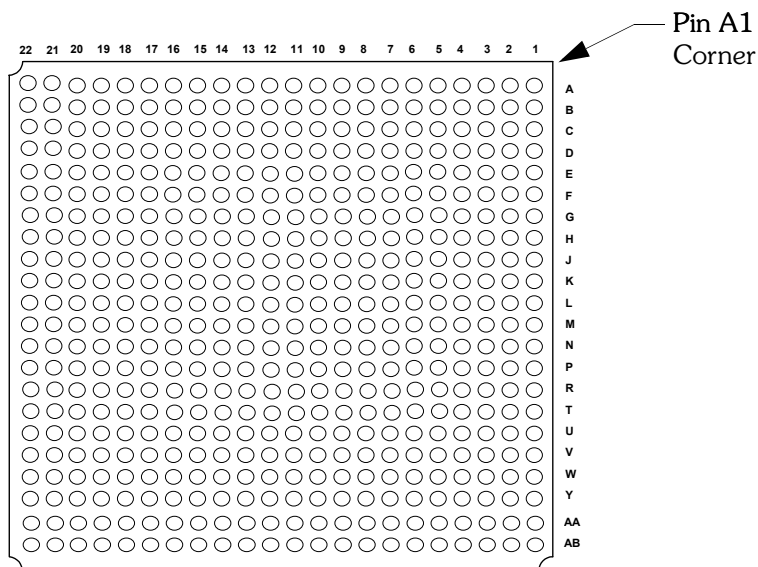
Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	PLLOUT(3)	C10	CLK(5)/PLLIN(3)	E19	IOCTRL(D)	K16	I/O(C)	R4	I/O(H)	U13	I/O(B)
A2	GNDPLL(0)	C11	VCCIO(E)	F1	INREF(G)	K17	I/O(D)	R5	GND	U14	IOCTRL(B)
A3	I/O(F)	C12	I/O(E)	F2	IOCTRL(G)	K18	I/O(C)	R6	GND	U15	VCCIO(B)
A4	I/O(F)	C13	I/O(E)	F3	I/O(G)	K19	TRSTB	R7	VCC	U16	I/O(B)
A5	I/O(F)	C14	I/O(E)	F4	I/O(G)	L1	I/O(H)	R8	VCC	U17	TDO
A6	IOCTRL(F)	C15	VCCIO(E)	F5	GND	L2	I/O(H)	R9	GND	U18	PLLRS(2)
A7	I/O(F)	C16	I/O(E)	F15	VCC	L3	VCCIO(H)	R10	GND	U19	I/O(B)
A8	I/O(F)	C17	I/O(E)	F16	IOCTRL(D)	L4	I/O(H)	R11	VCC	V1	PLLOUT(2)
A9	I/O(F)	C18	I/O(E)	F17	I/O(D)	L5	VCC	R12	VCC	V2	GNDPLL(3)
A10	CLK(7)	C19	I/O(E)	F18	I/O(D)	L15	GND	R13	VCC	V3	GND
A11	I/O(E)	D1	I/O(G)	F19	I/O(D)	L16	I/O(C)	R14	VDED	V4	I/O(A)
A12	I/O(E)	D2	I/O(G)	G1	I/O(G)	L17	VCCIO(C)	R15	GND	V5	I/O(A)
A13	I/O(E)	D3	I/O(F)	G2	I/O(G)	L18	I/O(C)	R16	I/O(C)	V6	IOCTRL(A)
A14	IOCTRL(E)	D4	I/O(F)	G3	IOCTRL(G)	L19	I/O(C)	R17	VCCIO(C)	V7	I/O(A)
A15	I/O(E)	D5	I/O(F)	G4	I/O(G)	M1	I/O(H)	R18	I/O(C)	V8	I/O(A)
A16	I/O(E)	D6	I/O(F)	G5	VCC	M2	I/O(H)	R19	I/O(C)	V9	I/O(A)
A17	I/O(E)	D7	I/O(F)	G15	VCC	M3	I/O(H)	T1	I/O(H)	V10	CLK(1)
A18	PLLRS(1)	D8	I/O(F)	G16	I/O(D)	M4	I/O(H)	T2	I/O(H)	V11	CLK(4) DEDCLK/PLLIN(0)
A19	GND	D9	CLK(8)	G17	I/O(D)	M5	VCC	T3	I/O(A)	V12	I/O(B)
B1	PLLRS(0)	D10	I/O(E)	G18	I/O(D)	M15	VDED	T4	I/O(A)	V13	I/O(B)
B2	GND	D11	I/O(E)	G19	I/O(D)	M16	INREF(C)	T5	I/O(A)	V14	INREF(B)
B3	I/O(F)	D12	I/O(E)	H1	I/O(G)	M17	I/O(C)	T6	IOCTRL(A)	V15	I/O(B)
B4	I/O(F)	D13	INREF(E)	H2	I/O(G)	M18	I/O(C)	T7	I/O(A)	V16	I/O(B)
B5	I/O(F)	D14	I/O(E)	H3	I/O(G)	M19	I/O(C)	T8	I/O(A)	V17	I/O(B)
B6	INREF(F)	D15	I/O(E)	H4	I/O(G)	N1	IOCTRL(H)	T9	I/O(A)	V18	GNDPLL(2)
B7	I/O(F)	D16	I/O(D)	H5	VCC	N2	I/O(H)	T10	I/O(A)	V19	GND
B8	I/O(F)	D17	I/O(D)	H15	VCC	N3	I/O(H)	T11	CLK(3)/PLLIN(1)	W1	GND
B9	TMS	D18	I/O(D)	H16	VDED2	N4	I/O(H)	T12	I/O(B)	W2	PLLRS(3)
B10	CLK(6)	D19	I/O(D)	H17	I/O(D)	N5	VCC	T13	I/O(B)	W3	I/O(A)
B11	I/O(E)	E1	I/O(G)	H18	I/O(D)	N15	VCC	T14	I/O(B)	W4	I/O(A)
B12	I/O(E)	E2	I/O(G)	H19	I/O(D)	N16	I/O(C)	T15	I/O(B)	W5	I/O(A)
B13	IOCTRL(E)	E3	VCCIO(G)	J1	I/O(G)	N17	I/O(C)	T16	I/O(B)	W6	I/O(A)
B14	I/O(E)	E4	I/O(F)	J2	I/O(G)	N18	IOCTRL(C)	T17	VCCPLL(2)	W7	I/O(A)
B15	I/O(E)	E5	GND	J3	VCCIO(G)	N19	IOCTRL(C)	T18	I/O(B)	W8	I/O(A)
B16	I/O(E)	E6	VCC	J4	I/O(G)	P1	I/O(H)	T19	I/O(B)	W9	TDI
B17	VCCPLL(1)	E7	VCC	J5	GND	P2	I/O(H)	U1	I/O(A)	W10	CLK(2)/PLLIN(2)
B18	GNDPLL(1)	E8	VDED	J15	VCC	P3	IOCTRL(H)	U2	I/O(A)	W11	I/O(B)
B19	PLLOUT(0)	E9	VCC	J16	I/O(C)	P4	INREF(H)	U3	VCCPLL(3)	W12	I/O(B)
C1	I/O(F)	E10	GND	J17	VCCIO(D)	P5	VCC	U4	I/O(A)	W13	I/O(B)
C2	VCCPLL(0)	E11	GND	J18	I/O(D)	P15	GND	U5	VCCIO(A)	W14	IOCTRL(B)
C3	I/O(F)	E12	VCC	J19	I/O(D)	P16	I/O(C)	U6	INREF(A)	W15	I/O(B)
C4	I/O(F)	E13	VCC	K1	VDED2	P17	I/O(C)	U7	I/O(A)	W16	I/O(B)
C5	VCCIO(F)	E14	GND	K2	TCK	P18	I/O(C)	U8	I/O(A)	W17	I/O(B)
C6	IOCTRL(F)	E15	VPUMP	K3	I/O(G)	P19	I/O(C)	U9	VCCIO(A)	W18	I/O(B)
C7	I/O(F)	E16	I/O(D)	K4	I/O(G)	R1	I/O(H)	U10	CLK(0)	W19	PLLOUT(1)
C8	I/O(F)	E17	VCCIO(D)	K5	GND	R2	I/O(H)	U11	VCCIO(B)		
C9	VCCIO(F)	E18	INREF(D)	K15	GND	R3	VCCIO(H)	U12	I/O(B)		

QL8250 - 484 PBGA Pinout Diagram

Top



Bottom



QL8250 - 484 PBGA Pinout Table

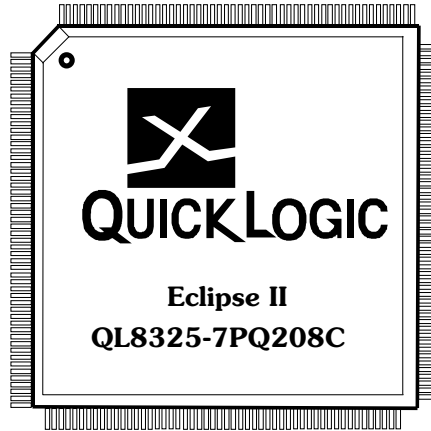
Table 49: QL8250 - 484 PBGA Pinout Table

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	NC	C1	NC	E1	IOCTRL(A)	G1	NC	J1	I/O(A)	L1	CLK(4), DEDCLK, PLLIN(0)
A2	PLLST(3)	C2	I/O(A)	E2	I/O(A)	G2	NC	J2	I/O(A)	L2	CLK(0)
A3	I/O(A)	C3	VCCPLL(3)	E3	I/O(A)	G3	I/O(A)	J3	I/O(A)	L3	CLK(2),PLLIN(2)
A4	I/O(A)	C4	PLLOUT(2)	E4	I/O(A)	G4	I/O(A)	J4	I/O(A)	L4	I/O(A)
A5	I/O(A)	C5	I/O(A)	E5	NC	G5	I/O(A)	J5	I/O(A)	L5	I/O(A)
A6	NC	C6	NC	E6	I/O(H)	G6	I/O(A)	J6	I/O(A)	L6	I/O(A)
A7	I/O(H)	C7	I/O(H)	E7	NC	G7	GND	J7	I/O(A)	L7	GND
A8	IOCTRL(H)	C8	NC	E8	I/O(H)	G8	I/O(H)	J8	VCC	L8	GND
A9	I/O(H)	C9	IOCTRL(H)	E9	I/O(H)	G9	I/O(H)	J9	GND	L9	GND
A10	NC	C10	NC	E10	I/O(H)	G10	NC	J10	VCC	L10	GND
A11	NC	C11	I/O(H)	E11	VDED2	G11	I/O(G)	J11	VCC	L11	GND
A12	TCK	C12	NC	E12	I/O(G)	G12	GND	J12	GND	L12	GND
A13	I/O(G)	C13	I/O(G)	E13	I/O(G)	G13	NC	J13	VCC	L13	GND
A14	I/O(G)	C14	NC	E14	NC	G14	NC	J14	GND	L14	VCC
A15	I/O(G)	C15	I/O(G)	E15	IOCTRL(G)	G15	I/O(G)	J15	VCC	L15	VCC
A16	NC	C16	I/O(G)	E16	I/O(G)	G16	VPUMP	J16	I/O(F)	L16	CLK(6)
A17	I/O(G)	C17	NC	E17	INREF(G)	G17	VCCIO(F)	J17	VCCIO(F)	L17	VCCIO(F)
A18	I/O(G)	C18	I/O(G)	E18	NC	G18	I/O(F)	J18	I/O(F)	L18	I/O(F)
A19	I/O(F)	C19	I/O(F)	E19	I/O(F)	G19	I/O(F)	J19	I/O(F)	L19	CLK(8)
A20	GND	C20	GNDPLL(0)	E20	I/O(F)	G20	I/O(F)	J20	I/O(F)	L20	I/O(F)
A21	PLLOUT(3)	C21	I/O(F)	E21	NC	G21	INREF(F)	J21	I/O(F)	L21	NC
A22	I/O(F)	C22	I/O(F)	E22	I/O(F)	G22	I/O(F)	J22	I/O(F)	L22	I/O(F)
B1	I/O(A)	D1	I/O(A)	F1	I/O(A)	H1	I/O(A)	K1	TDI	M1	I/O(B)
B2	GND	D2	I/O(A)	F2	INREF(A)	H2	I/O(A)	K2	I/O(A)	M2	I/O(B)
B3	GNDPLL(3)	D3	I/O(A)	F3	NC	H3	I/O(A)	K3	I/O(A)	M3	I/O(B)
B4	GND	D4	I/O(A)	F4	I/O(A)	H4	I/O(A)	K4	I/O(A)	M4	CLK(3),PLLIN(1)
B5	I/O(A)	D5	I/O(A)	F5	I/O(A)	H5	IOCTRL(A)	K5	I/O(A)	M5	NC
B6	I/O(H)	D6	I/O(H)	F6	VCCIO(A)	H6	VCCIO(A)	K6	VCCIO(A)	M6	VCCIO(B)
B7	I/O(H)	D7	NC	F7	VCCIO(H)	H7	I/O(H)	K7	NC	M7	CLK(1)
B8	INREF(H)	D8	I/O(H)	F8	I/O(H)	H8	GND	K8	VCC	M8	VCC
B9	I/O(H)	D9	NC	F9	VCCIO(H)	H9	VCC	K9	VCC	M9	VCC
B10	I/O(H)	D10	I/O(H)	F10	I/O(H)	H10	VCC	K10	GND	M10	GND
B11	I/O(H)	D11	I/O(H)	F11	VCCIO(H)	H11	VDED	K11	GND	M11	GND
B12	NC	D12	I/O(G)	F12	VCCIO(G)	H12	GND	K12	GND	M12	GND
B13	NC	D13	I/O(G)	F13	I/O(G)	H13	VCC	K13	GND	M13	GND
B14	NC	D14	I/O(G)	F14	VCCIO(G)	H14	VCC	K14	VCC	M14	GND
B15	NC	D15	IOCTRL(G)	F15	NC	H15	GND	K15	VCC	M15	GND
B16	I/O(G)	D16	I/O(G)	F16	VCCIO(G)	H16	I/O(F)	K16	NC	M16	GND
B17	I/O(G)	D17	I/O(G)	F17	NC	H17	I/O(F)	K17	I/O(F)	M17	I/O(E)
B18	I/O(G)	D18	I/O(F)	F18	I/O(F)	H18	NC	K18	I/O(F)	M18	I/O(E)
B19	PLLST(0)	D19	VCCPLL(0)	F19	I/O(F)	H19	I/O(F)	K19	NC	M19	I/O(E)
B20	I/O(F)	D20	I/O(F)	F20	IOCTRL(F)	H20	I/O(F)	K20	I/O(F)	M20	CLK(7)
B21	I/O(F)	D21	I/O(F)	F21	I/O(F)	H21	I/O(F)	K21	I/O(F)	M21	CLK(5),PLLIN(3)
B22	I/O(F)	D22	I/O(F)	F22	IOCTRL(F)	H22	NC	K22	NC	M22	TMS

Table 49: QL8250 - 484 PBGA Pinout Table (Continued)

Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
N1	NC	P16	I/O(E)	T9	NC	V2	I/O(B)	W17	NC	AA10	I/O(C)
N2	I/O(B)	P17	NC	T10	TRSTB	V3	I/O(B)	W18	I/O(E)	AA11	I/O(C)
N3	I/O(B)	P18	I/O(E)	T11	GND	V4	I/O(B)	W19	NC	AA12	I/O(D)
N4	NC	P19	NC	T12	NC	V5	I/O(B)	W20	I/O(E)	AA13	I/O(D)
N5	I/O(B)	P20	I/O(E)	T13	I/O(D)	V6	NC	W21	NC	AA14	I/O(D)
N6	NC	P21	I/O(E)	T14	NC	V7	I/O(C)	W22	I/O(E)	AA15	I/O(D)
N7	NC	P22	I/O(E)	T15	I/O(D)	V8	I/O(C)	Y1	I/O(B)	AA16	NC
N8	VCC	R1	I/O(B)	T16	GND	V9	NC	Y2	I/O(B)	AA17	NC
N9	VCC	R2	INREF(B)	T17	I/O(E)	V10	I/O(C)	Y3	VCCPLL(2)	AA18	I/O(D)
N10	GND	R3	I/O(B)	T18	I/O(E)	V11	NC	Y4	I/O(C)	AA19	I/O(E)
N11	GND	R4	I/O(B)	T19	NC	V12	VDED2	Y5	I/O(C)	AA20	GNDPLL(1)
N12	GND	R5	I/O(B)	T20	NC	V13	NC	Y6	I/O(C)	AA21	I/O(E)
N13	GND	R6	NC	T21	IOCTRL(E)	V14	I/O(D)	Y7	I/O(C)	AA22	I/O(E)
N14	VCC	R7	I/O(B)	T22	I/O(E)	V15	I/O(D)	Y8	IOCTRL(C)	AB1	I/O(B)
N15	VCC	R8	GND	U1	IOCTRL(B)	V16	INREF(D)	Y9	I/O(C)	AB2	GNDPLL(2)
N16	I/O(E)	R9	VCC	U2	I/O(B)	V17	I/O(D)	Y10	I/O(C)	AB3	PLLST(2)
N17	VCCIO(E)	R10	VCC	U3	IOCTRL(B)	V18	I/O(E)	Y11	I/O(D)	AB4	I/O(B)
N18	I/O(E)	R11	GND	U4	I/O(B)	V19	I/O(E)	Y12	NC	AB5	I/O(B)
N19	I/O(E)	R12	VDED	U5	I/O(B)	V20	I/O(E)	Y13	NC	AB6	I/O(C)
N20	I/O(E)	R13	VCC	U6	I/O(C)	V21	I/O(E)	Y14	I/O(D)	AB7	I/O(C)
N21	I/O(E)	R14	VCC	U7	VCCIO(C)	V22	I/O(E)	Y15	IOCTRL(D)	AB8	IOCTRL(C)
N22	I/O(E)	R15	GND	U8	NC	W1	I/O(B)	Y16	I/O(D)	AB9	I/O(C)
P1	NC	R16	I/O(D)	U9	VCCIO(C)	W2	I/O(B)	Y17	I/O(D)	AB10	I/O(C)
P2	I/O(B)	R17	VCCIO(E)	U10	I/O(C)	W3	I/O(B)	Y18	I/O(E)	AB11	NC
P3	I/O(B)	R18	I/O(E)	U11	VCCIO(C)	W4	I/O(B)	Y19	PLLOUT(0)	AB12	I/O(D)
P4	I/O(B)	R19	I/O(E)	U12	VCCIO(D)	W5	I/O(B)	Y20	PLLST(1)	AB13	I/O(D)
P5	I/O(B)	R20	I/O(E)	U13	I/O(D)	W6	I/O(C)	Y21	I/O(E)	AB14	NC
P6	VCCIO(B)	R21	I/O(E)	U14	VCCIO(D)	W7	NC	Y22	I/O(E)	AB15	I/O(D)
P7	I/O(B)	R22	I/O(E)	U15	NC	W8	NC	AA1	TDO	AB16	IOCTRL(D)
P8	VCC	T1	I/O(B)	U16	VCCIO(D)	W9	NC	AA2	PLLOUT(1)	AB17	I/O(D)
P9	GND	T2	I/O(B)	U17	VCCIO(E)	W10	NC	AA3	GND	AB18	I/O(D)
P10	VCC	T3	I/O(B)	U18	I/O(E)	W11	I/O(C)	AA4	I/O(B)	AB19	I/O(E)
P11	GND	T4	I/O(B)	U19	I/O(E)	W12	NC	AA5	I/O(C)	AB20	GND
P12	VCC	T5	I/O(B)	U20	IOCTRL(E)	W13	I/O(D)	AA6	I/O(C)	AB21	VCCPLL(1)
P13	VCC	T6	VCCIO(B)	U21	NC	W14	NC	AA7	NC	AB22	I/O(E)
P14	GND	T7	GND	U22	INREF(E)	W15	I/O(D)	AA8	INREF(C)		
P15	VDED	T8	I/O(C)	V1	I/O(B)	W16	NC	AA9	NC		

QL8325 - 208 PQFP Pinout Diagram



QL8325 - 208 PQFP Pinout Table

Table 50: QL8325 - 208 PQFP Pinout Table

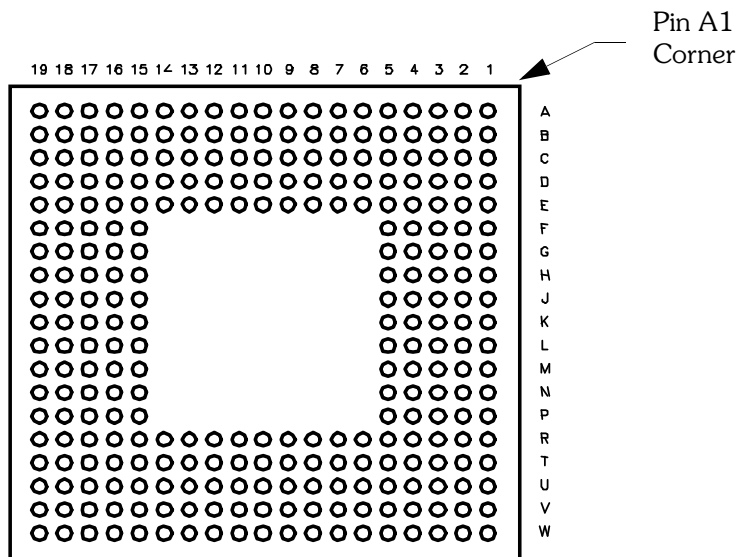
Pin	Function	Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	PLLST(3)	43	I/O(B)	85	I/O(D)	127	CLK(5),PLLIN(3)	169	I/O(G)
2	VCCPLL(3)	44	VCCIO(B)	86	VCC	128	CLK(6)	170	INREF(G)
3	GND	45	I/O(B)	87	I/O(D)	129	VDED	171	I/O(G)
4	GND	46	VCC	88	I/O(D)	130	CLK(7)	172	I/O(G)
5	I/O(A)	47	I/O(B)	89	VCC	131	VCC	173	I/O(G)
6	I/O(A)	48	I/O(B)	90	I/O(D)	132	CLK(8)	174	I/O(G)
7	I/O(A)	49	GND	91	I/O(D)	133	TMS	175	VCC
8	VCCIO(A)	50	TDO	92	I/O(D)	134	I/O(F)	176	I/O(G)
9	I/O(A)	51	PLLOUT(1)	93	INREF(D)	135	I/O(F)	177	VCCIO(G)
10	I/O(A)	52	GNDPLL(2)	94	I/O(D)	136	I/O(F)	178	GND
11	I/O(A)	53	GND	95	I/O(D)	137	GND	179	I/O(G)
12	VCC	54	VCCPLL(2)	96	I/O(D)	138	VCCIO(F)	180	I/O(G)
13	INREF(A)	55	PLLST(2)	97	I/O(D)	139	I/O(F)	181	I/O(G)
14	I/O(A)	56	VDED	98	VCCIO(D)	140	I/O(F)	182	VCC
15	I/O(A)	57	I/O(C)	99	I/O(D)	141	I/O(F)	183	TCK
16	I/O(A)	58	GND	100	I/O(D)	142	I/O(F)	184	VDED2
17	I/O(A)	59	I/O(C)	101	VPUMP	143	I/O(F)	185	I/O(H)
18	I/O(A)	60	VCCIO(C)	102	PLLOUT(0)	144	I/O(F)	186	I/O(H)
19	VCCIO(A)	61	I/O(C)	103	GND	145	INREF(F)	187	I/O(H)
20	I/O(A)	62	I/O(C)	104	GNDPLL(1)	146	VCC	188	GND
21	GND	63	I/O(C)	105	PLLST(1)	147	I/O(F)	189	VCCIO(H)
22	I/O(A)	64	I/O(C)	106	VCCPLL(1)	148	I/O(F)	190	I/O(H)
23	TDI	65	I/O(C)	107	I/O(E)	149	I/O(F)	191	I/O(H)
24	CLK(0)	66	I/O(C)	108	GND	150	VCCIO(F)	192	I/O(H)
25	CLK(1)	67	I/O(C)	109	I/O(E)	151	I/O(F)	193	I/O(H)
26	VCC	68	INREF(C)	110	I/O(E)	152	I/O(F)	194	INREF(H)
27	CLK(2),PLLIN(2)	69	I/O(C)	111	VCCIO(E)	153	GND	195	VCC
28	CLK(3),PLLIN(1)	70	I/O(C)	112	I/O(E)	154	I/O(F)	196	I/O(H)
29	VDED	71	I/O(C)	113	VCC	155	PLLOUT(3)	197	I/O(H)
30	CLK(4),DEDCLK, PLLIN(0)	72	VCCIO(C)	114	I/O(E)	156	GNDPLL(0)	198	I/O(H)
31	I/O(B)	73	I/O(C)	115	I/O(E)	157	GND	199	I/O(H)
32	I/O(B)	74	I/O(C)	116	I/O(E)	158	VCCPLL(0)	200	I/O(H)
33	GND	75	GND	117	I/O(E)	159	PLLST(0)	201	I/O(H)
34	VCCIO(B)	76	VCC	118	INREF(E)	160	GND	202	I/O(H)
35	I/O(B)	77	I/O(C)	119	I/O(E)	161	I/O(G)	203	VCCIO(H)
36	I/O(B)	78	TRSTB	120	I/O(E)	162	VCCIO(G)	204	GND
37	I/O(B)	79	VDED2	121	I/O(E)	163	I/O(G)	205	I/O(H)
38	I/O(B)	80	I/O(D)	122	VCCIO(E)	164	I/O(G)	206	PLLOUT(2)
39	I/O(B)	81	I/O(D)	123	GND	165	VCC	207	GND
40	INREF(B)	82	I/O(D)	124	I/O(E)	166	I/O(G)	208	GNDPLL(3)
41	I/O(B)	83	GND	125	I/O(E)	167	I/O(G)		
42	I/O(B)	84	VCCIO(D)	126	I/O(E)	168	I/O(G)		

QL8325 - 280 LFBGA Pinout Diagram

Top



Bottom



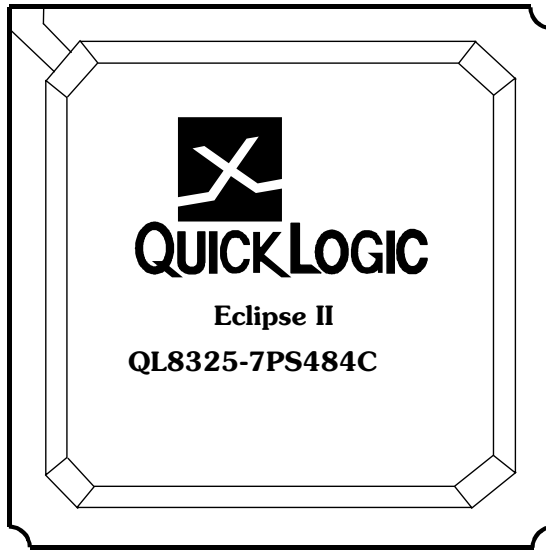
QL8325 - 280 LFBGA Pinout Table

Table 51: QL8325 - 280 LFBGA Pinout Table

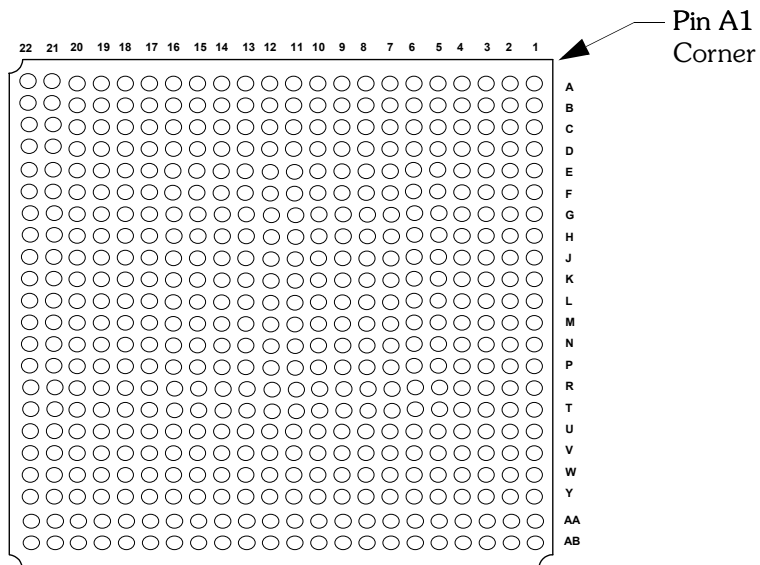
Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	PLLOUT(3)	C10	CLK(5)/ PLLIN(3)	E19	IOCTRL(D)	K16	I/O(C)	R4	I/O(H)	U13	I/O(B)
A2	GNDPLL(0)	C11	VCCIO(E)	F1	INREF(G)	K17	I/O(D)	R5	GND	U14	IOCTRL(B)
A3	I/O(F)	C12	I/O(E)	F2	IOCTRL(G)	K18	I/O(C)	R6	GND	U15	VCCIO(B)
A4	I/O(F)	C13	I/O(E)	F3	I/O(G)	K19	TRSTB	R7	VCC	U16	I/O(B)
A5	I/O(F)	C14	I/O(E)	F4	I/O(G)	L1	I/O(H)	R8	VCC	U17	TDO
A6	IOCTRL(F)	C15	VCCIO(E)	F5	GND	L2	I/O(H)	R9	GND	U18	PLLRS(2)
A7	I/O(F)	C16	I/O(E)	F15	VCC	L3	VCCIO(H)	R10	GND	U19	I/O(B)
A8	I/O(F)	C17	I/O(E)	F16	IOCTRL(D)	L4	I/O(H)	R11	VCC	V1	PLLOUT(2)
A9	I/O(F)	C18	I/O(E)	F17	I/O(D)	L5	VCC	R12	VCC	V2	GNDPLL(3)
A10	CLK(7)	C19	I/O(E)	F18	I/O(D)	L15	GND	R13	VCC	V3	GND
A11	I/O(E)	D1	I/O(G)	F19	I/O(D)	L16	I/O(C)	R14	VDED	V4	I/O(A)
A12	I/O(E)	D2	I/O(G)	G1	I/O(G)	L17	VCCIO(C)	R15	GND	V5	I/O(A)
A13	I/O(E)	D3	I/O(F)	G2	I/O(G)	L18	I/O(C)	R16	I/O(C)	V6	IOCTRL(A)
A14	IOCTRL(E)	D4	I/O(F)	G3	IOCTRL(G)	L19	I/O(C)	R17	VCCIO(C)	V7	I/O(A)
A15	I/O(E)	D5	I/O(F)	G4	I/O(G)	M1	I/O(H)	R18	I/O(C)	V8	I/O(A)
A16	I/O(E)	D6	I/O(F)	G5	VCC	M2	I/O(H)	R19	I/O(C)	V9	I/O(A)
A17	I/O(E)	D7	I/O(F)	G15	VCC	M3	I/O(H)	T1	I/O(H)	V10	CLK(1)
A18	PLLRS(1)	D8	I/O(F)	G16	I/O(D)	M4	I/O(H)	T2	I/O(H)	V11	CLK(4) DEDCLK/ PLLIN(0)
A19	GND	D9	CLK(8)	G17	I/O(D)	M5	VCC	T3	I/O(A)	V12	I/O(B)
B1	PLLRS(0)	D10	I/O(E)	G18	I/O(D)	M15	VDED	T4	I/O(A)	V13	I/O(B)
B2	GND	D11	I/O(E)	G19	I/O(D)	M16	INREF(C)	T5	I/O(A)	V14	INREF(B)
B3	I/O(F)	D12	I/O(E)	H1	I/O(G)	M17	I/O(C)	T6	IOCTRL(A)	V15	I/O(B)
B4	I/O(F)	D13	INREF(E)	H2	I/O(G)	M18	I/O(C)	T7	I/O(A)	V16	I/O(B)
B5	I/O(F)	D14	I/O(E)	H3	I/O(G)	M19	I/O(C)	T8	I/O(A)	V17	I/O(B)
B6	INREF(F)	D15	I/O(E)	H4	I/O(G)	N1	IOCTRL(H)	T9	I/O(A)	V18	GNDPLL(2)
B7	I/O(F)	D16	I/O(D)	H5	VCC	N2	I/O(H)	T10	I/O(A)	V19	GND
B8	I/O(F)	D17	I/O(D)	H15	VCC	N3	I/O(H)	T11	CLK(3) /PLLIN(1)	W1	GND
B9	TMS	D18	I/O(D)	H16	VDED2	N4	I/O(H)	T12	I/O(B)	W2	PLLRS(3)
B10	CLK(6)	D19	I/O(D)	H17	I/O(D)	N5	VCC	T13	I/O(B)	W3	I/O(A)
B11	I/O(E)	E1	I/O(G)	H18	I/O(D)	N15	VCC	T14	I/O(B)	W4	I/O(A)
B12	I/O(E)	E2	I/O(G)	H19	I/O(D)	N16	I/O(C)	T15	I/O(B)	W5	I/O(A)
B13	IOCTRL(E)	E3	VCCIO(G)	J1	I/O(G)	N17	I/O(C)	T16	I/O(B)	W6	I/O(A)
B14	I/O(E)	E4	I/O(F)	J2	I/O(G)	N18	IOCTRL(C)	T17	VCCPLL(2)	W7	I/O(A)
B15	I/O(E)	E5	GND	J3	VCCIO(G)	N19	IOCTRL(C)	T18	I/O(B)	W8	I/O(A)
B16	I/O(E)	E6	VCC	J4	I/O(G)	P1	I/O(H)	T19	I/O(B)	W9	TDI
B17	VCCPLL(1)	E7	VCC	J5	GND	P2	I/O(H)	U1	I/O(A)	W10	CLK(2)/ PLLIN(2)
B18	GNDPLL(1)	E8	VDED	J15	VCC	P3	IOCTRL(H)	U2	I/O(A)	W11	I/O(B)
B19	PLLOUT(0)	E9	VCC	J16	I/O(C)	P4	INREF(H)	U3	VCCPLL(3)	W12	I/O(B)
C1	I/O(F)	E10	GND	J17	VCCIO(D)	P5	VCC	U4	I/O(A)	W13	I/O(B)
C2	VCCPLL(0)	E11	GND	J18	I/O(D)	P15	GND	U5	VCCIO(A)	W14	IOCTRL(B)
C3	I/O(F)	E12	VCC	J19	I/O(D)	P16	I/O(C)	U6	INREF(A)	W15	I/O(B)
C4	I/O(F)	E13	VCC	K1	VDED2	P17	I/O(C)	U7	I/O(A)	W16	I/O(B)
C5	VCCIO(F)	E14	GND	K2	TCK	P18	I/O(C)	U8	I/O(A)	W17	I/O(B)
C6	IOCTRL(F)	E15	VPUMP	K3	I/O(G)	P19	I/O(C)	U9	VCCIO(A)	W18	I/O(B)
C7	I/O(F)	E16	I/O(D)	K4	I/O(G)	R1	I/O(H)	U10	CLK(0)	W19	PLLOUT(1)
C8	I/O(F)	E17	VCCIO(D)	K5	GND	R2	I/O(H)	U11	VCCIO(B)		
C9	VCCIO(F)	E18	INREF(D)	K15	GND	R3	VCCIO(H)	U12	I/O(B)		

QL8325 - 484 PBGA Pinout Diagram

Top



Bottom



QL8325 - 484 PBGA Pinout Table

Table 52: QL8325 - 484 PBGA Pinout Table

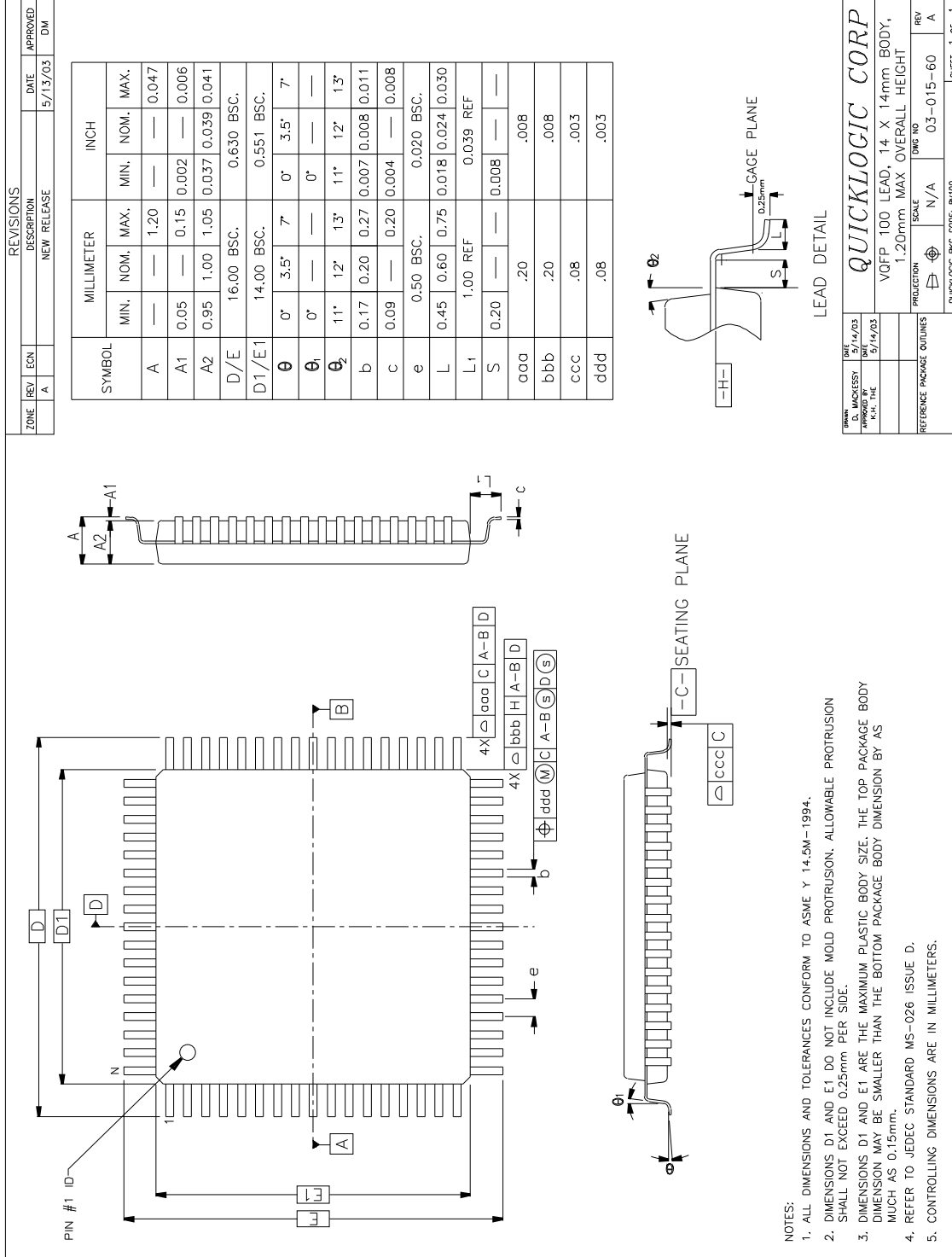
Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
A1	I/O(A)	C1	I/O(A)	E1	IOCTRL(A)	G1	I/O(A)	J1	I/O(A)	L1	CLK(4) DEDCLK/ PLLIN(0)
A2	PLLRST(3)	C2	I/O(A)	E2	I/O(A)	G2	I/O(A)	J2	I/O(A)	L2	CLK(0)
A3	I/O(A)	C3	VCCPLL(3)	E3	I/O(A)	G3	I/O(A)	J3	I/O(A)	L3	CLK(2)/ PLLIN(2)
A4	I/O(A)	C4	PLLOUT(2)	E4	I/O(A)	G4	I/O(A)	J4	I/O(A)	L4	I/O(A)
A5	I/O(A)	C5	I/O(A)	E5	I/O(A)	G5	I/O(A)	J5	I/O(A)	L5	I/O(A)
A6	I/O(H)	C6	I/O(H)	E6	I/O(H)	G6	I/O(A)	J6	I/O(A)	L6	I/O(A)
A7	I/O(H)	C7	I/O(H)	E7	N/C	G7	GND	J7	I/O(A)	L7	GND
A8	IOCTRL(H)	C8	I/O(H)	E8	I/O(H)	G8	I/O(H)	J8	VCC	L8	GND
A9	I/O(H)	C9	IOCTRL(H)	E9	I/O(H)	G9	I/O(H)	J9	GND	L9	GND
A10	N/C	C10	I/O(H)	E10	I/O(H)	G10	I/O(H)	J10	VCC	L10	GND
A11	N/C	C11	I/O(H)	E11	VDED2	G11	I/O(G)	J11	VCC	L11	GND
A12	TCK	C12	I/O(H)	E12	I/O(G)	G12	GND	J12	GND	L12	GND
A13	I/O(G)	C13	I/O(G)	E13	I/O(G)	G13	I/O(G)	J13	VCC	L13	GND
A14	I/O(G)	C14	I/O(G)	E14	I/O(G)	G14	I/O(G)	J14	GND	L14	VCC
A15	I/O(G)	C15	I/O(G)	E15	IOCTRL(G)	G15	I/O(G)	J15	VCC	L15	VCC
A16	I/O(G)	C16	I/O(G)	E16	I/O(G)	G16	VPUMP	J16	I/O(F)	L16	CLK(6)
A17	I/O(G)	C17	I/O(G)	E17	INREF(G)	G17	VCCIO(F)	J17	VCCIO(F)	L17	VCCIO(F)
A18	I/O(G)	C18	I/O(G)	E18	I/O(G)	G18	I/O(F)	J18	I/O(F)	L18	I/O(F)
A19	I/O(F)	C19	I/O(F)	E19	I/O(F)	G19	I/O(F)	J19	I/O(F)	L19	CLK(8)
A20	GND	C20	GNDPLL(0)	E20	I/O(F)	G20	I/O(F)	J20	I/O(F)	L20	I/O(F)
A21	PLLOUT(3)	C21	I/O(F)	E21	I/O(F)	G21	INREF(F)	J21	I/O(F)	L21	I/O(F)
A22	I/O(F)	C22	I/O(F)	E22	I/O(F)	G22	I/O(F)	J22	I/O(F)	L22	I/O(F)
B1	I/O(A)	D1	I/O(A)	F1	I/O(A)	H1	I/O(A)	K1	TDI	M1	I/O(B)
B2	GND	D2	I/O(A)	F2	INREF(A)	H2	I/O(A)	K2	I/O(A)	M2	I/O(B)
B3	GNDPLL(3)	D3	I/O(A)	F3	I/O(A)	H3	I/O(A)	K3	I/O(A)	M3	I/O(B)
B4	GND	D4	I/O(A)	F4	I/O(A)	H4	I/O(A)	K4	I/O(A)	M4	CLK(3)/ PLLIN(1)
B5	I/O(A)	D5	I/O(A)	F5	I/O(A)	H5	IOCTRL(A)	K5	I/O(A)	M5	I/O(B)
B6	I/O(H)	D6	I/O(H)	F6	VCCIO(A)	H6	VCCIO(A)	K6	VCCIO(A)	M6	VCCIO(B)
B7	I/O(H)	D7	I/O(H)	F7	VCCIO(H)	H7	I/O(H)	K7	I/O(A)	M7	CLK(1)
B8	INREF(H)	D8	I/O(H)	F8	I/O(H)	H8	GND	K8	VCC	M8	VCC
B9	I/O(H)	D9	I/O(H)	F9	VCCIO(H)	H9	VCC	K9	VCC	M9	VCC
B10	I/O(H)	D10	I/O(H)	F10	I/O(H)	H10	VCC	K10	GND	M10	GND
B11	I/O(H)	D11	I/O(H)	F11	VCCIO(H)	H11	VDED	K11	GND	M11	GND
B12	N/C	D12	I/O(G)	F12	VCCIO(G)	H12	GND	K12	GND	M12	GND
B13	N/C	D13	I/O(G)	F13	I/O(G)	H13	VCC	K13	GND	M13	GND
B14	N/C	D14	I/O(G)	F14	VCCIO(G)	H14	VCC	K14	VCC	M14	GND
B15	I/O(G)	D15	IOCTRL(G)	F15	N/C	H15	GND	K15	VCC	M15	GND
B16	I/O(G)	D16	I/O(G)	F16	VCCIO(G)	H16	I/O(F)	K16	I/O(F)	M16	GND
B17	I/O(G)	D17	I/O(G)	F17	N/C	H17	I/O(F)	K17	I/O(F)	M17	I/O(E)
B18	I/O(G)	D18	I/O(F)	F18	I/O(F)	H18	I/O(F)	K18	I/O(F)	M18	I/O(E)
B19	PLLRST(0)	D19	VCCPLL(0)	F19	I/O(F)	H19	I/O(F)	K19	I/O(F)	M19	I/O(E)
B20	I/O(F)	D20	I/O(F)	F20	IOCTRL(F)	H20	I/O(F)	K20	I/O(F)	M20	CLK(7)
B21	I/O(F)	D21	I/O(F)	F21	I/O(F)	H21	I/O(F)	K21	I/O(F)	M21	CLK(5)/ PLLIN(3)
B22	I/O(F)	D22	I/O(F)	F22	IOCTRL(F)	H22	I/O(F)	K22	I/O(F)	M22	TMS

Table 52: QL8325 - 484 PBGA Pinout Table (Continued)

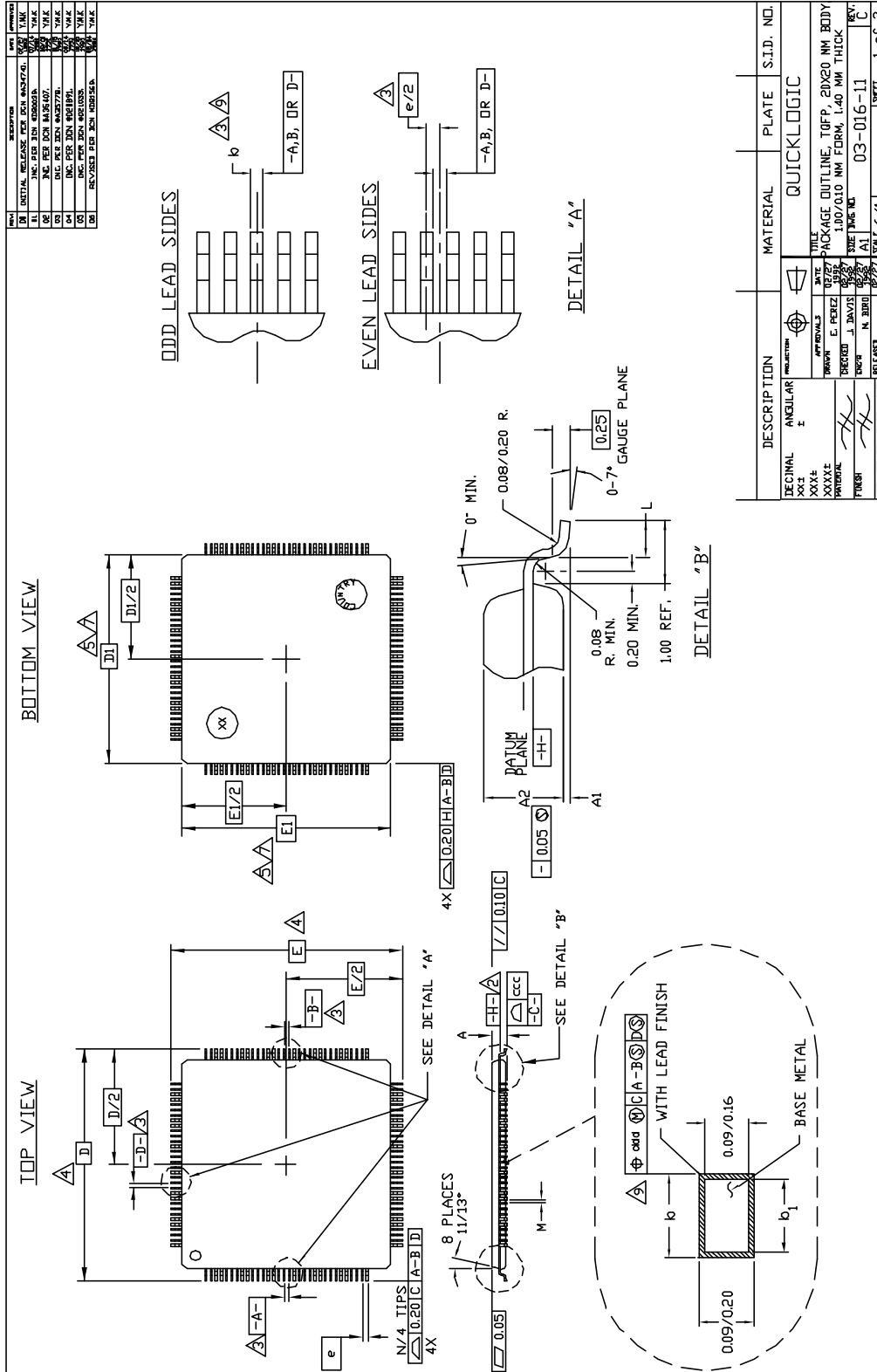
Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function	Ball	Function
N1	I/O(B)	P16	I/O(E)	T9	N/C	V2	I/O(B)	W17	I/O(D)	AA10	I/O(C)
N2	I/O(B)	P17	I/O(E)	T10	TRSTB	V3	I/O(B)	W18	I/O(E)	AA11	I/O(C)
N3	I/O(B)	P18	I/O(E)	T11	GND	V4	I/O(B)	W19	I/O(E)	AA12	I/O(D)
N4	I/O(B)	P19	I/O(E)	T12	N/C	V5	I/O(B)	W20	I/O(E)	AA13	I/O(D)
N5	I/O(B)	P20	I/O(E)	T13	I/O(D)	V6	I/O(C)	W21	I/O(E)	AA14	I/O(D)
N6	I/O(B)	P21	I/O(E)	T14	N/C	V7	I/O(C)	W22	I/O(E)	AA15	I/O(D)
N7	I/O(B)	P22	I/O(E)	T15	I/O(D)	V8	I/O(C)	Y1	I/O(B)	AA16	I/O(D)
N8	VCC	R1	I/O(B)	T16	GND	V9	N/C	Y2	I/O(B)	AA17	I/O(D)
N9	VCC	R2	INREF(B)	T17	I/O(E)	V10	I/O(C)	Y3	VCCPLL(2)	AA18	I/O(D)
N10	GND	R3	I/O(B)	T18	I/O(E)	V11	I/O(C)	Y4	I/O(C)	AA19	I/O(E)
N11	GND	R4	I/O(B)	T19	I/O(E)	V12	VDED2	Y5	I/O(C)	AA20	GNDPLL(1)
N12	GND	R5	I/O(B)	T20	I/O(E)	V13	N/C	Y6	I/O(C)	AA21	I/O(E)
N13	GND	R6	I/O(B)	T21	IOCTRL(E)	V14	I/O(D)	Y7	I/O(C)	AA22	I/O(E)
N14	VCC	R7	I/O(B)	T22	I/O(E)	V15	I/O(D)	Y8	IOCTRL(C)	AB1	I/O(B)
N15	VCC	R8	GND	U1	IOCTRL(B)	V16	INREF(D)	Y9	I/O(C)	AB2	GNDPLL(2)
N16	I/O(E)	R9	VCC	U2	I/O(B)	V17	I/O(D)	Y10	I/O(C)	AB3	PLLIRST(2)
N17	VCCIO(E)	R10	VCC	U3	IOCTRL(B)	V18	I/O(E)	Y11	I/O(D)	AB4	I/O(B)
N18	I/O(E)	R11	GND	U4	I/O(B)	V19	I/O(E)	Y12	I/O(D)	AB5	I/O(B)
N19	I/O(E)	R12	VDED	U5	I/O(B)	V20	I/O(E)	Y13	I/O(D)	AB6	I/O(C)
N20	I/O(E)	R13	VCC	U6	I/O(C)	V21	I/O(E)	Y14	I/O(D)	AB7	I/O(C)
N21	I/O(E)	R14	VCC	U7	VCCIO(C)	V22	I/O(E)	Y15	IOCTRL(D)	AB8	IOCTRL(C)
N22	I/O(E)	R15	GND	U8	N/C	W1	I/O(B)	Y16	I/O(D)	AB9	I/O(C)
P1	I/O(B)	R16	I/O(D)	U9	VCCIO(C)	W2	I/O(B)	Y17	I/O(D)	AB10	I/O(C)
P2	I/O(B)	R17	VCCIO(E)	U10	I/O(C)	W3	I/O(B)	Y18	I/O(E)	AB11	I/O(C)
P3	I/O(B)	R18	I/O(E)	U11	VCCIO(C)	W4	I/O(B)	Y19	PLLOUT(0)	AB12	I/O(D)
P4	I/O(B)	R19	I/O(E)	U12	VCCIO(D)	W5	I/O(B)	Y20	PLLIRST(1)	AB13	I/O(D)
P5	I/O(B)	R20	I/O(E)	U13	I/O(D)	W6	I/O(C)	Y21	I/O(E)	AB14	I/O(D)
P6	VCCIO(B)	R21	I/O(E)	U14	VCCIO(D)	W7	N/C	Y22	I/O(E)	AB15	I/O(D)
P7	I/O(B)	R22	I/O(E)	U15	N/C	W8	I/O(C)	AA1	TDO	AB16	IOCTRL(D)
P8	VCC	T1	I/O(B)	U16	VCCIO(D)	W9	I/O(C)	AA2	PLLOUT(1)	AB17	I/O(D)
P9	GND	T2	I/O(B)	U17	VCCIO(E)	W10	I/O(C)	AA3	GND	AB18	I/O(D)
P10	VCC	T3	I/O(B)	U18	I/O(E)	W11	I/O(C)	AA4	I/O(B)	AB19	I/O(E)
P11	GND	T4	I/O(B)	U19	I/O(E)	W12	I/O(D)	AA5	I/O(C)	AB20	GND
P12	VCC	T5	I/O(B)	U20	IOCTRL(E)	W13	I/O(D)	AA6	I/O(C)	AB21	VCCPLL(1)
P13	VCC	T6	VCCIO(B)	U21	I/O(E)	W14	I/O(D)	AA7	I/O(C)	AB22	I/O(E)
P14	GND	T7	GND	U22	INREF(E)	W15	I/O(D)	AA8	INREF(C)		
P15	VDED	T8	I/O(C)	V1	I/O(B)	W16	N/C	AA9	I/O(C)		

Package Mechanical Drawings

100 VQFP Packaging Drawing



144 TQFP Packaging Drawing



144 TQFP Packaging Drawing (Continued)

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5-1982.
 2. DATUM PLANE $\square\text{---}\square$ LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
 3. DATUMS $\square\text{---}\square$ AND $\square\text{---}\square$ TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE $\square\text{---}\square$.
 4. TO BE DETERMINED AT SEATING PLANE $\square\text{---}\square$.
 5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION, ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
 6. "N" IS THE TOTAL NUMBER OF TERMINALS.
 7. THESE DIMENSIONS TO BE DETERMINED AT DATUM PLANE $\square\text{---}\square$.
 8. THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS, AND THE TOP OF THE PACKAGE WILL NOT OVERHANG THE BOTTOM OF THE PACKAGE.
9. DIMENSION b_1 DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm. TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
 10. CONTROLLING DIMENSION: MILLIMETER.
 11. MAXIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PACKAGE FAMILY IS 0.38 MILLIMETERS.
 12. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-136, VARIATION BT.

(JEDEC VARIATION)

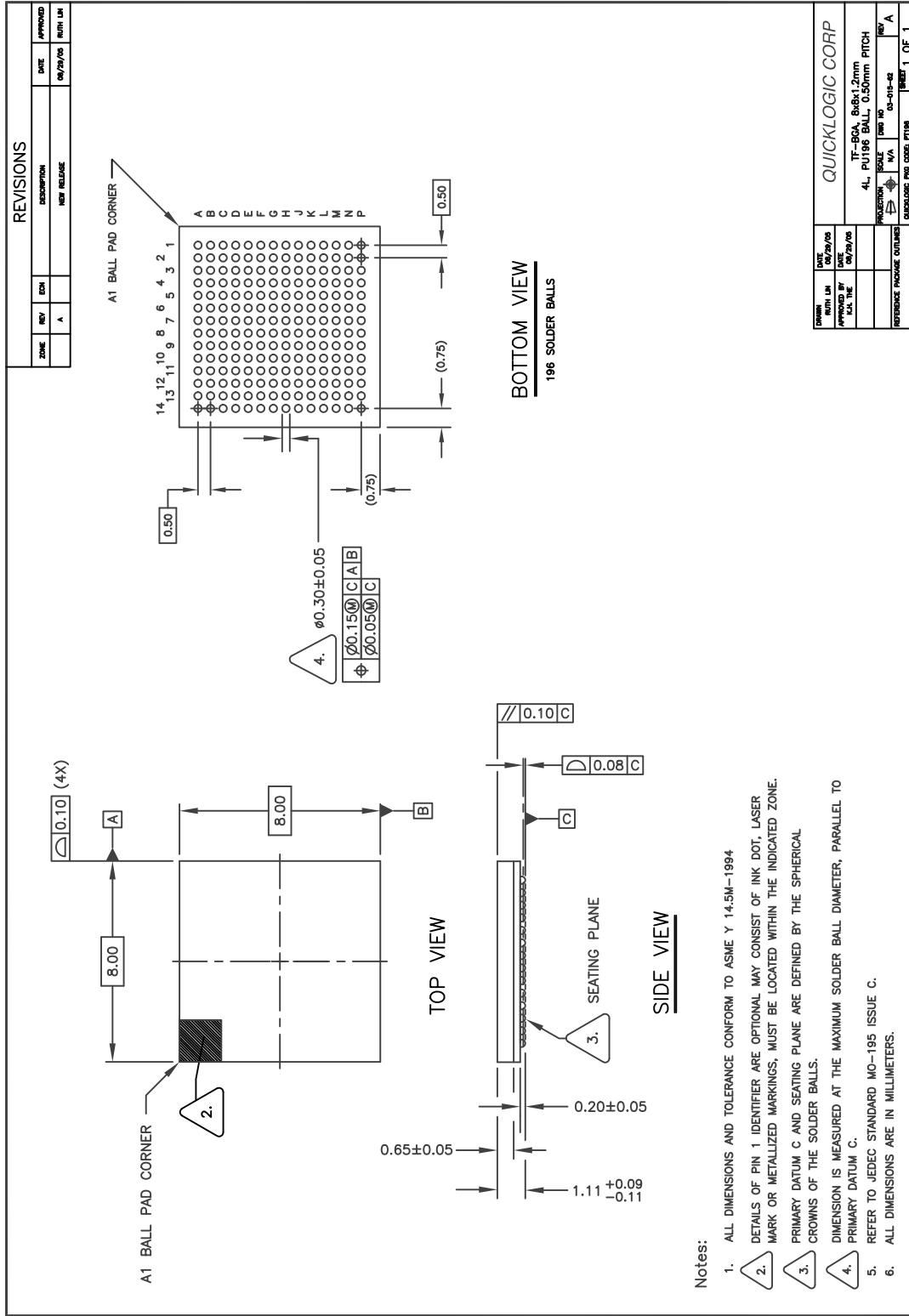
ALL DIMENSIONS IN MILLIMETERS

SYMBOL	BT			NOTE
	MIN.	NOM.	MAX.	
A	\curvearrowright	\curvearrowright	1.60	
A1	0.05	0.10	0.15	
A2	1.35	1.40	1.45	
D	22.00 BSC.			4
D1	20.00 BSC.			7,8
E	22.00 BSC.			4
E1	20.00 BSC.			7,8
L	0.45	0.60	0.75	
M	0.14	\curvearrowright	\curvearrowright	
N	*128, 144			
e	0.50 BSC.			
b	0.17	0.22	0.27	
b1	0.17	0.20	0.23	9
ccc	\curvearrowright	\curvearrowright	0.08	
ddd	\curvearrowright	\curvearrowright	0.08	

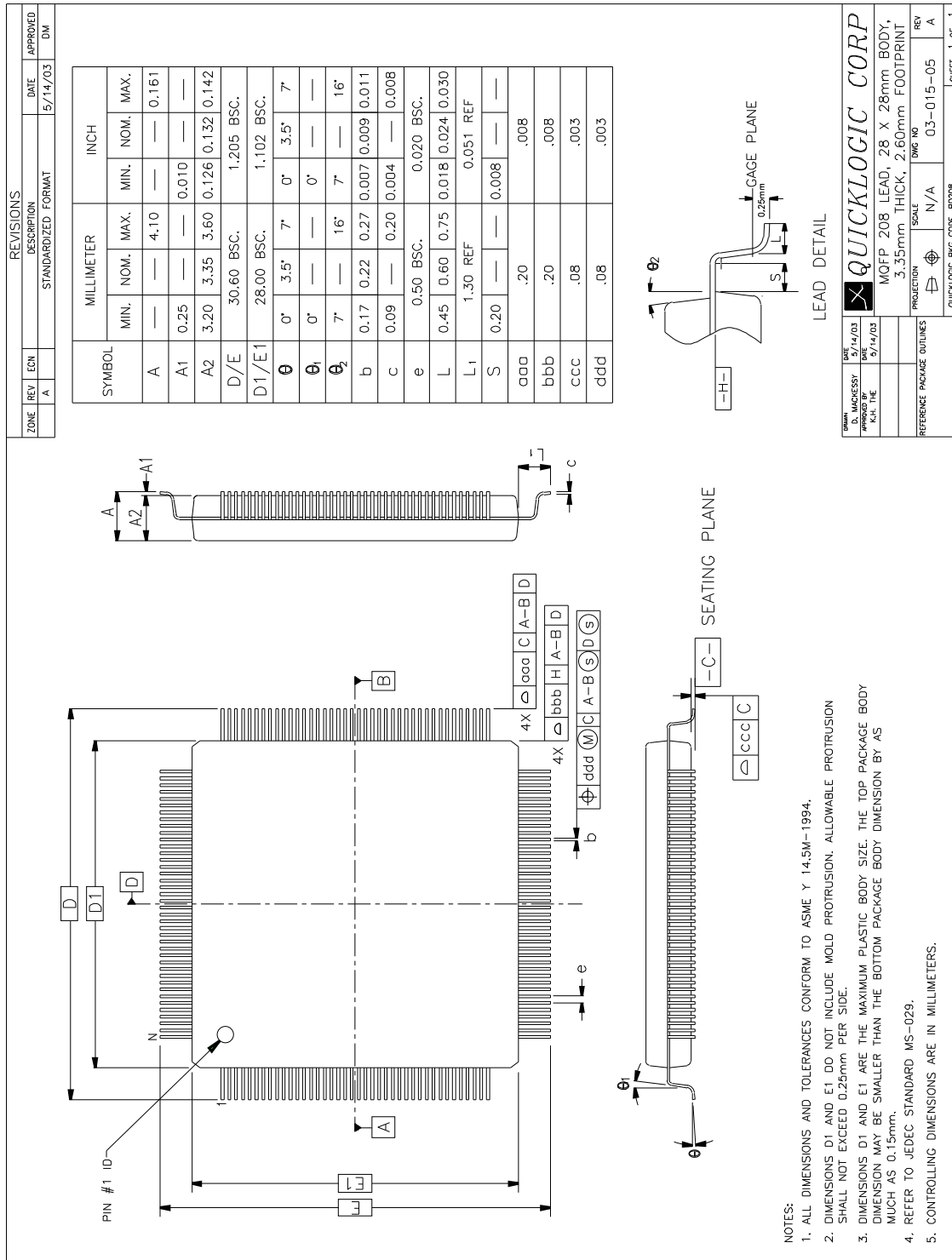
* NOTE: THE 128 LEAD IS A COMPLIANT DEPOPULATION OF THE 144 LEAD MO-136 VARIATION BT.

REV. 03-016-11
 DATE 06/21
 PAGE 2 OF 2

196 TFBGA (8 mm x 8 mm Package) Packaging Drawing

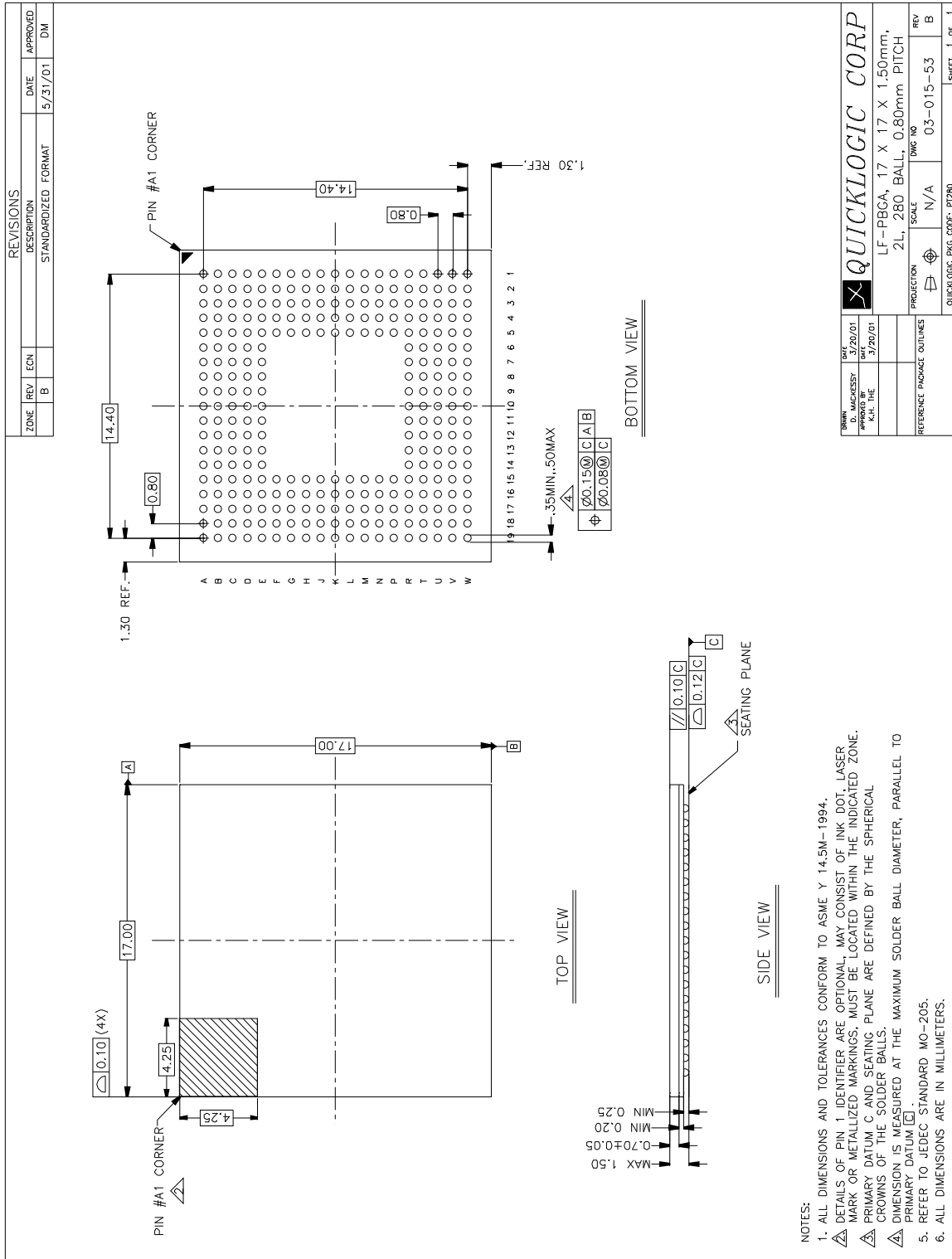


208 PQFP Packaging Drawing



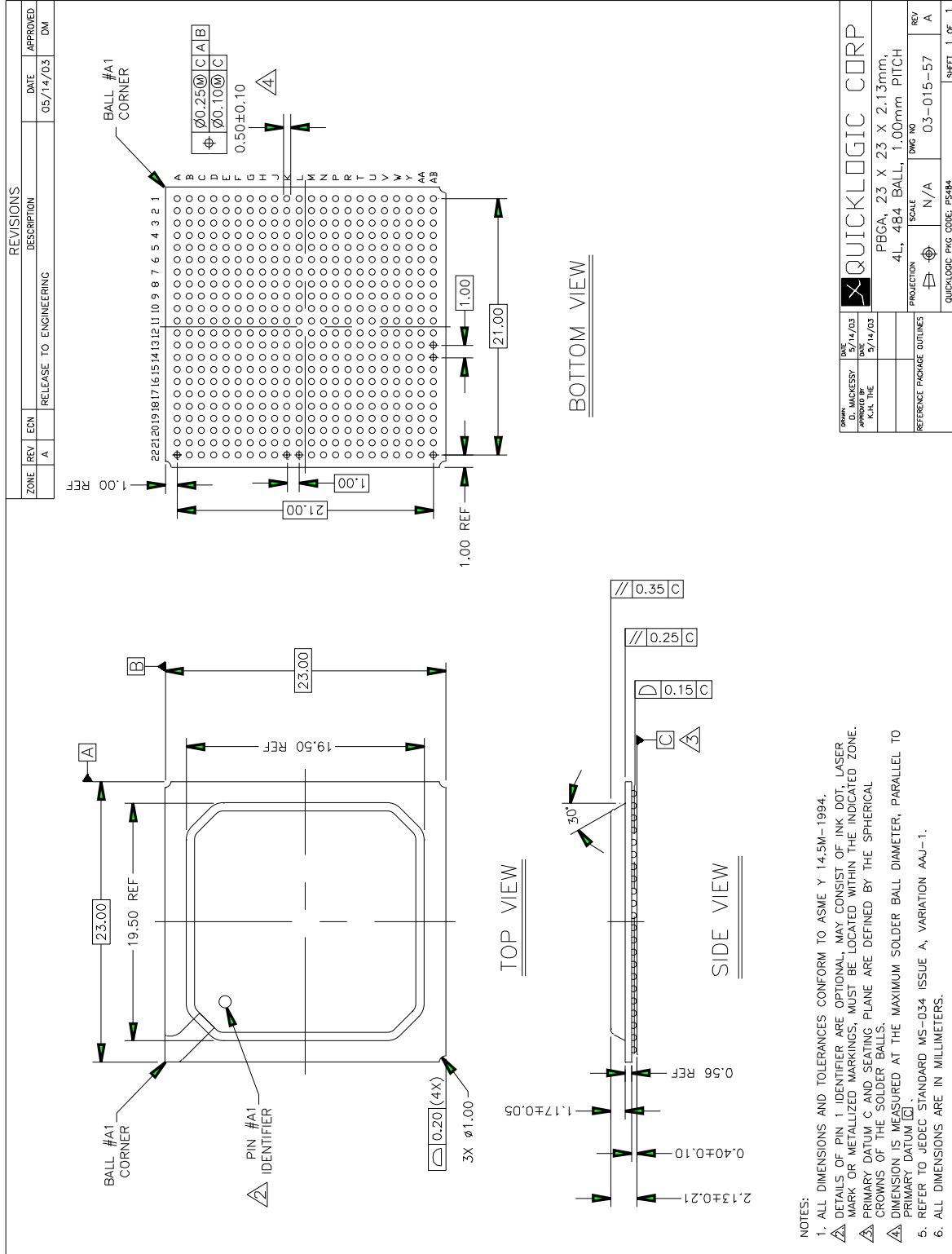
DATE	5/14/03	QUICKLOGIC CORP	DATE	03-015-05	
DRN	D. WICKESSEY		QUICKLOGIC PKG CODE: P0208	REV	A
APPROVED BY	9/14/03		SCALE	N/A	SHEET
PACKAGE	208	DESCRIPTION	MOQFP 208 LEAD, 28 X 28mm BODY, 3.35mm THICK, 2.60mm FOOTPRINT	PROJECTION	
REFERENCE PACKAGE OUTLINES		PROJECTION		SCALE	N/A

280 LFBGA Packaging Drawing



- NOTES:
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y 14.5M-1994.
 - DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, MAY CONSIST OF INK DOT, LASER MARK OR METALLIZED MARKINGS, MUST BE LOCATED WITHIN THE INDICATED ZONE.
 - PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
 - REFER TO JEDEC STANDARD MO-205.
 - ALL DIMENSIONS ARE IN MILLIMETERS.

484 PBGA Packaging Drawing



DATE	5/14/03	QUICKLOGIC CORP
APPROVED BY	K.J.H. THE	
SCALE	N/A	
PROJECTION	1st Angle	
REFERENCE PACKAGE OUTLINES		
DWG NO		
SCALE		
REV	03-015-57	A
SHEET	1	OF 1

Packaging Information

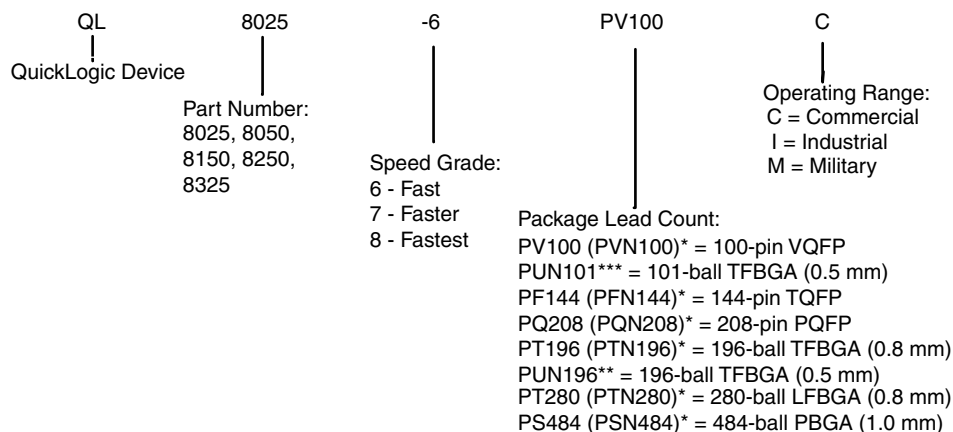
The Eclipse II product family packaging information is presented in **Table 53**.

Table 53: Packaging Options

Device Information	Device											
	QL8325/QL8250			QL8150			QL8050			QL8025		
	Pin	Pb	Pb-Free	Pin	Pb	Pb-Free	Pin	Pb	Pb-Free	Pin	Pb	Pb-Free
Package Definitions ^a	208 PQFP (28 mm x 28 mm) Pitch - 0.50 mm	X	X	144 TQFP (20 mm x 20 mm) Pitch - 0.50 mm	X	X	100 VQFP (14 mm x 14 mm) Pitch - 0.50 mm	X	X	100 VQFP (14 mm x 14 mm) Pitch - 0.50 mm	X	X
	280 LFBGA (17 mm x 17 mm) Pitch - 0.80 mm	X	X	196 TFBGA (12 mm x 12 mm) Pitch - 0.80 mm	X	X	101 TFBGA (6 mm x 6 mm) Pitch - 0.50 mm		X	144 TQFP (20 mm x 20 mm) Pitch - 0.50 mm	X	X
	484 BGA (23 mm x 23 mm) Pitch - 1.0 mm	X	X	196 TFBG (8 mm x 8 mm) Pitch - 0.50 mmA		X	144 TQFP (20 mm x 20 mm) Pitch - 0.50 mm	X	X	196 TFBGA (12 mm x 12 mm) Pitch - 0.80 mm	X	X
				208 PQFP (28 mm x 28 mm) Pitch - 0.50 mm	X	X	196 TFBGA (12 mm x 12 mm) Pitch - 0.80 mm	X	X			
				280 LFBGA (17 mm x 17 mm) Pitch - 0.80 mm	X	X						

- a. BGA = Ball Grid Array
- LFBGA = Low Profile Fine Pitch Ball Grid Array
- PQFP = Plastic Quad Flat Pack
- TFBGA = Thin Fine Pitch Ball Grid Array
- TQFP = Thin Quad Flat Pack
- VQFP = Very Thin Quad Flat Pack

Ordering Information



* Lead-free packaging is available, contact QuickLogic regarding availability (see Contact Information).

** 196 TFBGA (8 mm x 8 mm, 0.5 mm pitch) is offered in lead-free packaging only.

*** 101 TFBGA (6 mm x 6 mm, 0.5 mm pitch) is offered in lead-free packaging only.

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Revision History

Revision	Date	Comments
1.0	September 2012	Initial production release.
1.1	July 2013	Paul Karazuba and Kathleen Bylsma Updated back matter and terminology.

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